# Berry Discrete/UMA Schematics Document AMD Danube CPU S1g4 AMD GPU Madison-LP/M96-LP M2 RS880M + SB820M

2010-03-08

**REV** : **A00** 

DY : Nopop Component

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Cover Page

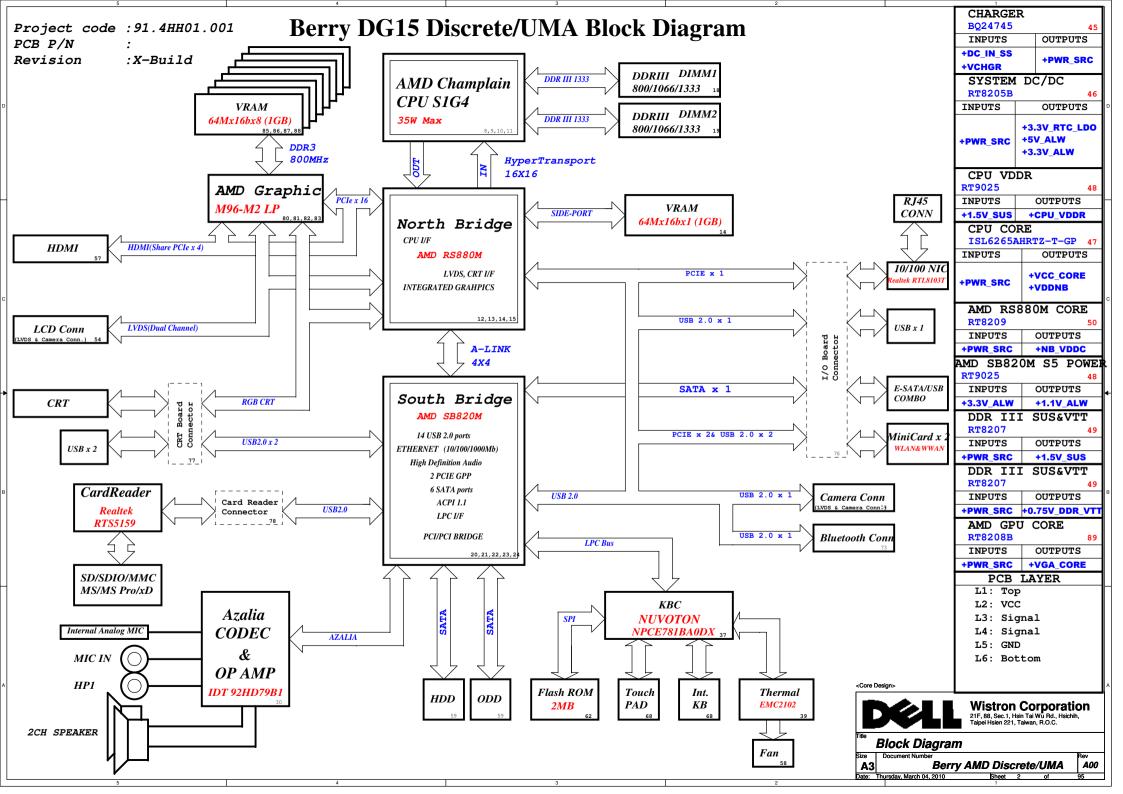
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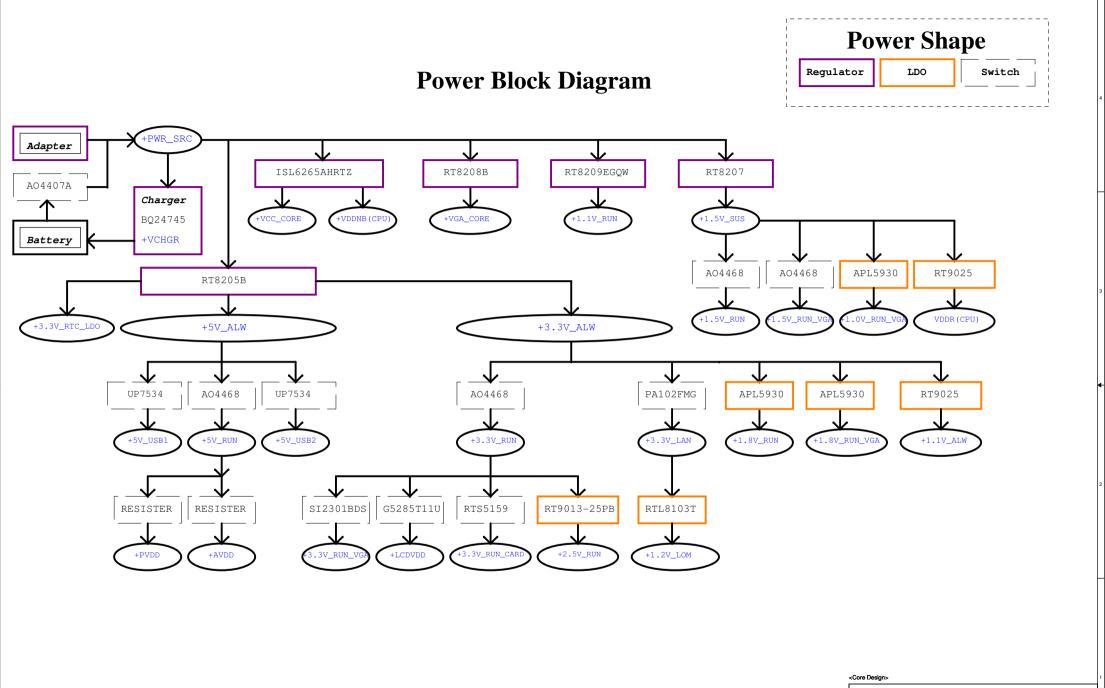
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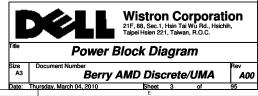
Berry AMD Discrete/UMA

Date: Monday, March 08, 2010

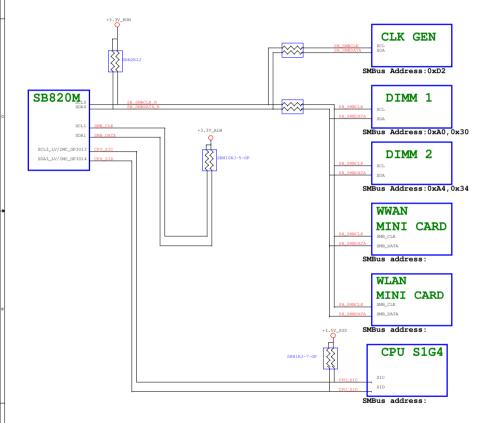
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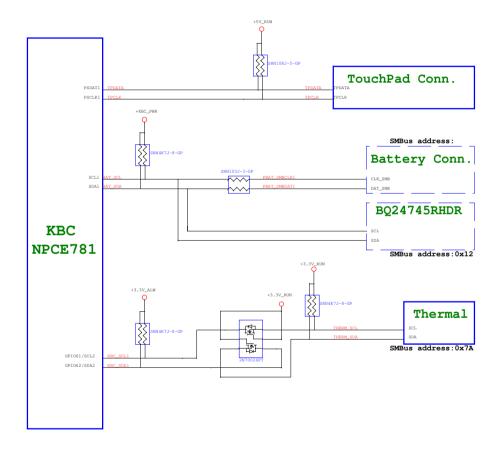


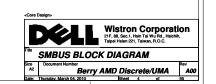


# SB820M SMBus Block Diagram

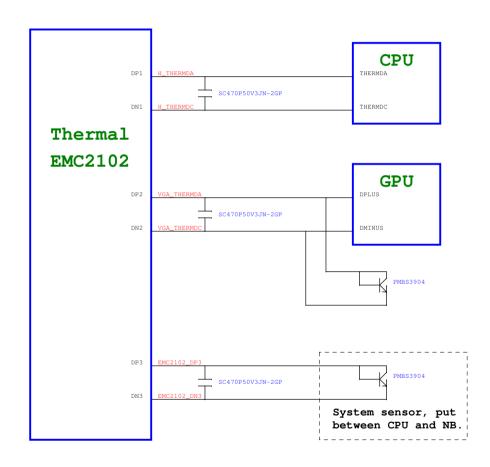


# KBC SMBus Block Diagram

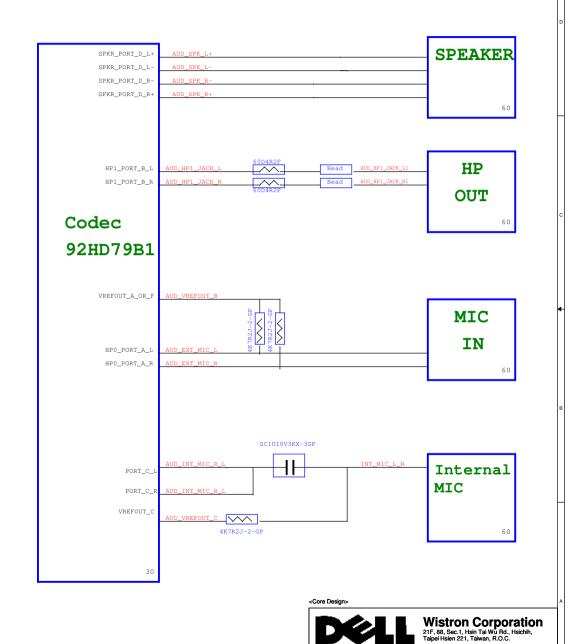




# Thermal Block Diagram



# Audio Block Diagram



THERMAL/AUDIO BLOCK DIAGRAM

| Document Number | Berry AMD Discrete/UMA | Rev

### SB820M Strapping

apture from 45484 Rev. 1.02 AMD SB8xx-Series Southbridge Design Guid

Name	Strap Name	AMD SB8xx-Series Southbridge Design Guide Schematic Note						
LPCCLK0	ECEnableStrap	Embedded Controller (EC)  * 0 V - Disabled 3.3 V - Enabled						
		ROMTYPE_1						
EC_PWM3 EC_PWM2	{ROMTYPE_1, ROMTYPE_0 }	3.3V 3.3V Reserved  OV OV Firmware Hub						
		0V 3.3V LPC ROM  * (supports both LPC and PMC ROM types)						
LPCCLK1	CLKGEN	Defines clock generator  * OV - External clock mode: Use 100-MHz PCIeR clock as reference clock and generate i nternal clocks only.  3.3V- Integrated clock mode: Use 25-MHz crystal clock and generate both internal and external clocks						
PCICLK1	BIF_GEN2_ COMPLIANCE_Strap	Set PCIe to Gen II mode  OV_ Force PCIe interface at Gen I mode  * 3.3V_ PCIe interface is at Gen II mode Not Applicable to SB20M but provision for pull-down is required.						
PCICLK2	BootFailTmrEn	<pre>Watchdog function  *</pre>						
PCICLK3	DefaultStrapMode	Default Debug Straps  * OV- Disable Debug Straps. 3.3V- Select external Debug Straps						
PCICLK4	CPUClkSel	CPU/NB HT Clock Selection  OV- Reserved.  * 3.3V- Required setting for integrated clock mode. This strap is not used if the strap CLKGEN is configured for external clock generator mode.						
AZ_SDOUT	CoreSpeedMode	Slow down core clock for low power platform.  * OV- Performance mode 3.3V- Low Power mode						

### RS880M Strapping

Capture from 46113\_rs880m\_ds\_nda\_1.03

Name	Strap Function	Schematic Note				
DAC_VSYNC	STRAP_DEBUG_BUS_GPIO _ENABLE#	Enables debug bus access through memory I/O pads and GPIOs. 0: Enable 1: Disable				
DAC_HSYNC	SIDE_PORT_EN#	<pre>Indicates if memory side-port is available or not 0: Available(UMA) 1: Not available(Discrete)</pre>				
SUS_STAT#	LOAD_EEPROM_STRAPS#	Selects loading of strap values from EEPROM.  0: 12C master can load strap values from EEPROM if connected, or use default values if EEPROM is not connected. Please refer to RS880M's reference schematics for system level implementation details.  * 1: Use default values				

### USB Table

USB								
Pair	Device							
0	USB0 (I/O Board/ESATA)							
1	USB1 (I/O Board)							
2	USB2 (CRT Board)							
3	USB3 (CRT Board)							
4	WLAN USB							
5	WWAN USB							
6	RESERVED							
7	RESERVED							
8	RESERVED							
9	BLUETOOTH							
10	CARD READER							
11	CAMERA (LVDS CONN)							
12	RESERVED							
13	RESERVED							

### PCIE Routing

RS880M						
LANE0	MiniCard WLAN					
LANE1	LAN					
LANE2	MiniCard WWAN					

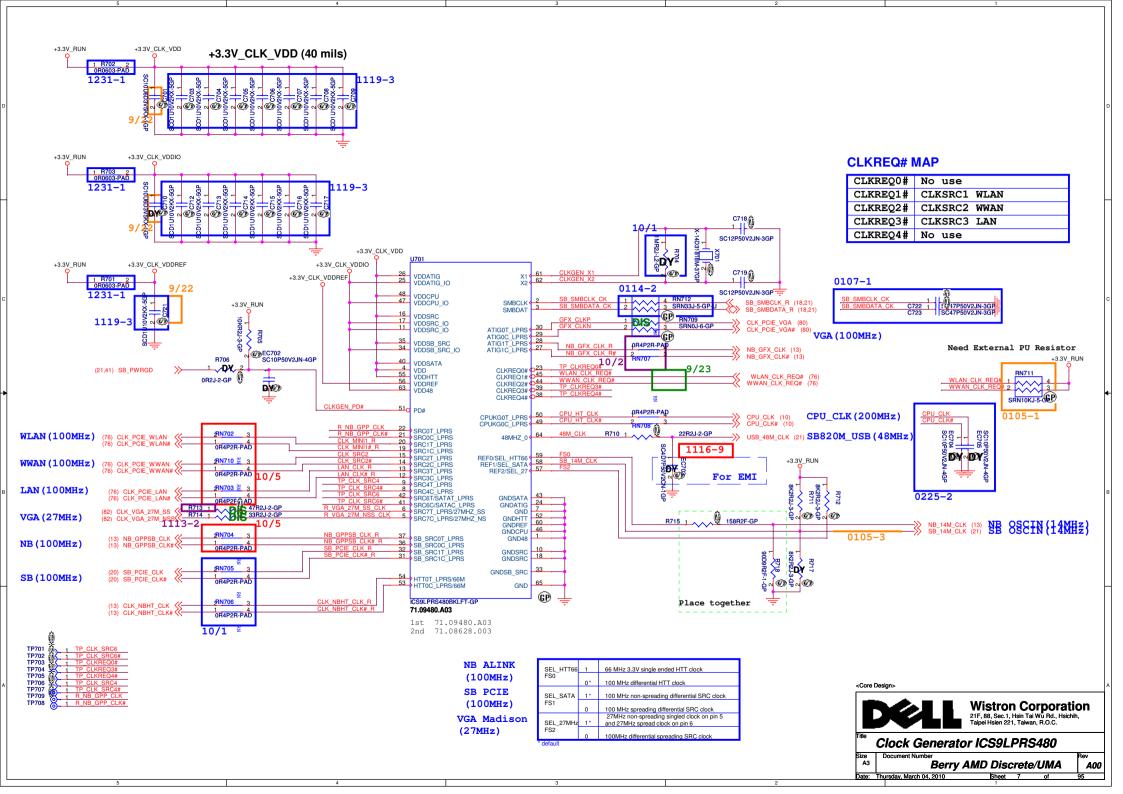
Core Design

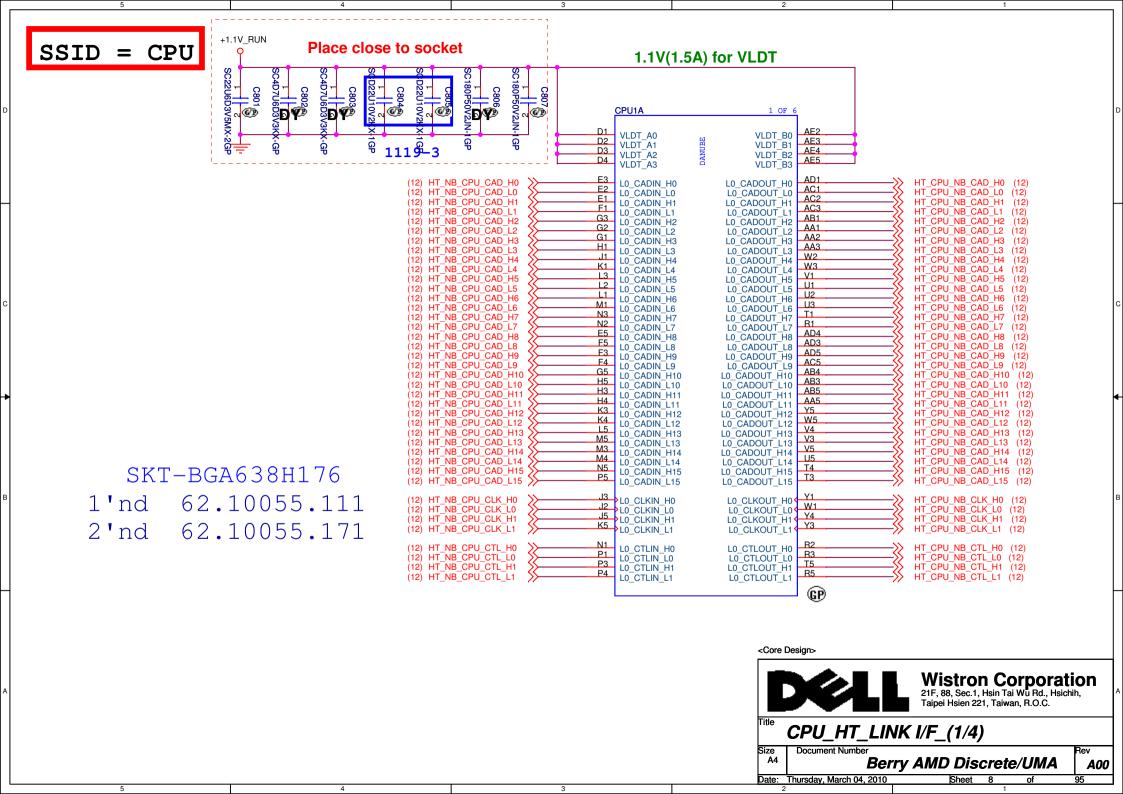
Wistron Corporation
21F, 88, Sec. 1, Hein Tai Will Rd., Habrish,
Taple Haden 221, Talway, R.O.C.

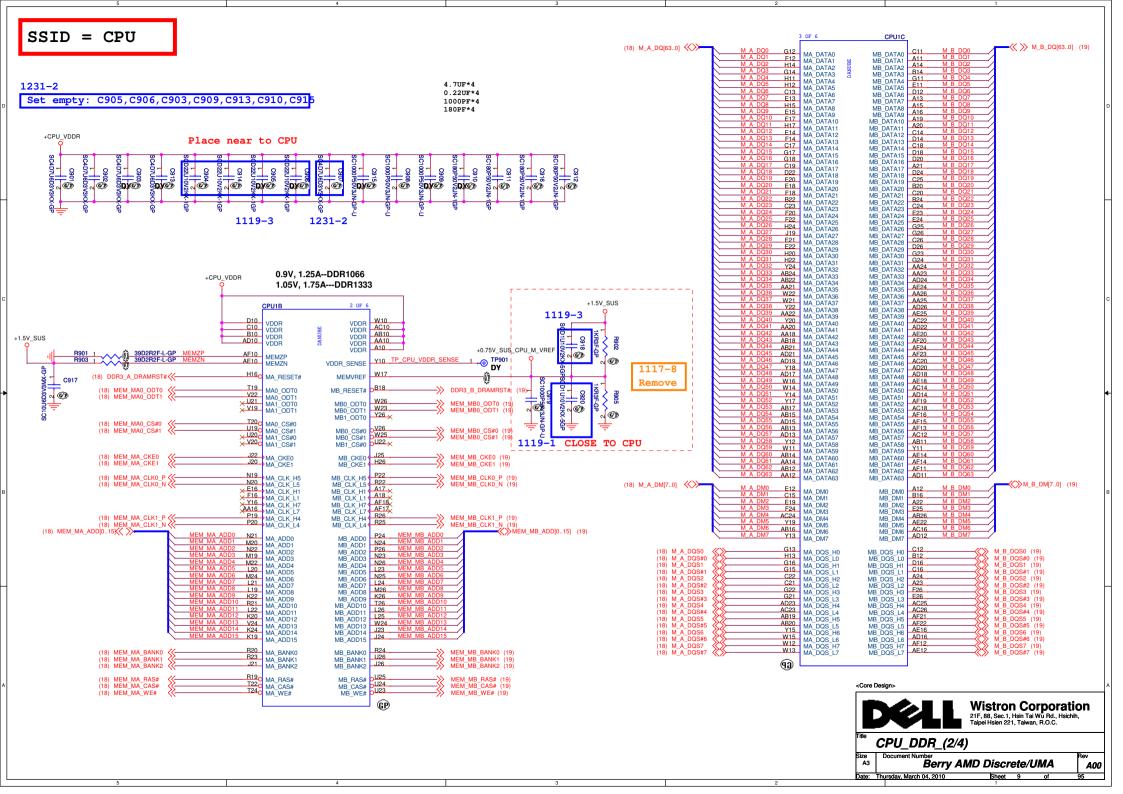
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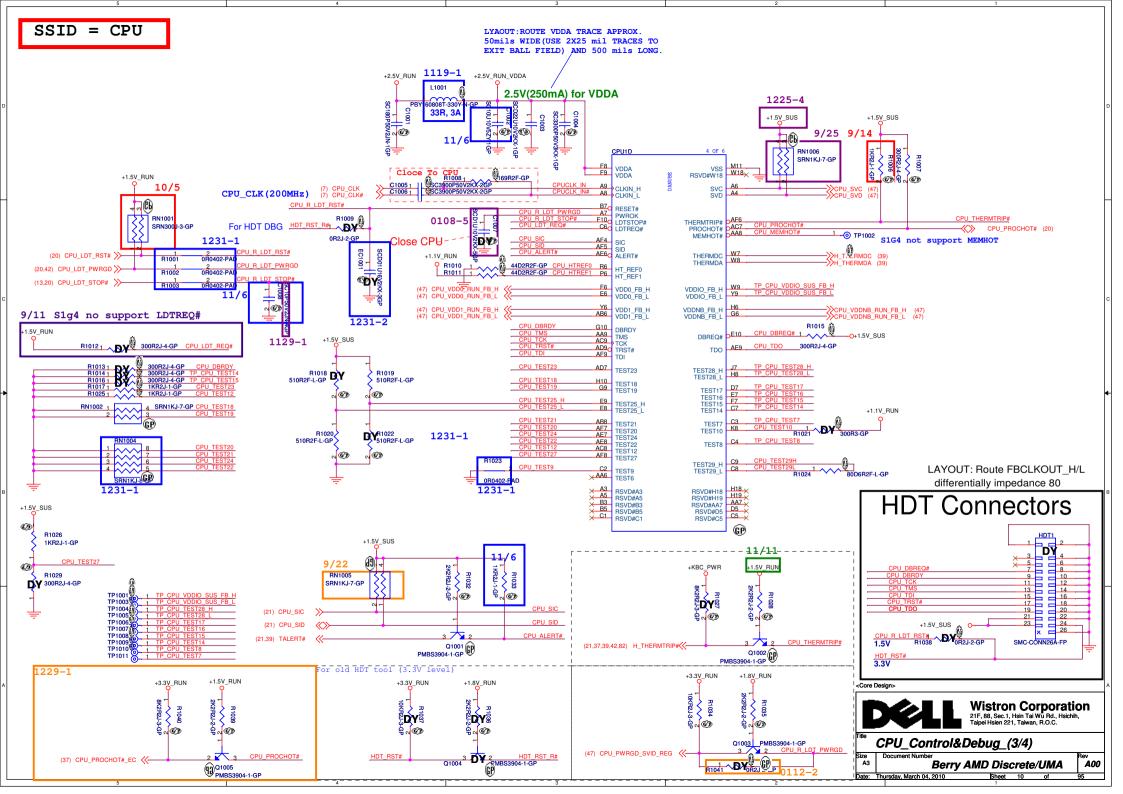
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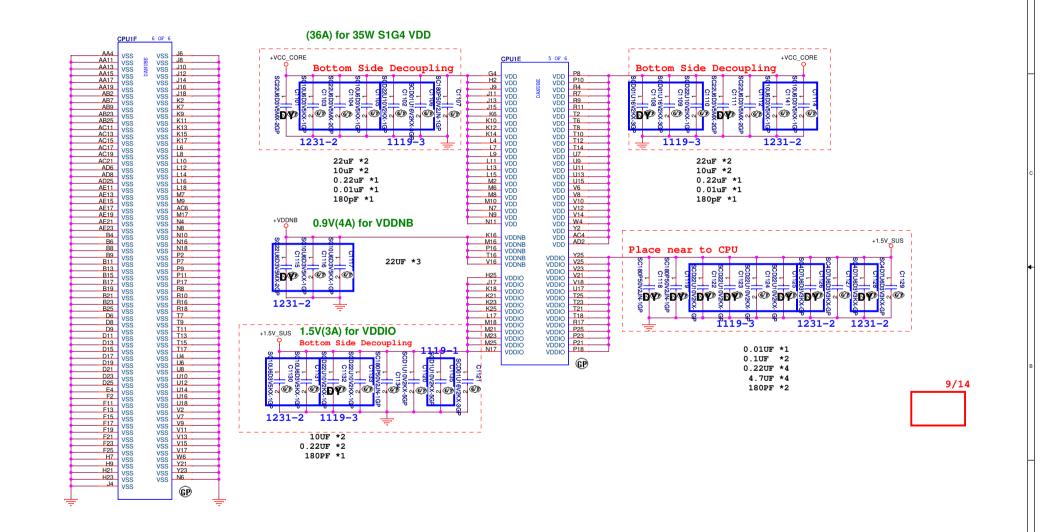


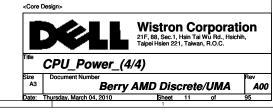


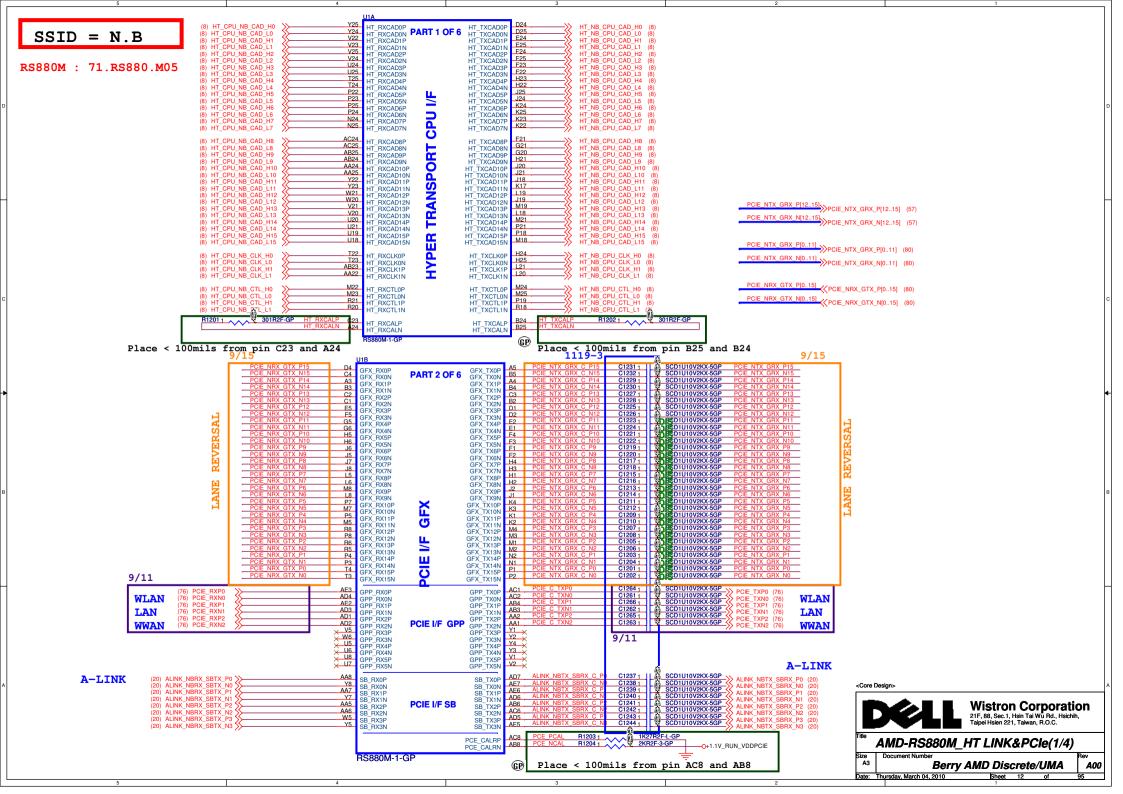


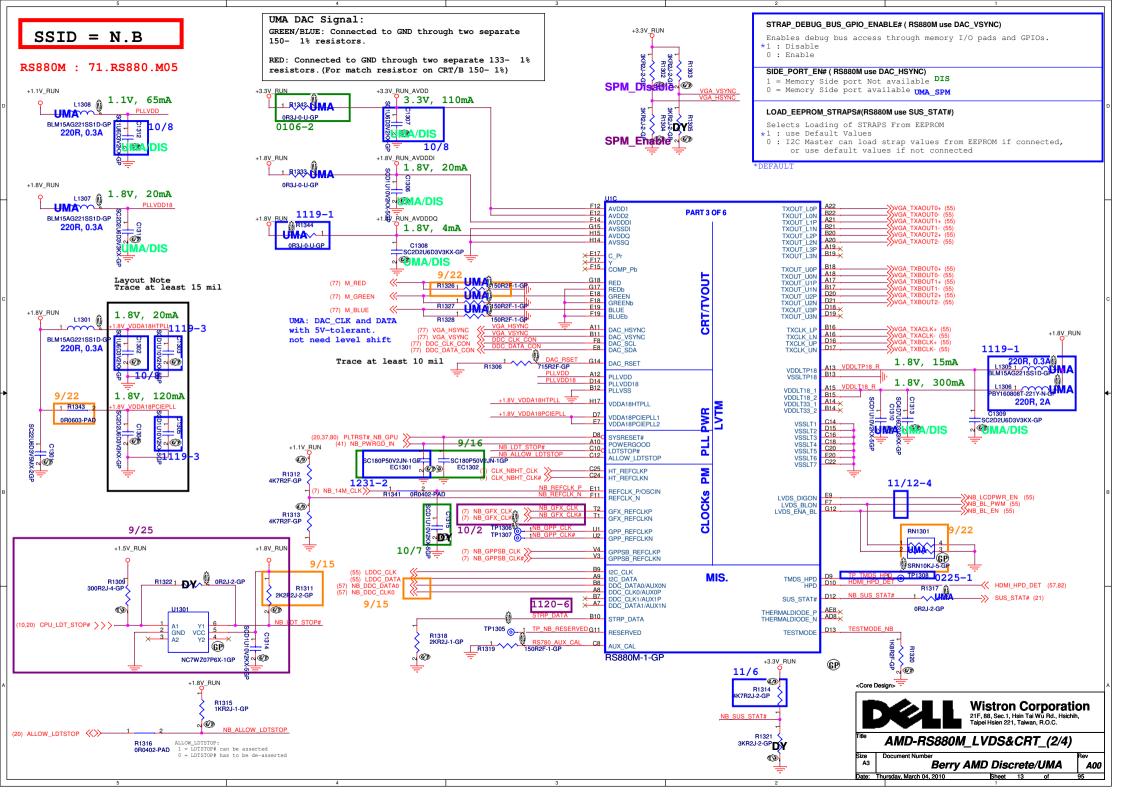


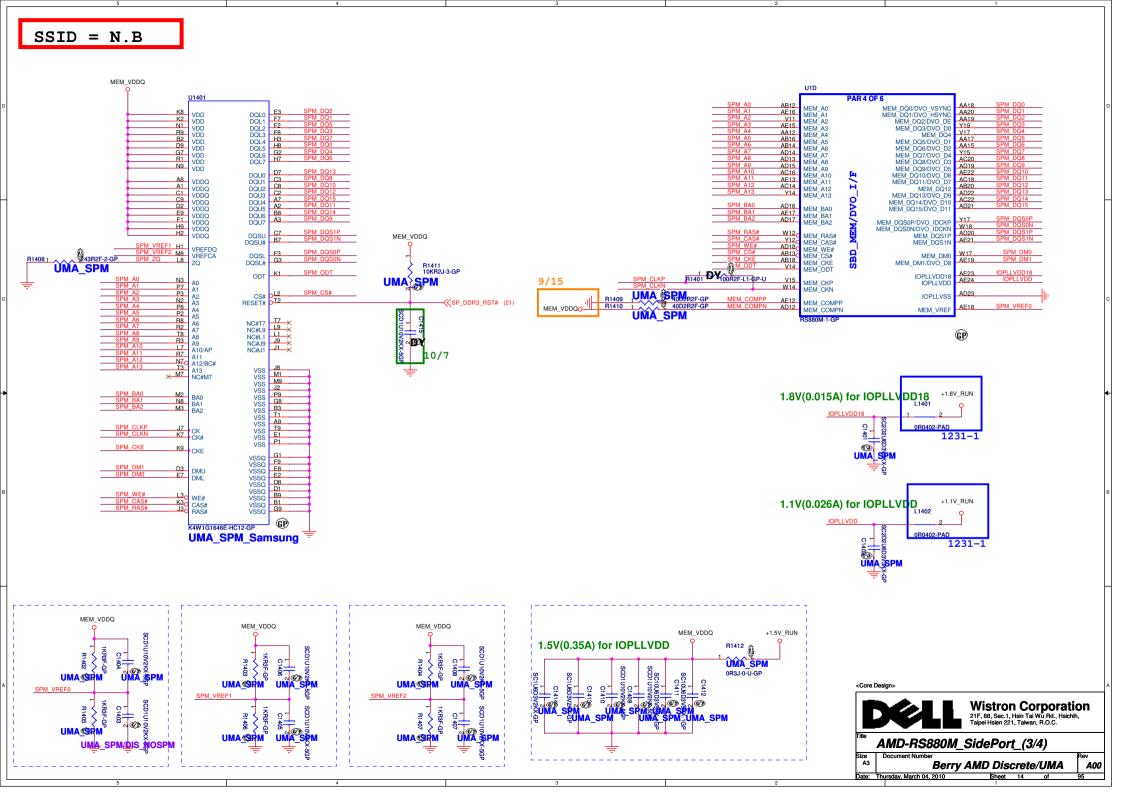
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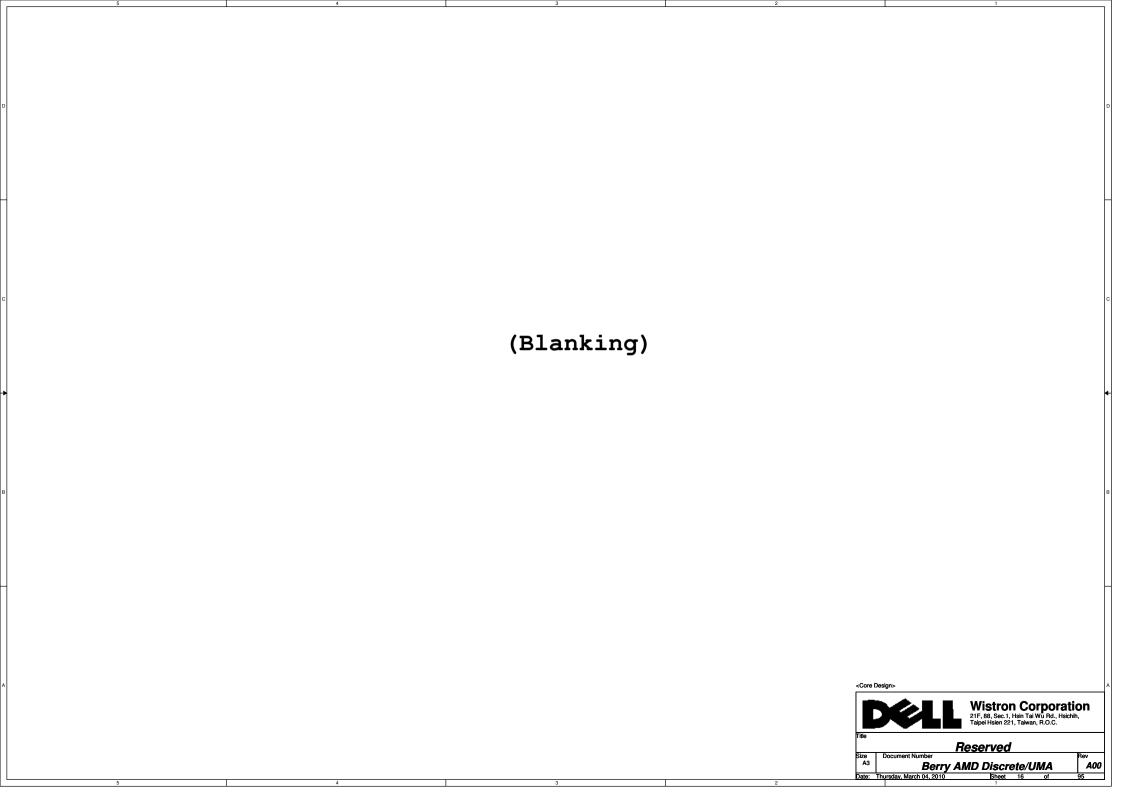


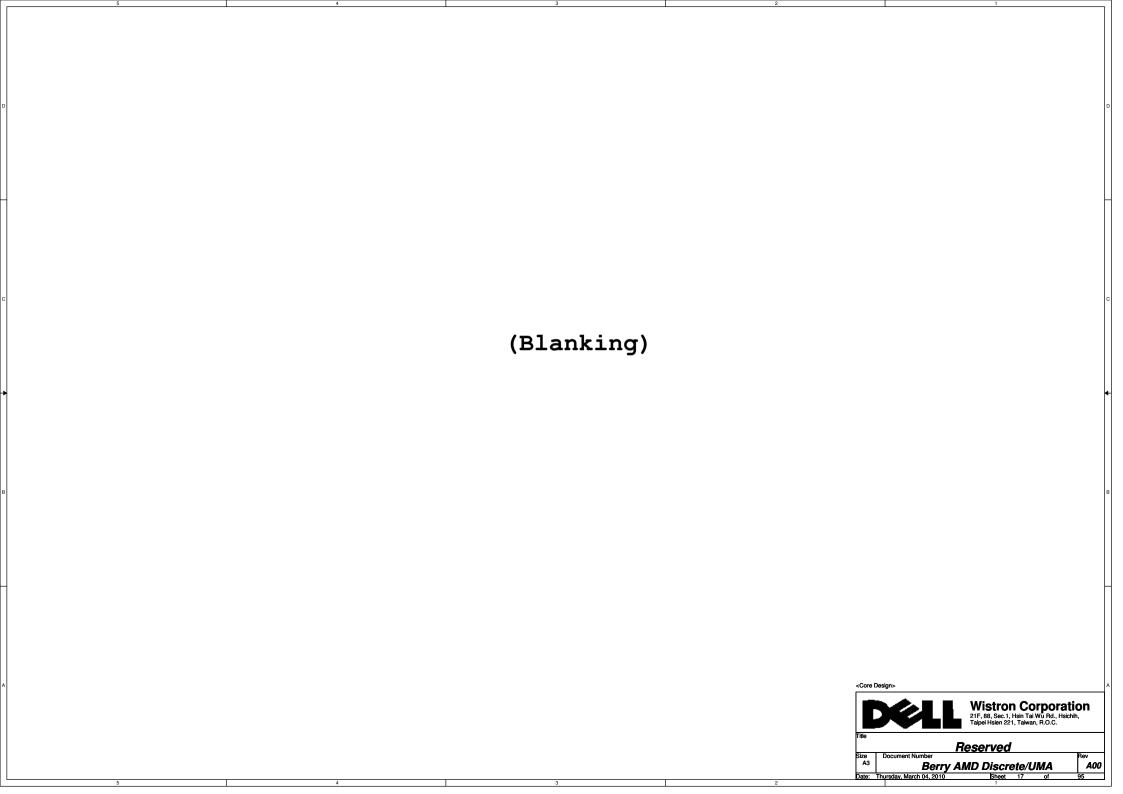


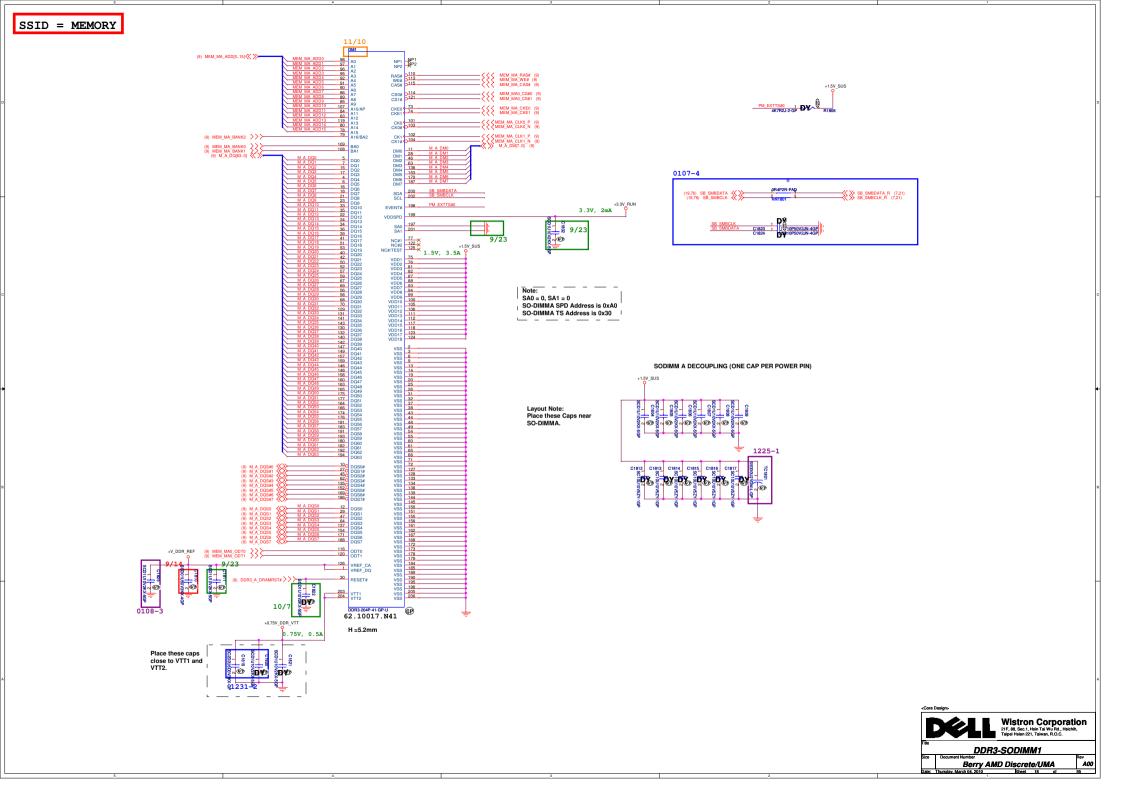


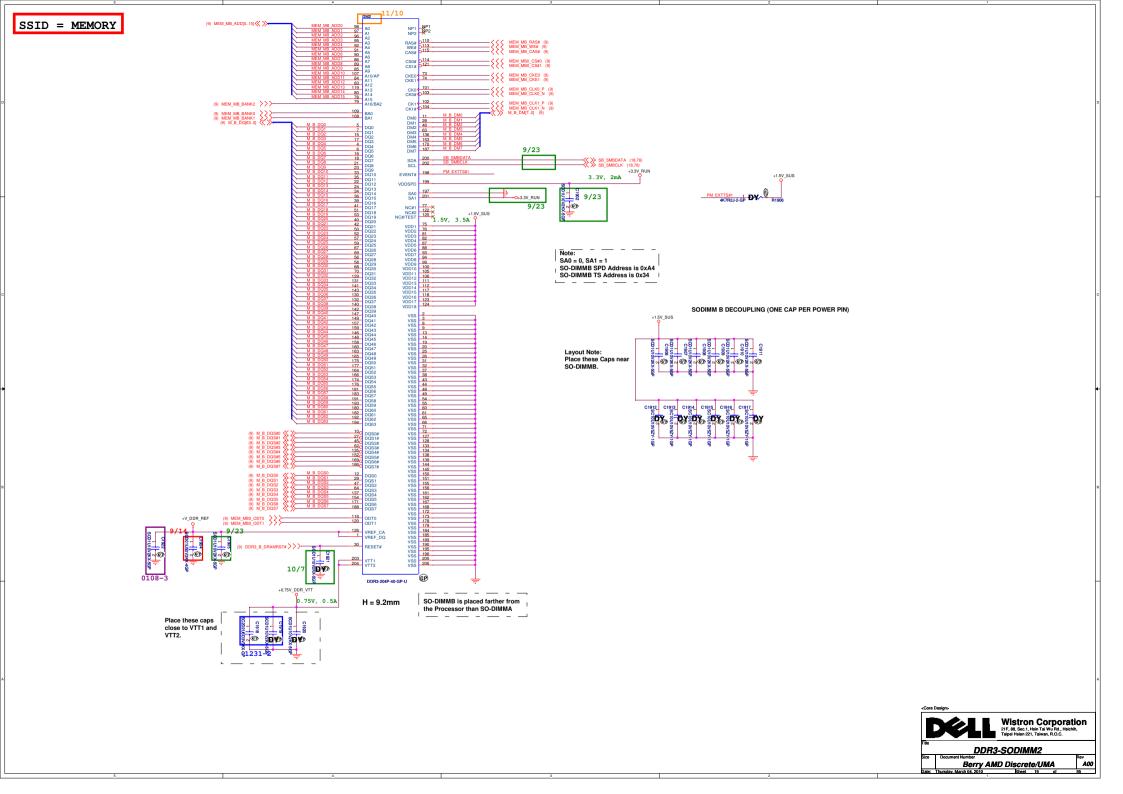


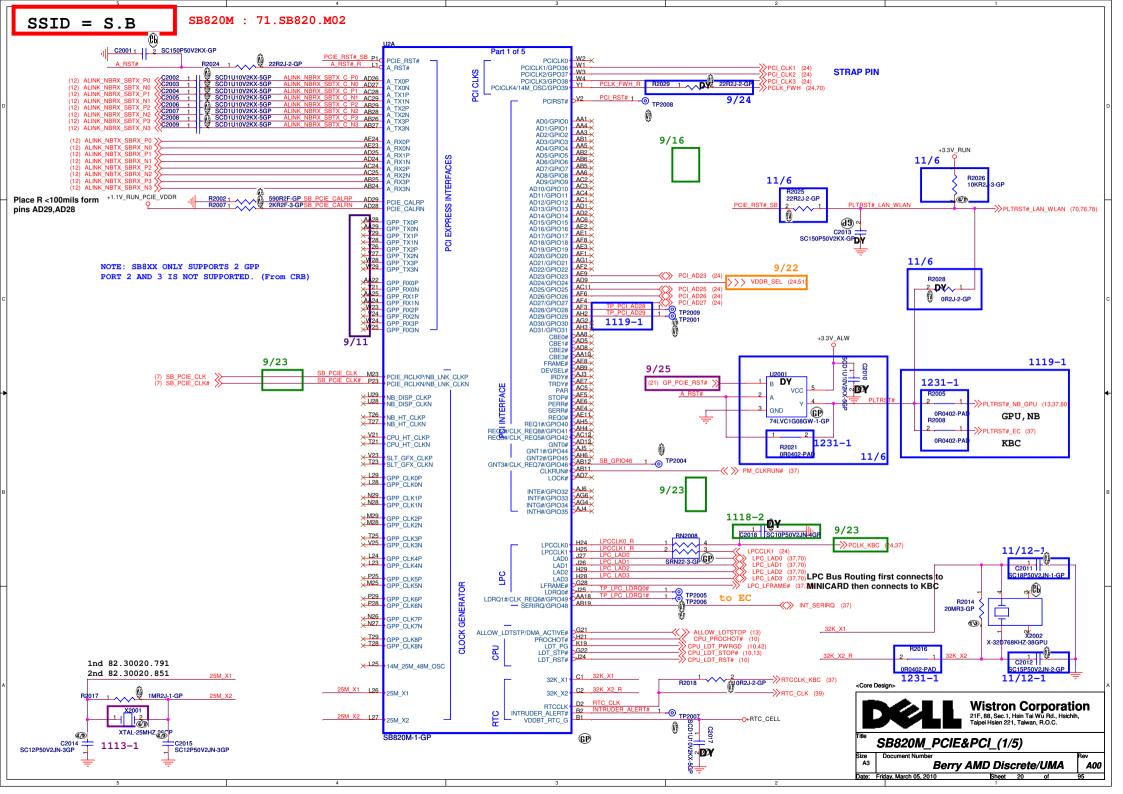


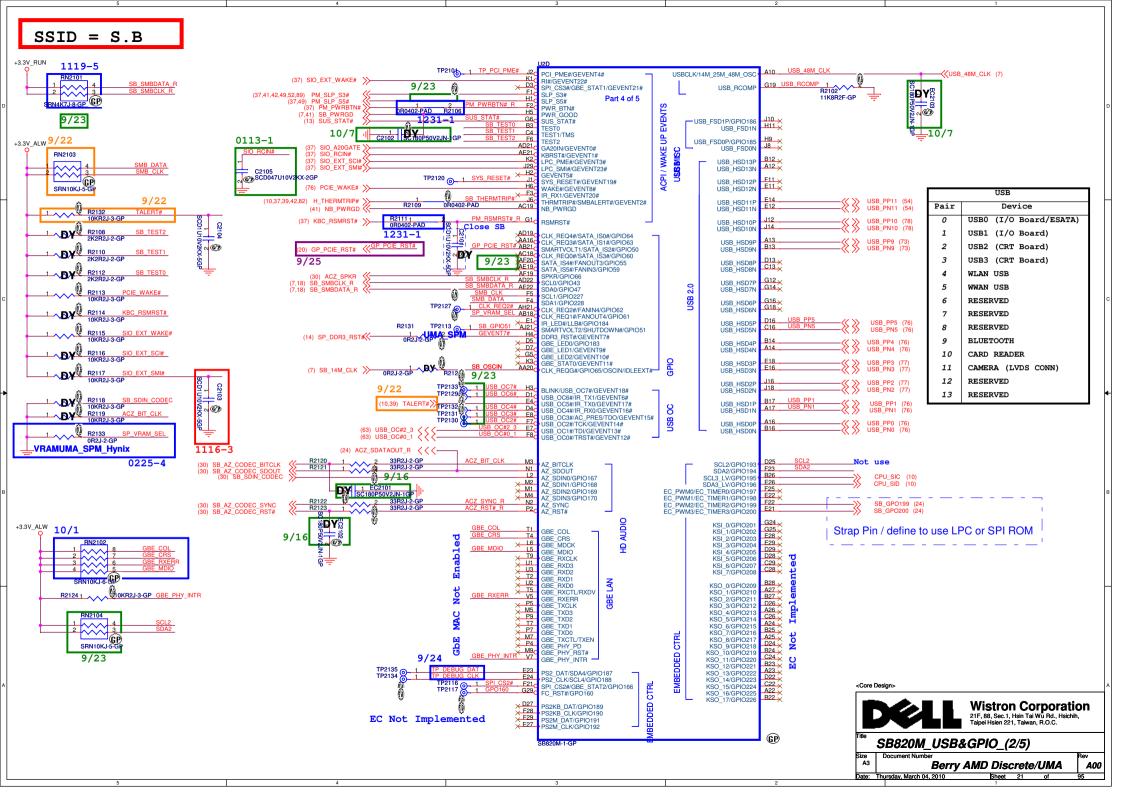


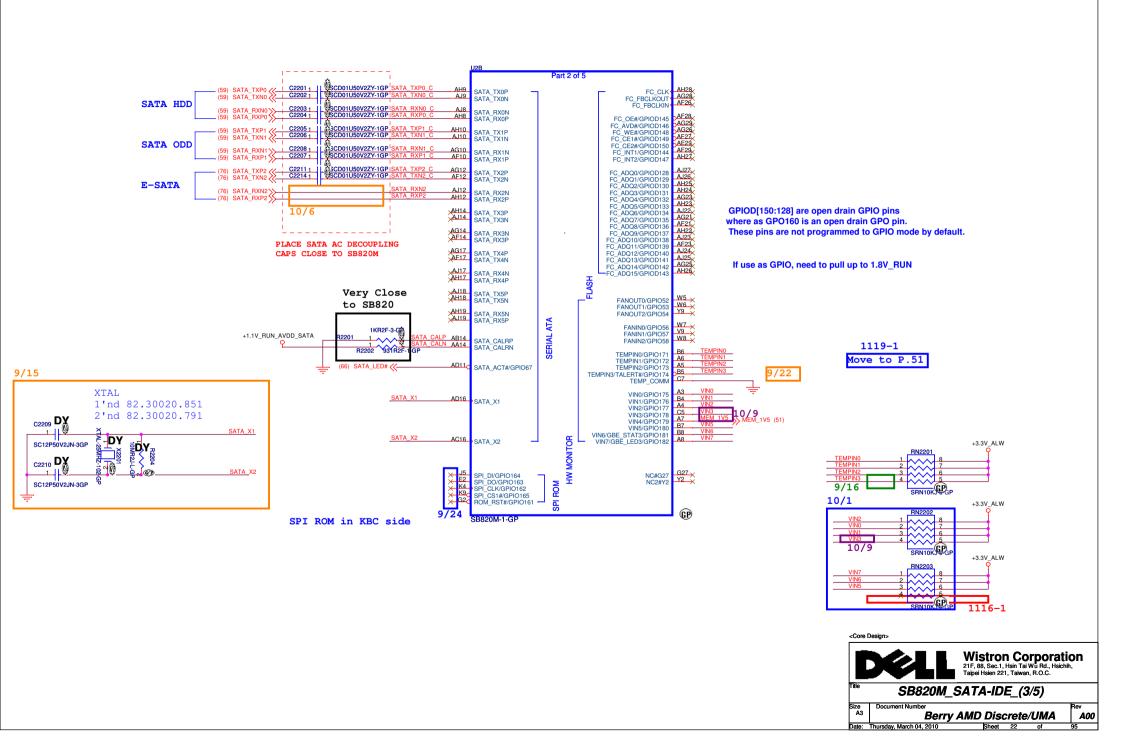


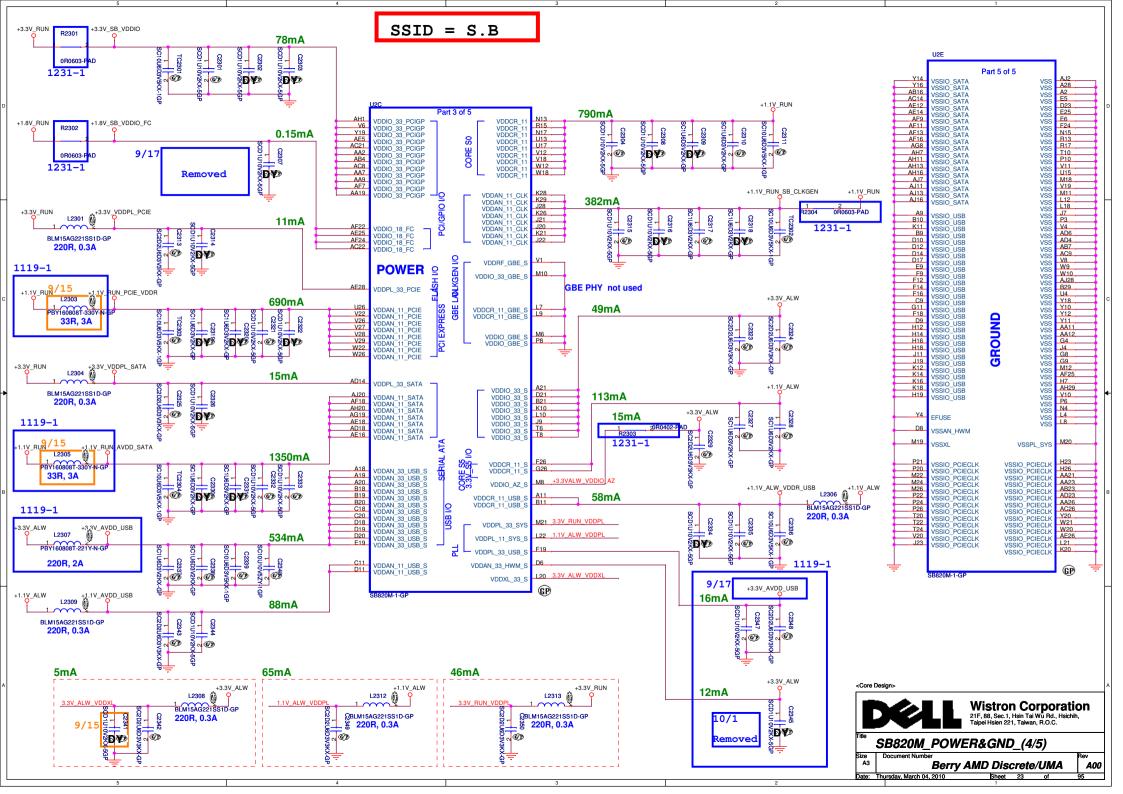






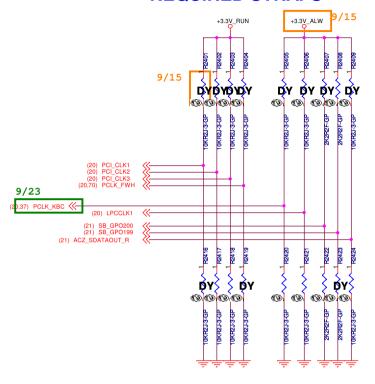






SSID = S.B

### **REQUIRED STRAPS**

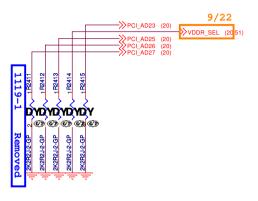


### **REQUIRED SYSTEM STRAPS**

### USE this pin to determine INT/EXT CLK

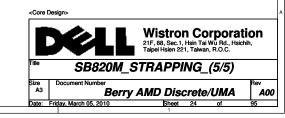
	AZ_SDOUT#	PCI_CLK1	PCI_CLK2	PCLK_KBC (PCI_CLK3)	PCLK_FWH (PCI_CLK4)	LPCCLK0	LPCCLK1	SB_GPO200 , SB_GPO199 ROM TYPE:
PULL HIGH	LOW POWER MODE	Allow PCIE GEN2 DEFAULT	WatchDOG (NB_PWRGD) ENABLED	USE DEBUG STRAPS	non_Fusion CLOCK mode DEFAULT	ENABLE EC	CLKGEN ENABLED (Use Internal)	H, H = Reserved H, L = SPI ROM
PULL LOW	PERFORMANCE MODE DEFAULT	Force PCIE GEN1	WatchDog (NB_PWRGD) DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT	Fusion CLOCK mode	DISABLE EC	DEFAULT CLKGEN DISABLED (Use External)	L, H = LPC ROM DEFAULT L, L = FWH ROM

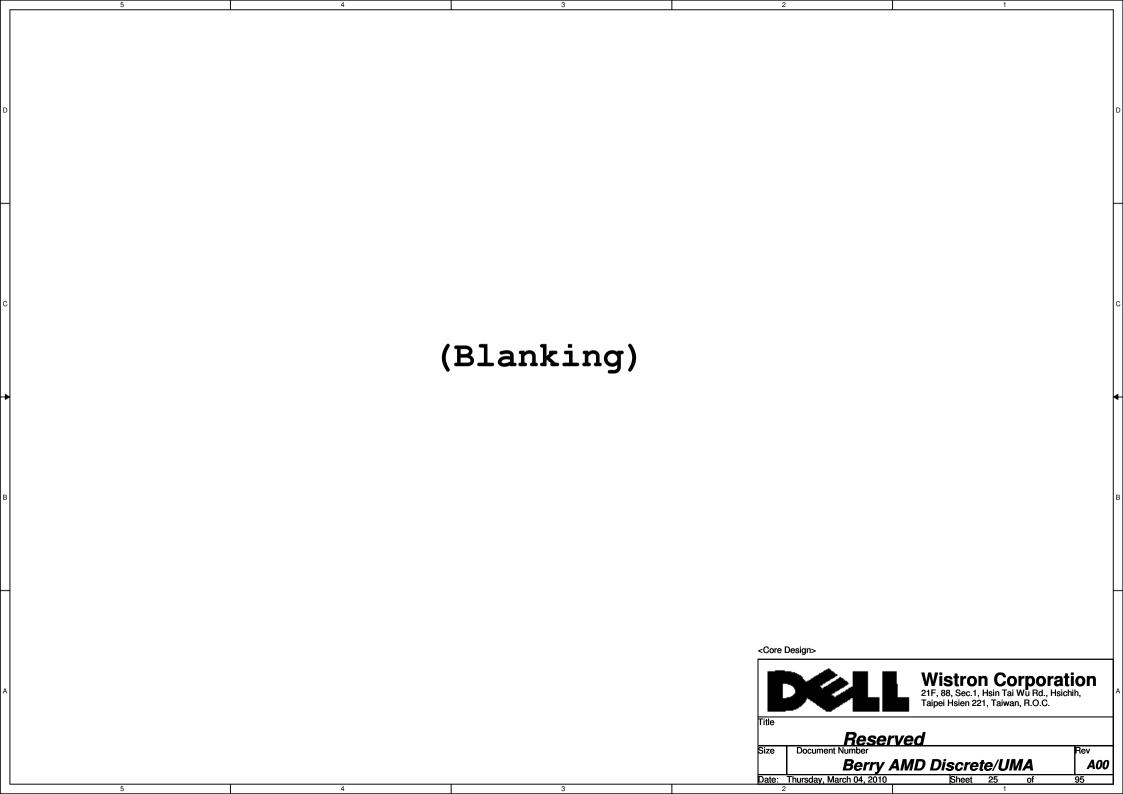
### **DEBUG STRAPS**

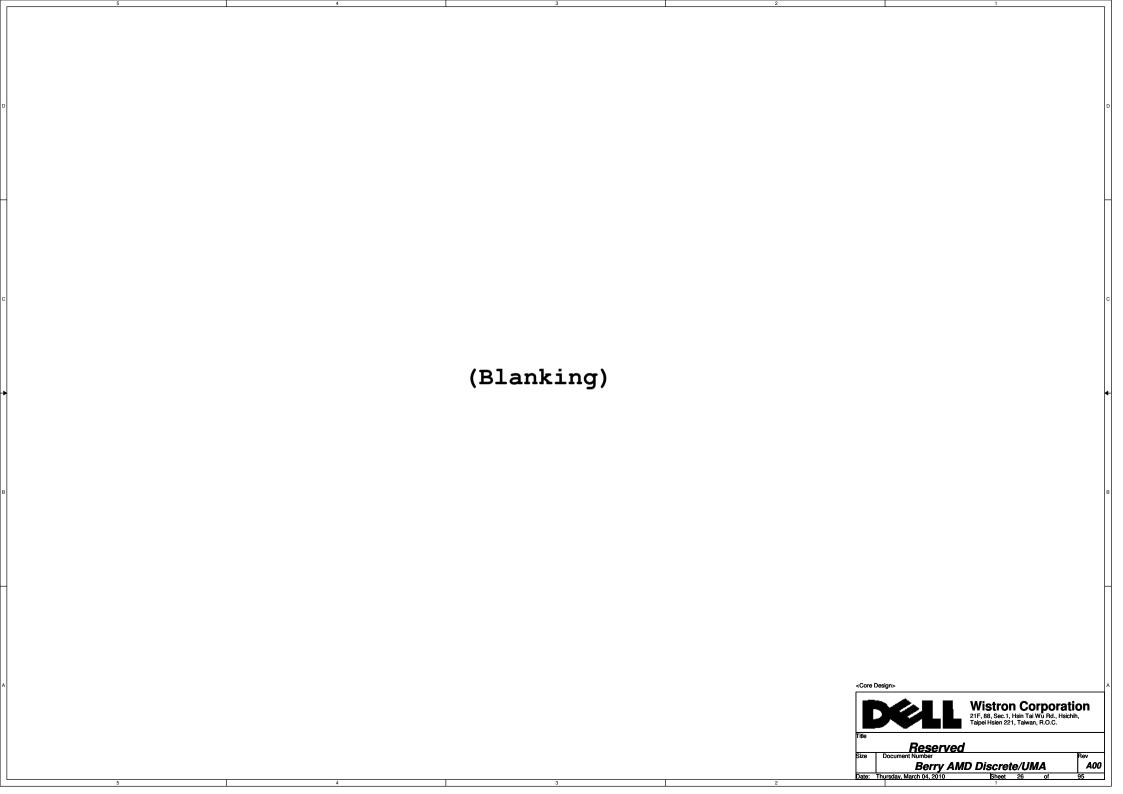


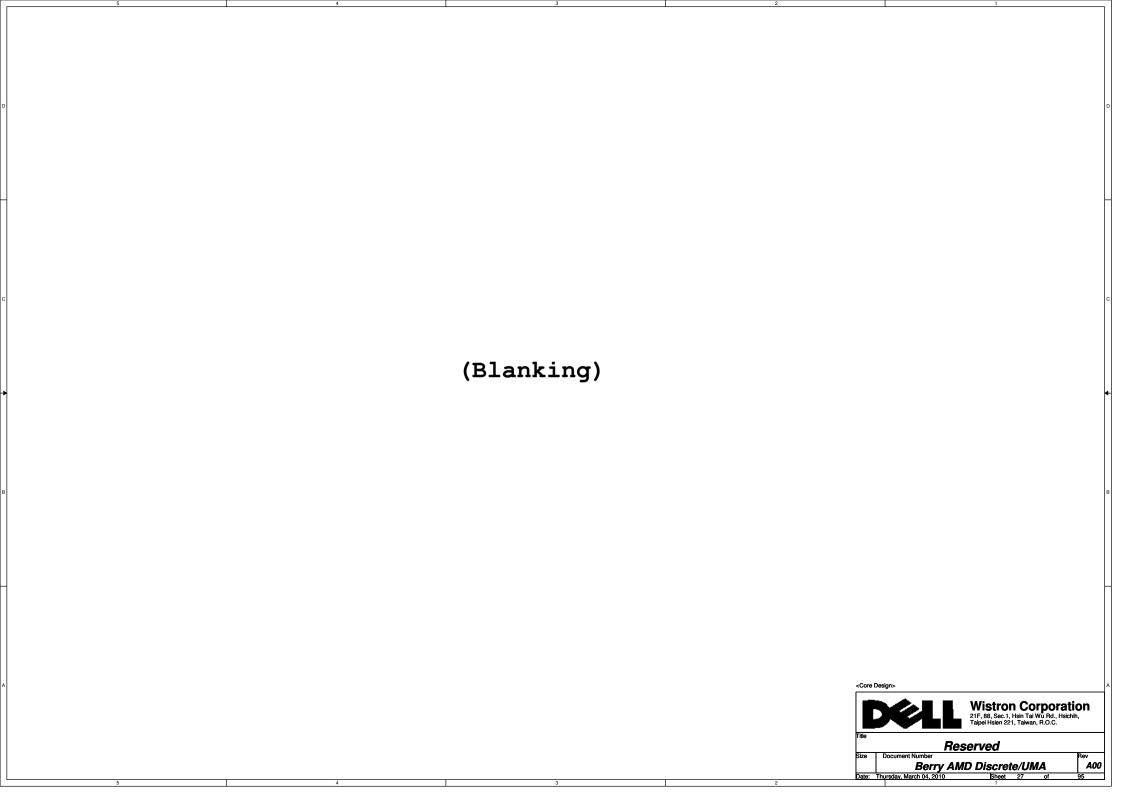
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
JLL GH	USE PCI PLL	Disable ILA AUTORUN	USE FC PLL	USE DEFAULT PCIE STRAPS	Disable PCI MEM BOOT
	(DEFAULT)	(DEFAULT)	(DEFAULT)	(DEFAULT)	(DEFAULT)
ULL	BYPASS PCI PLL	Enable ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	Enable PCI MEM BOOT

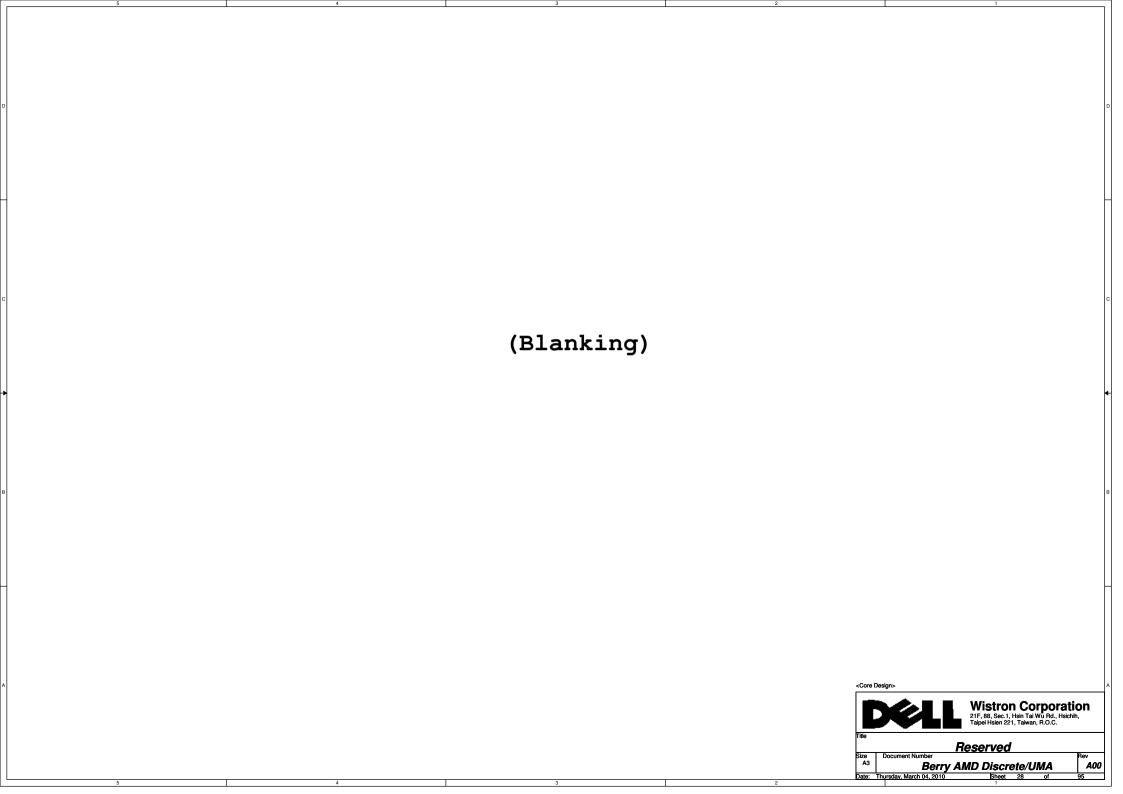
Note: SB820M has 15K internal PU FOR PCI AD[27:23]

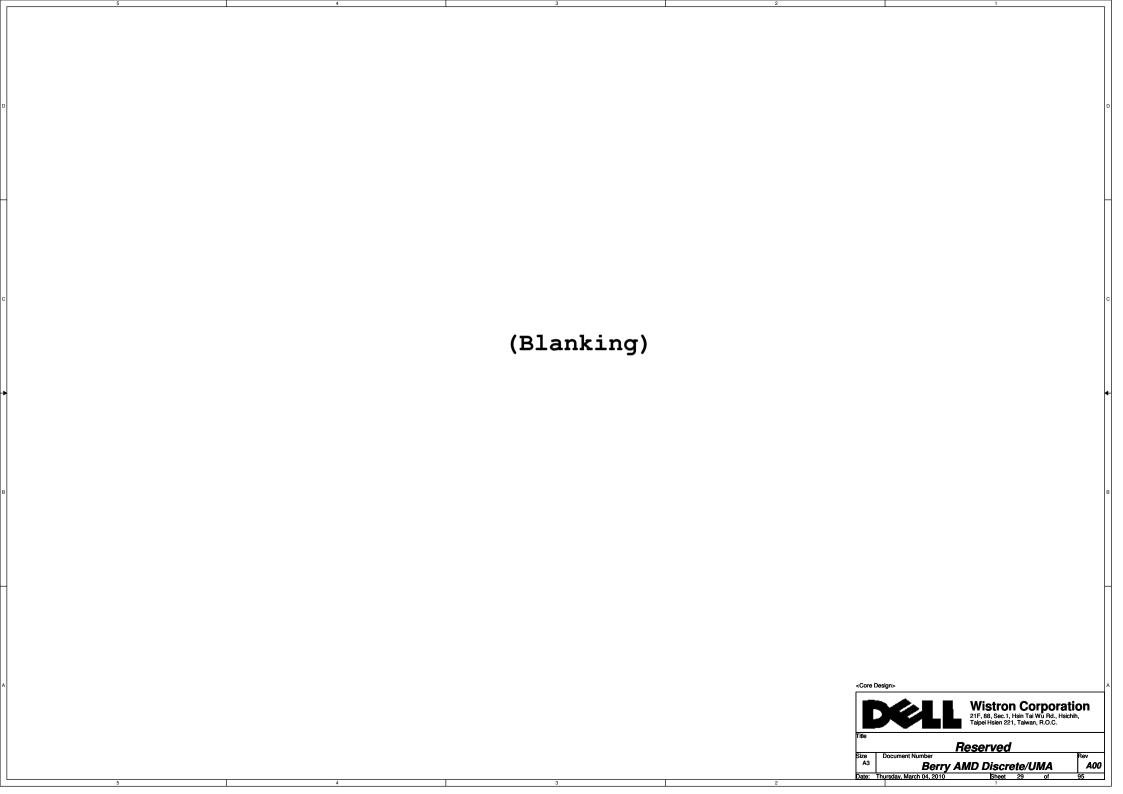


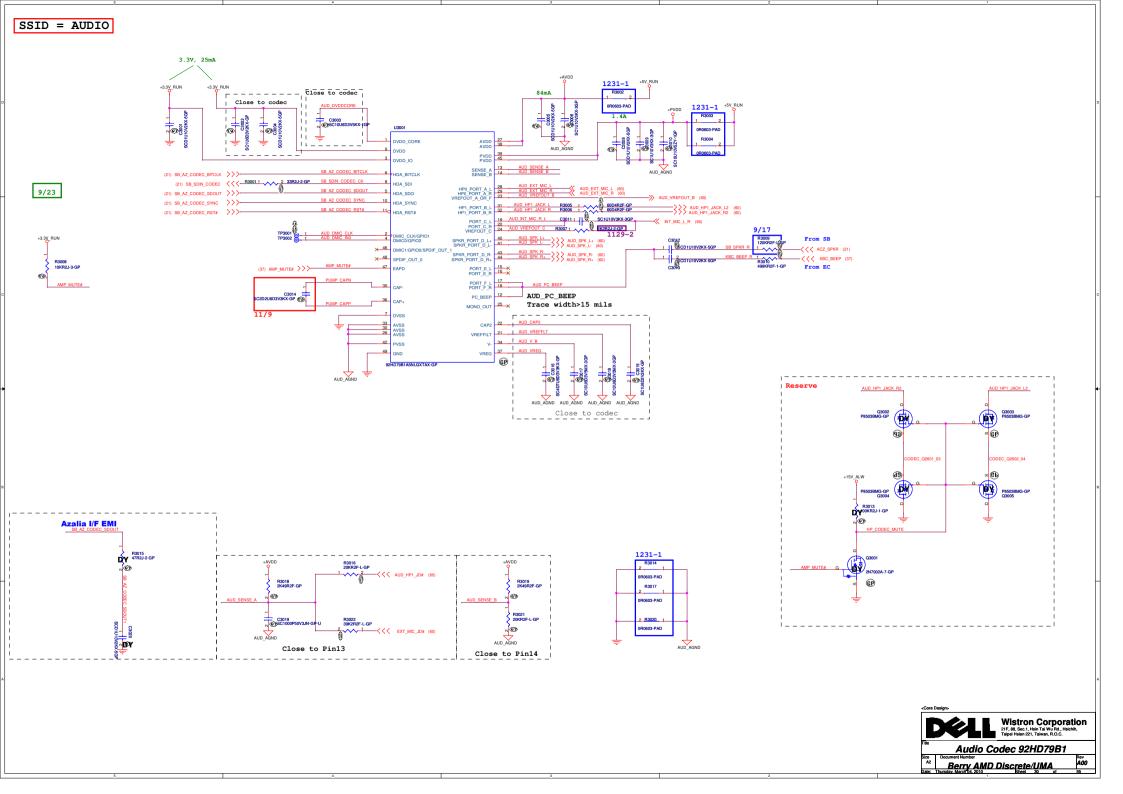


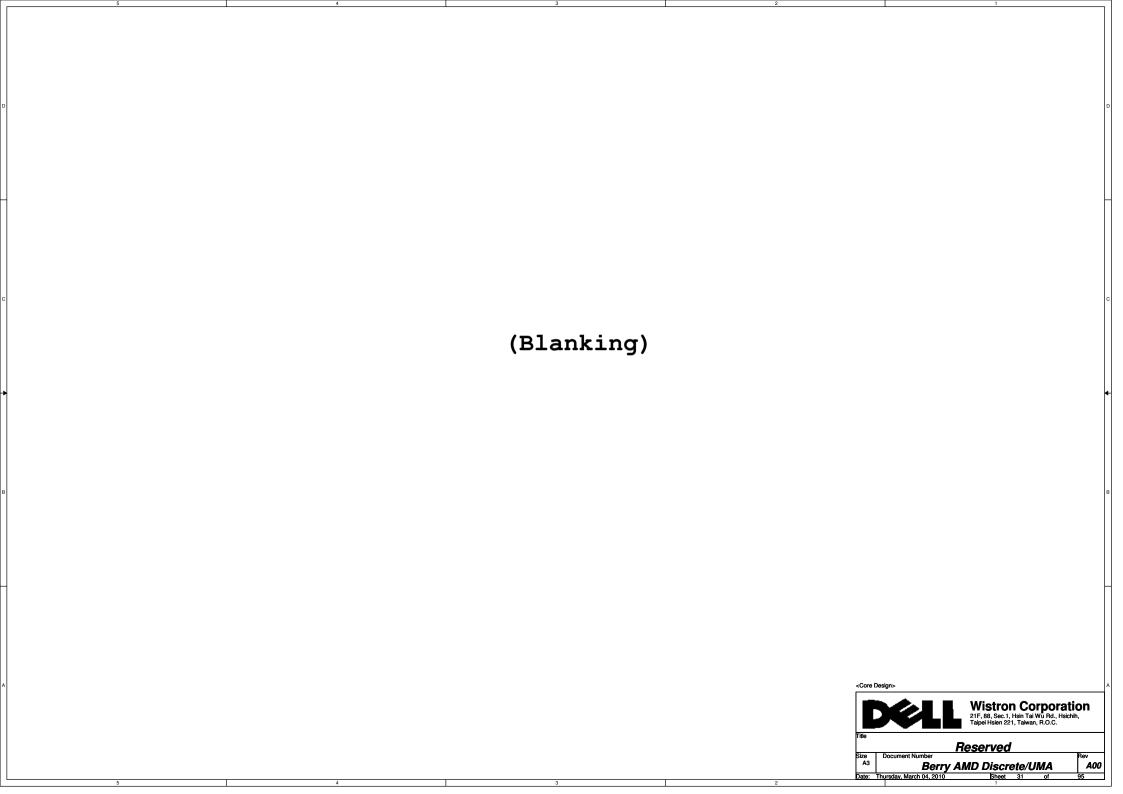


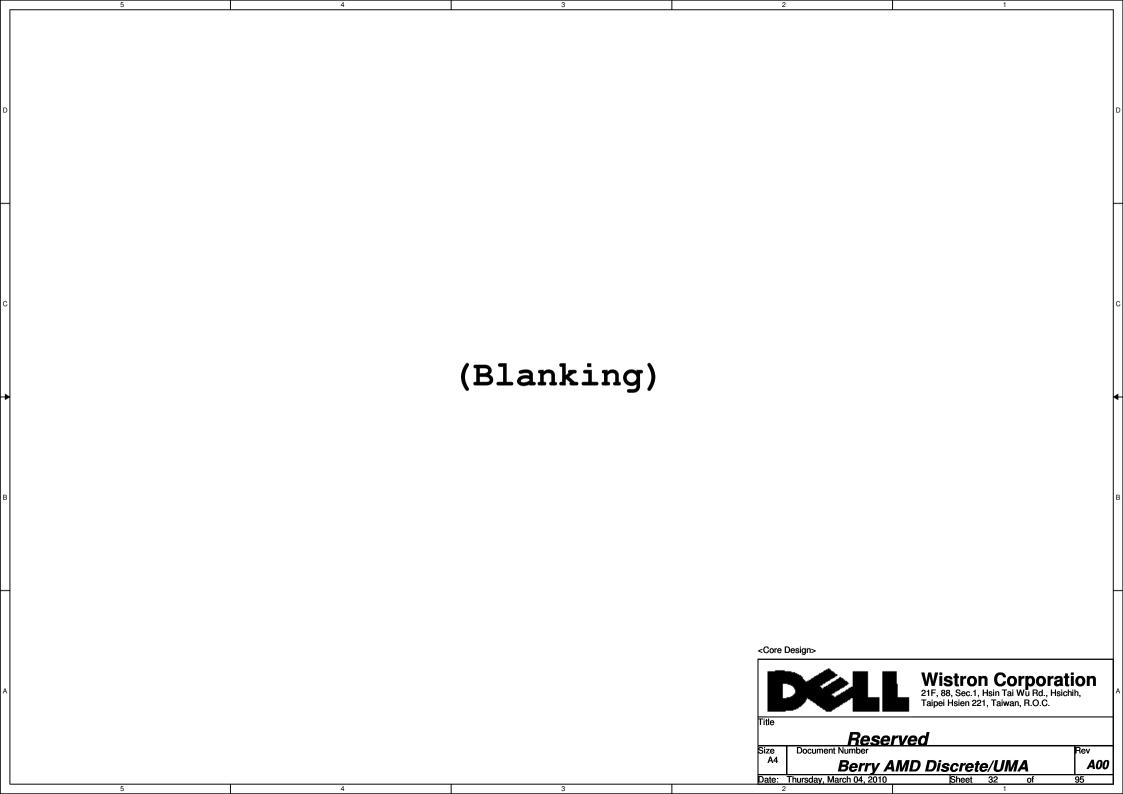


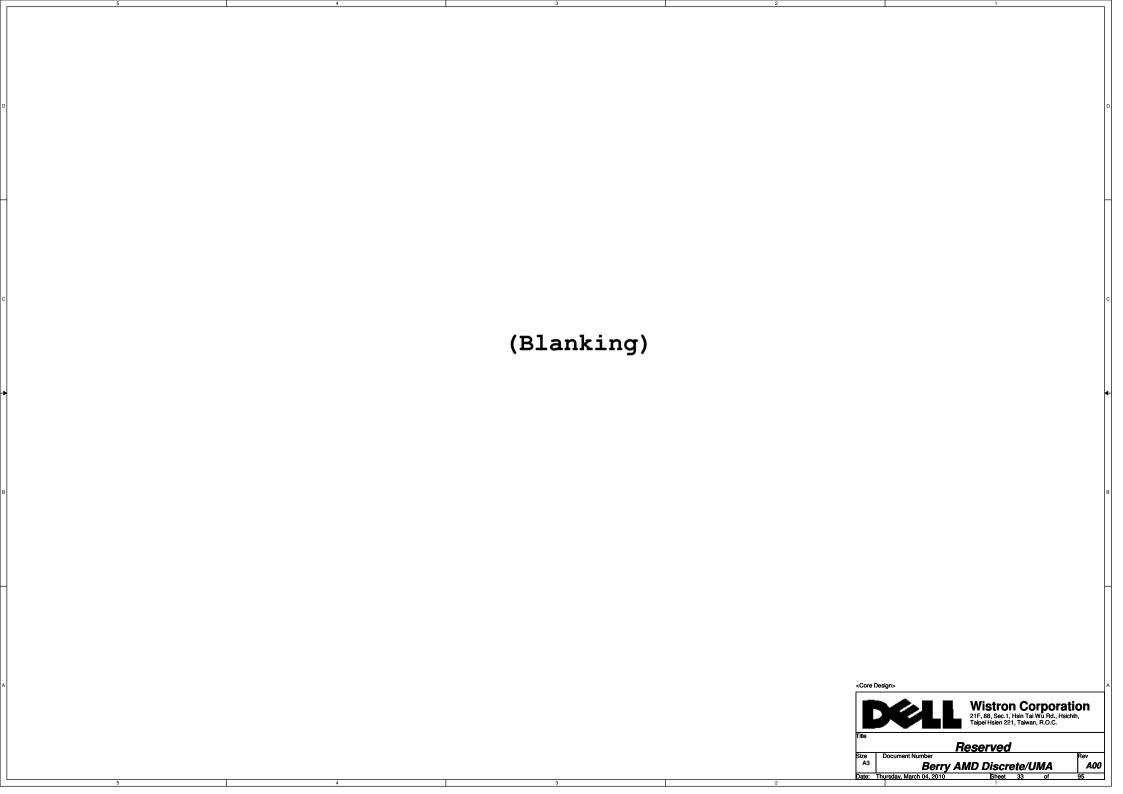


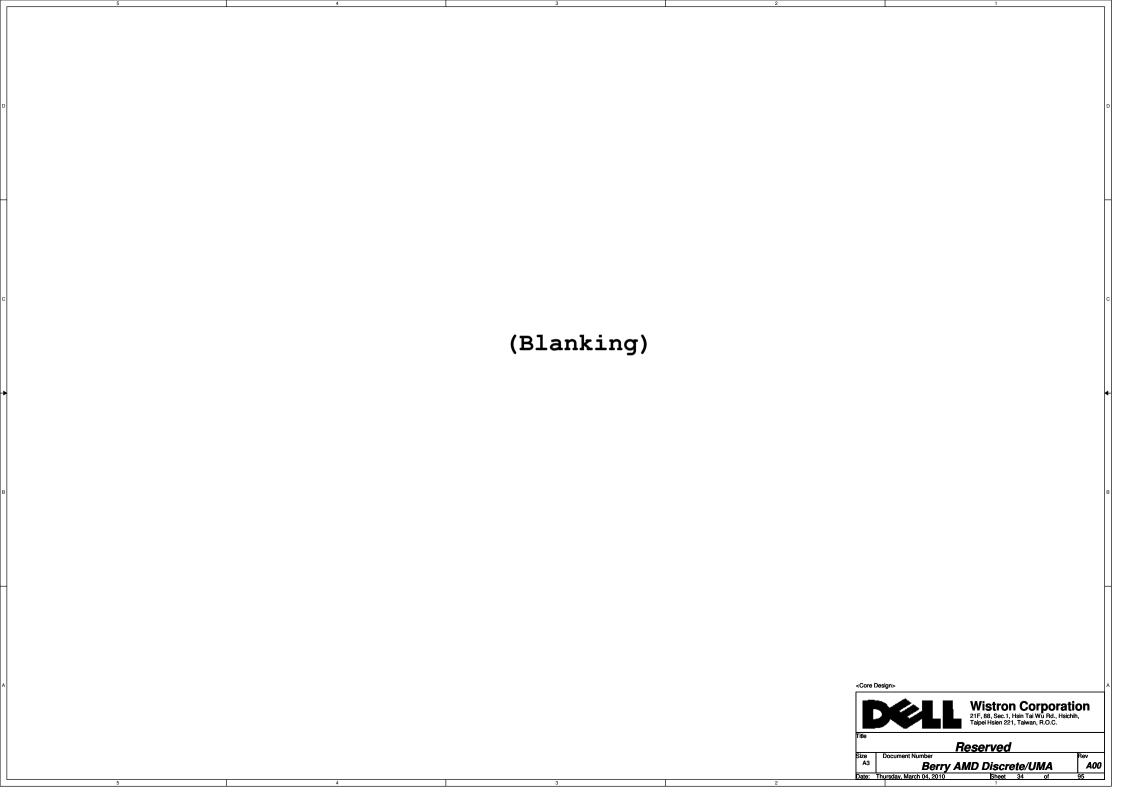


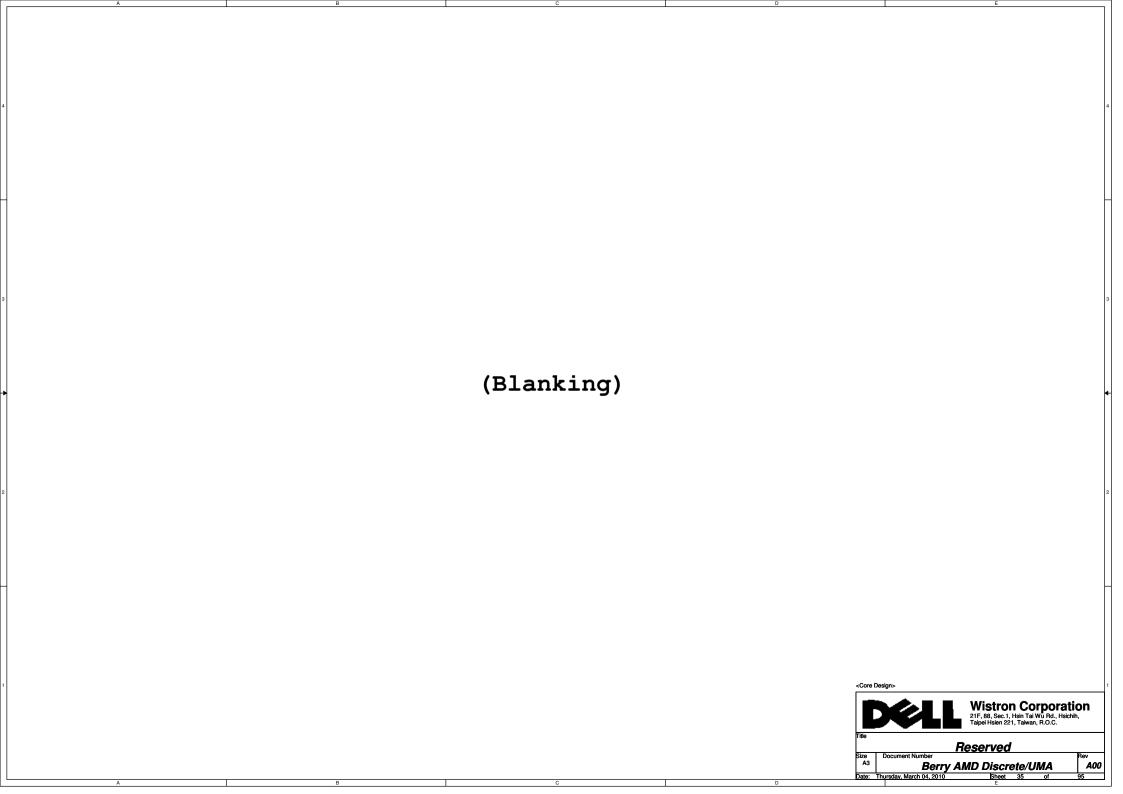


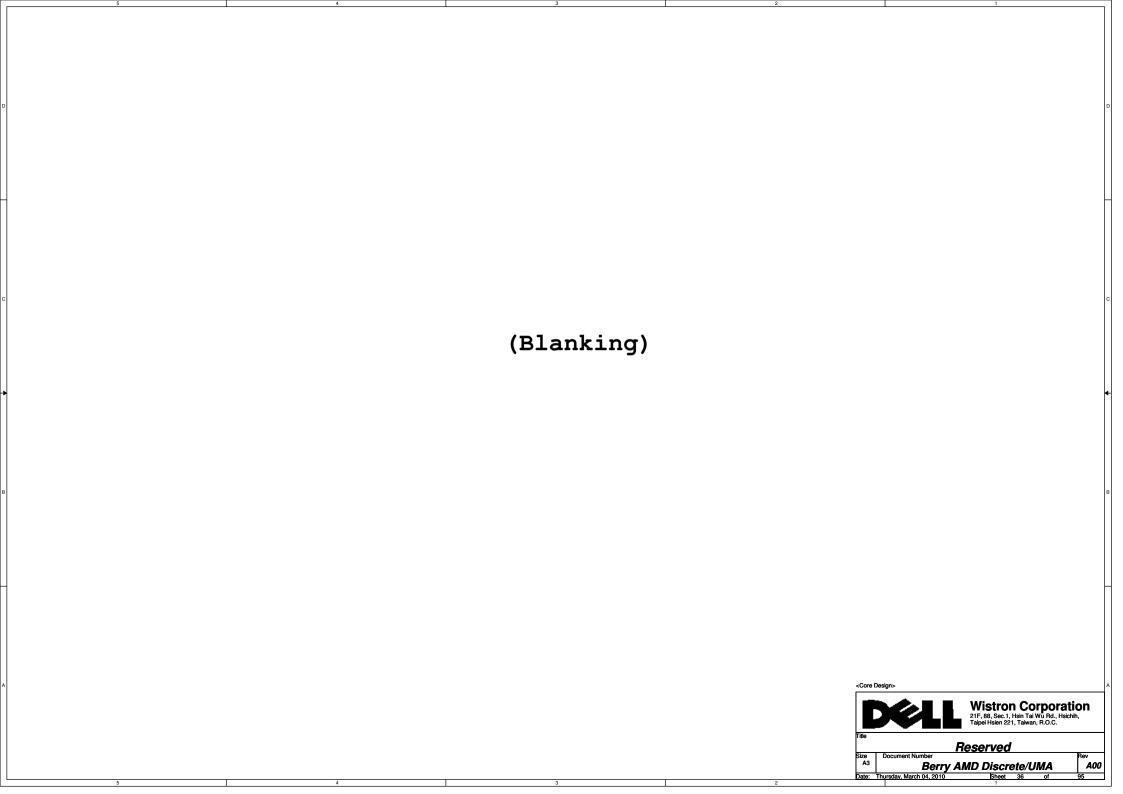


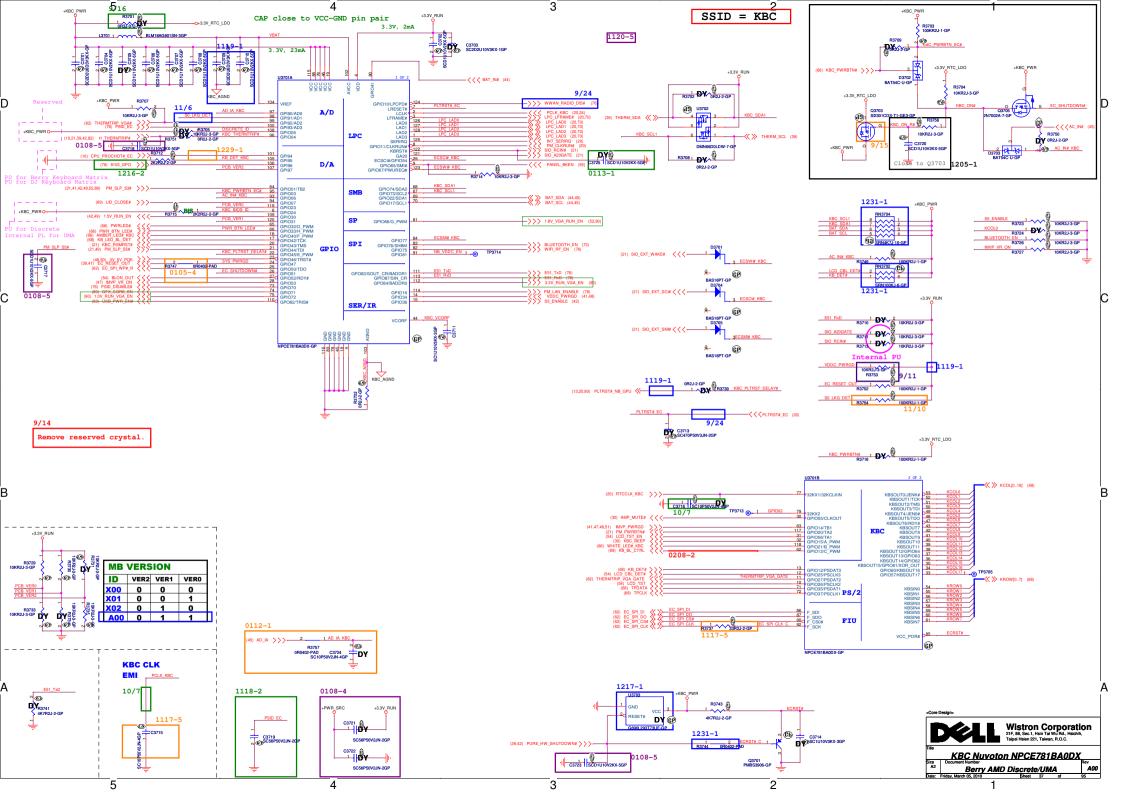


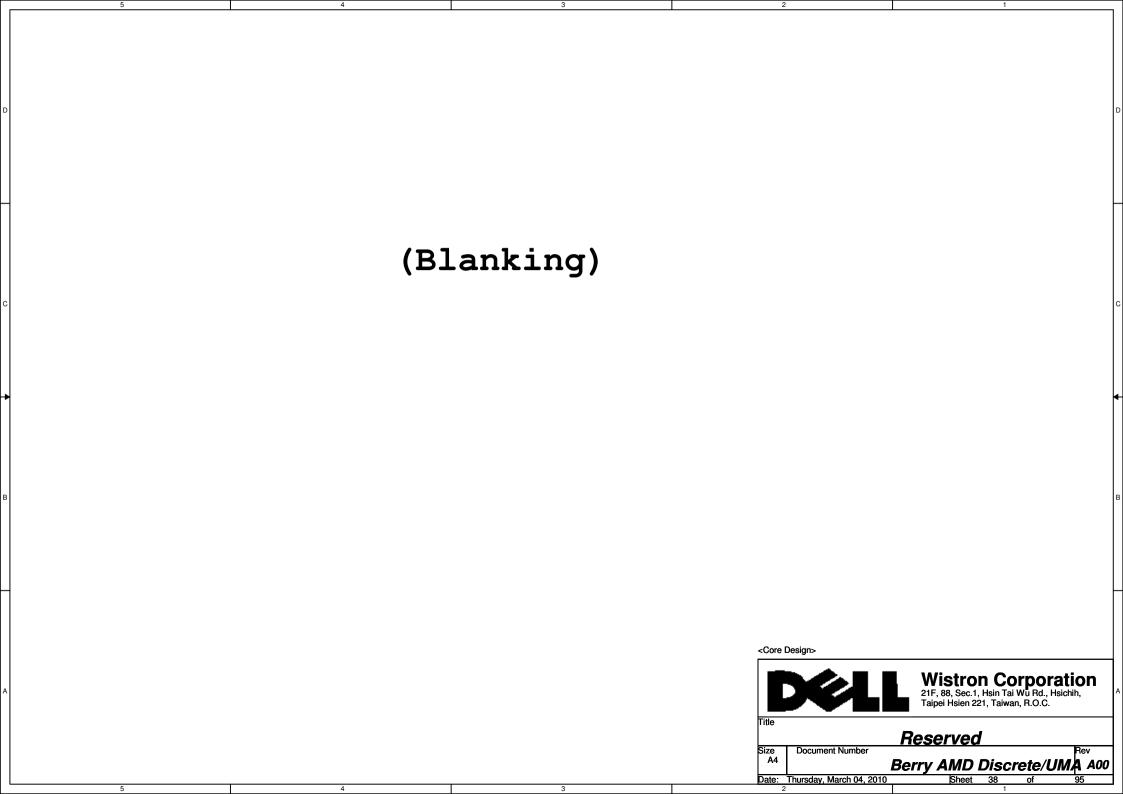


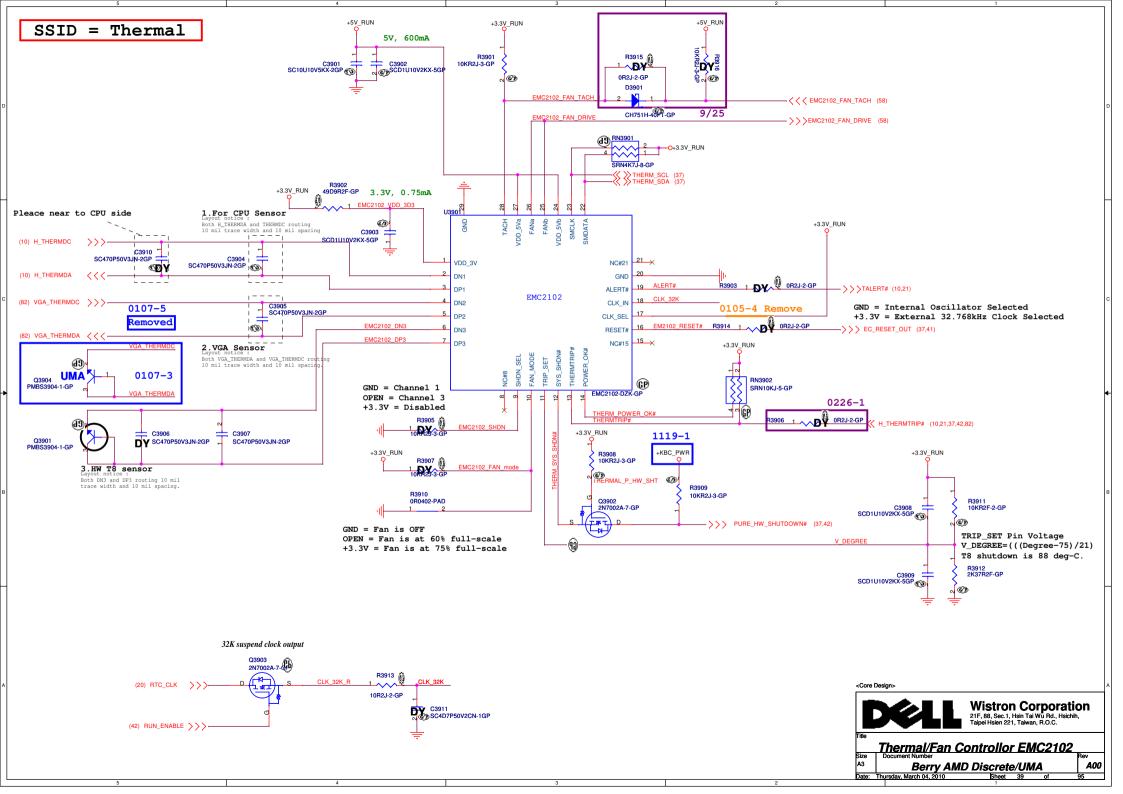


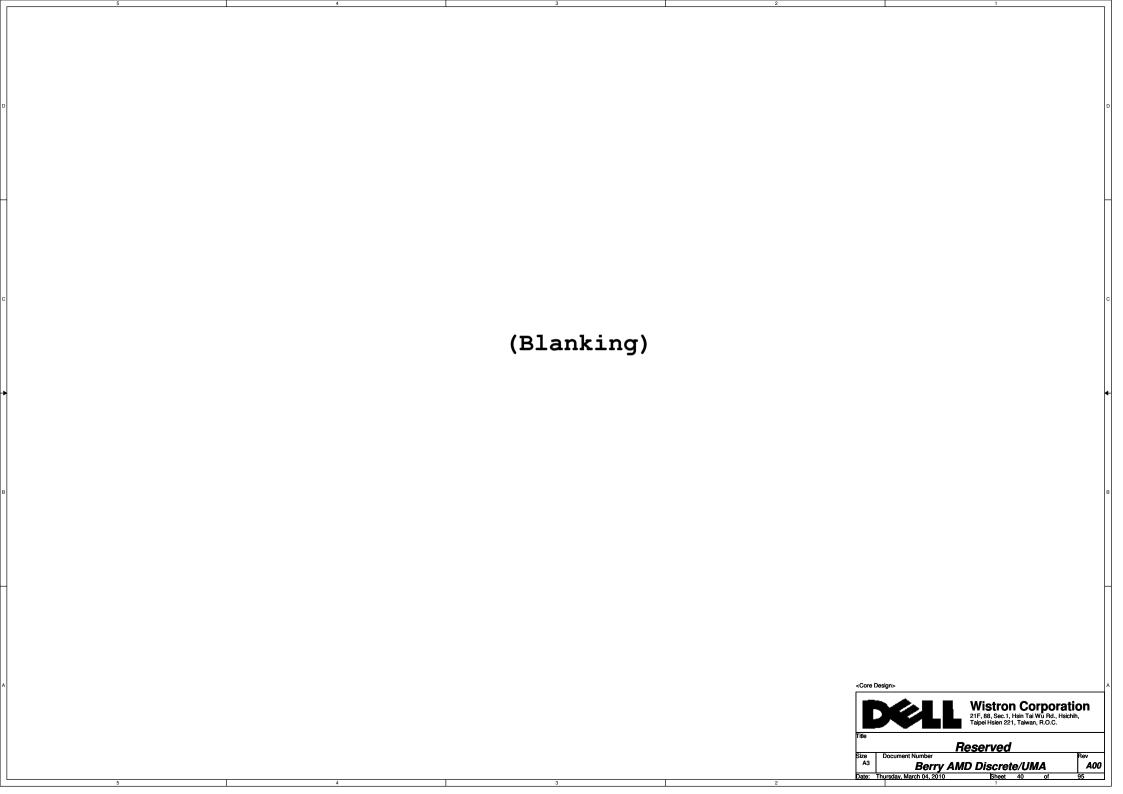


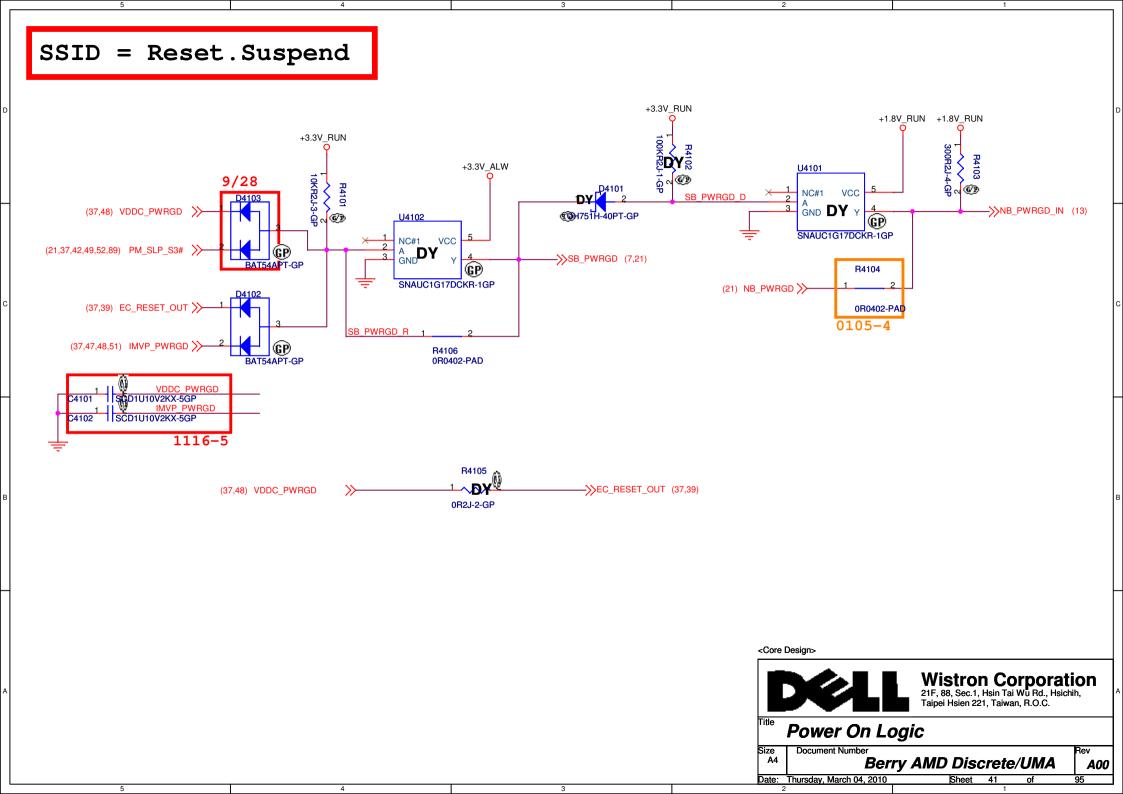


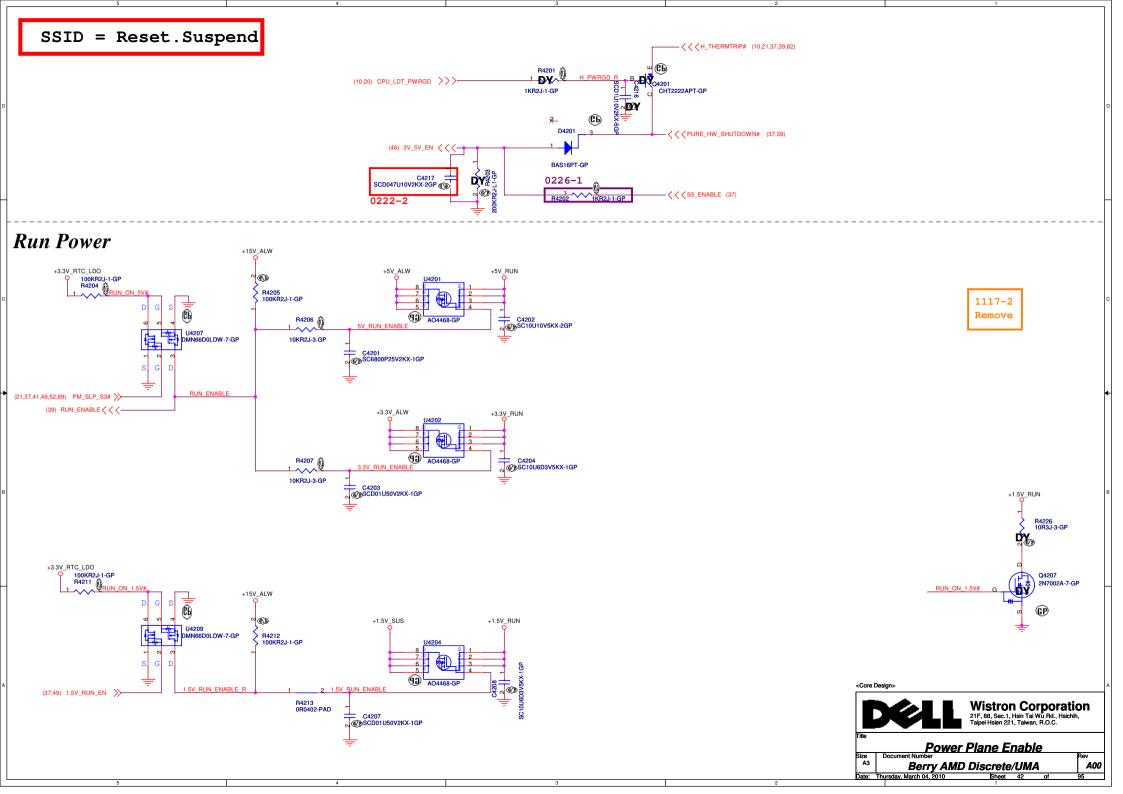


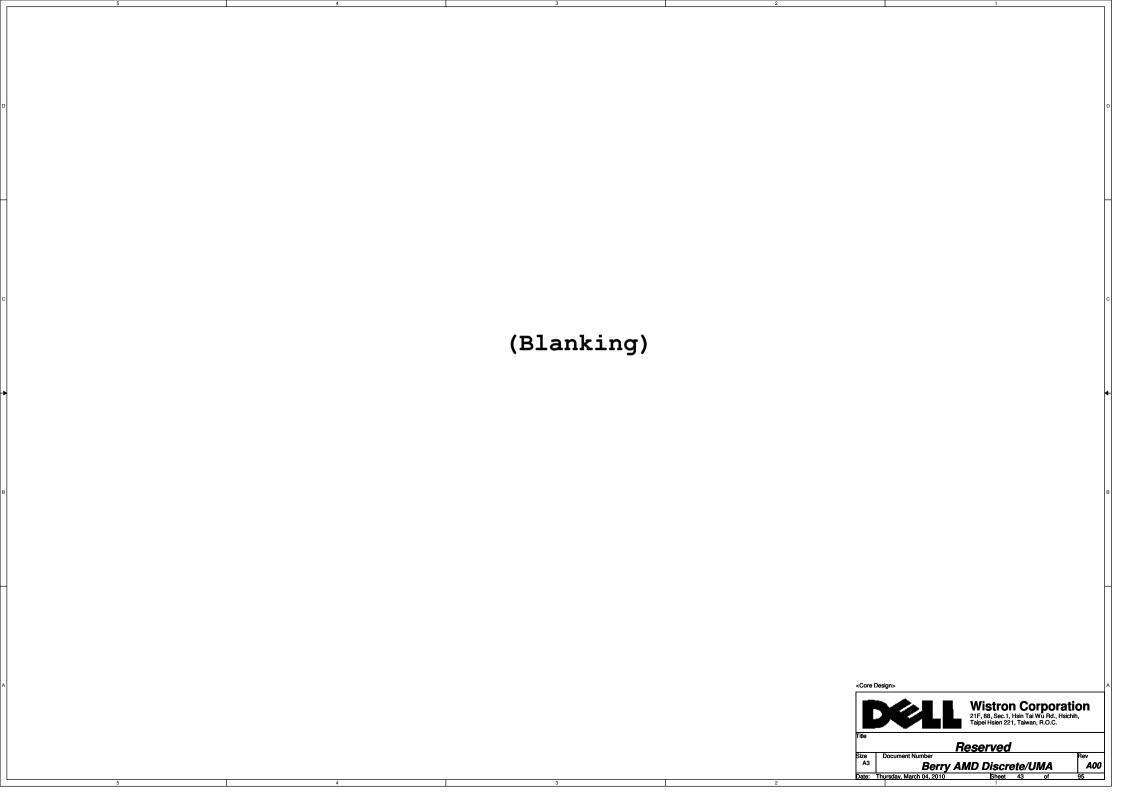


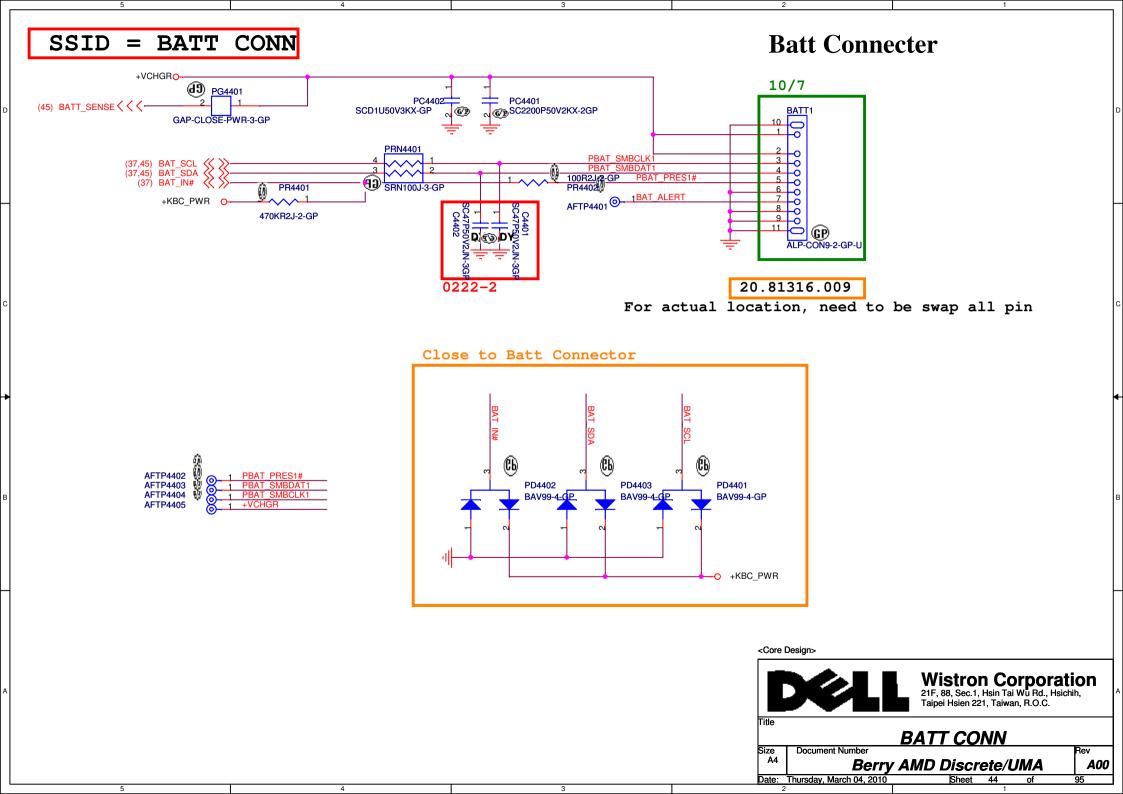


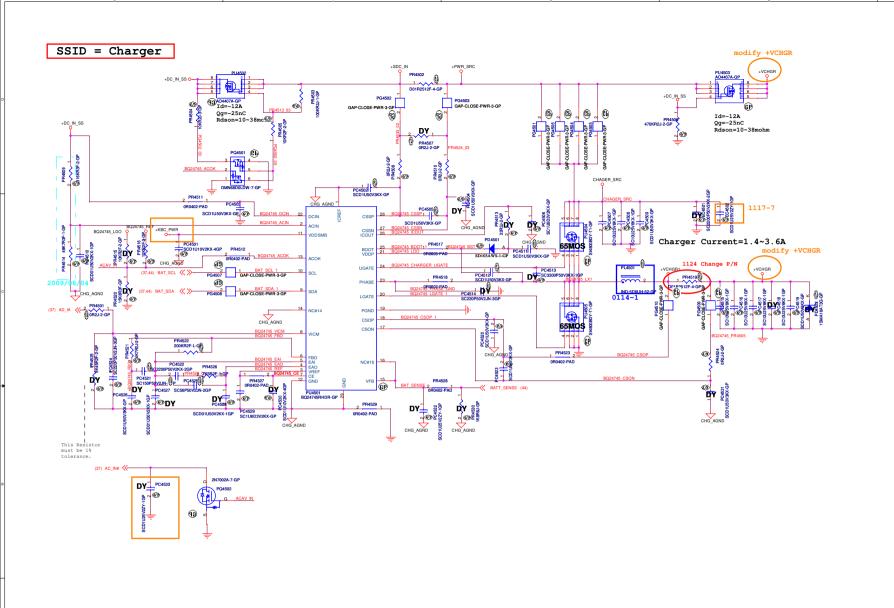


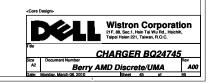


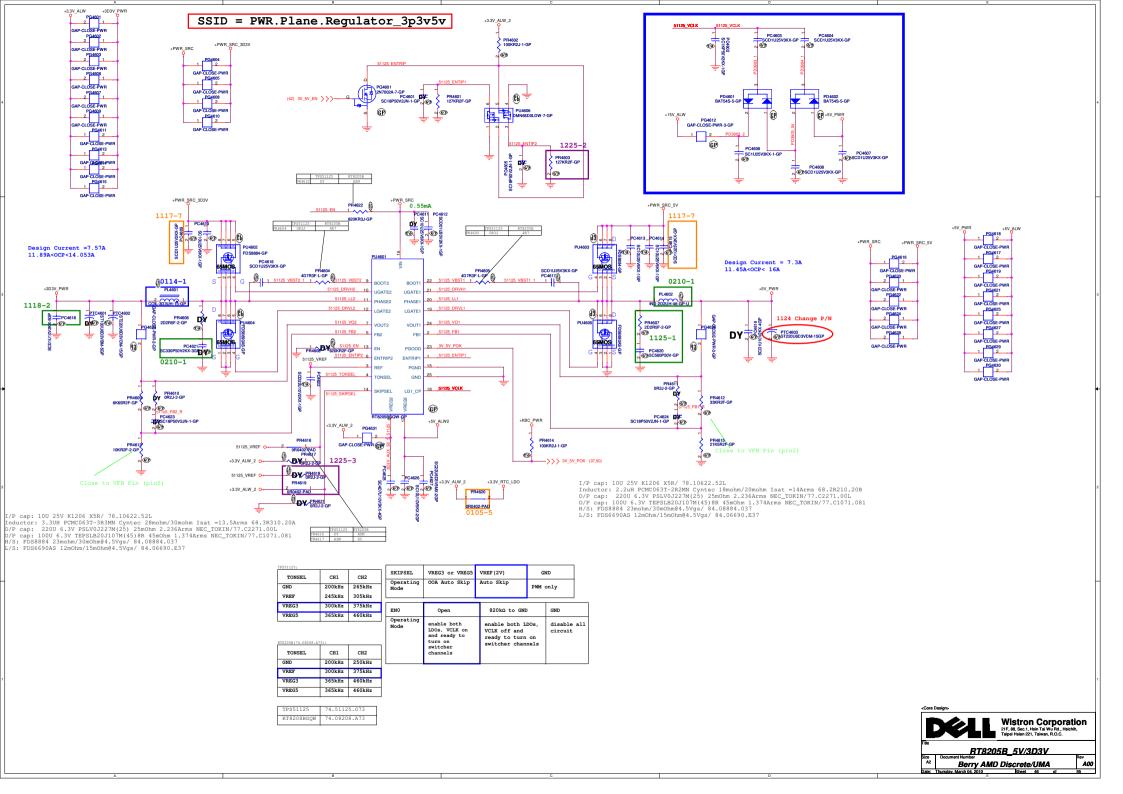


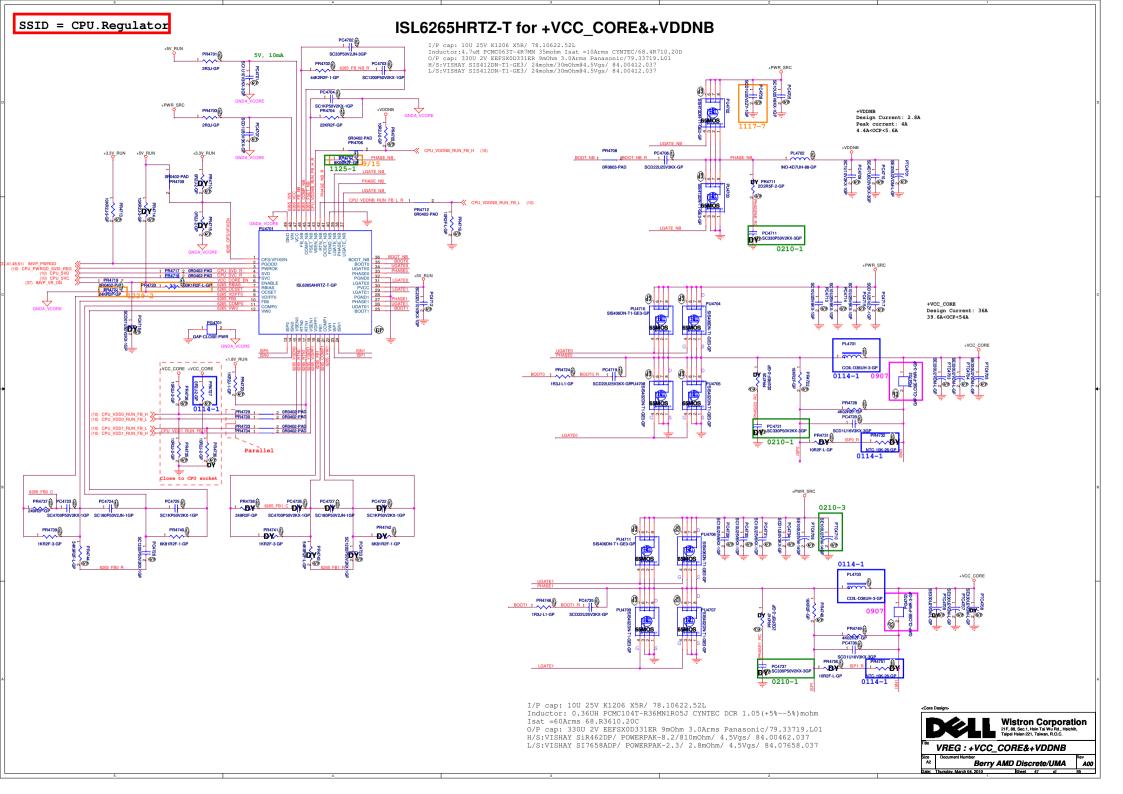


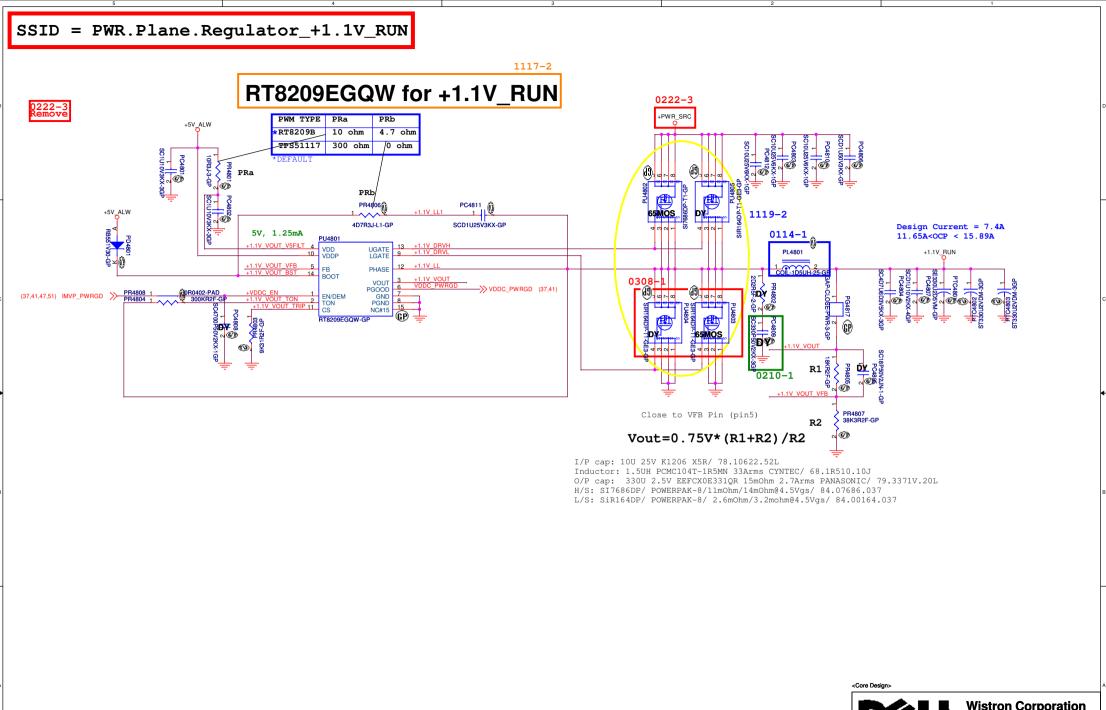




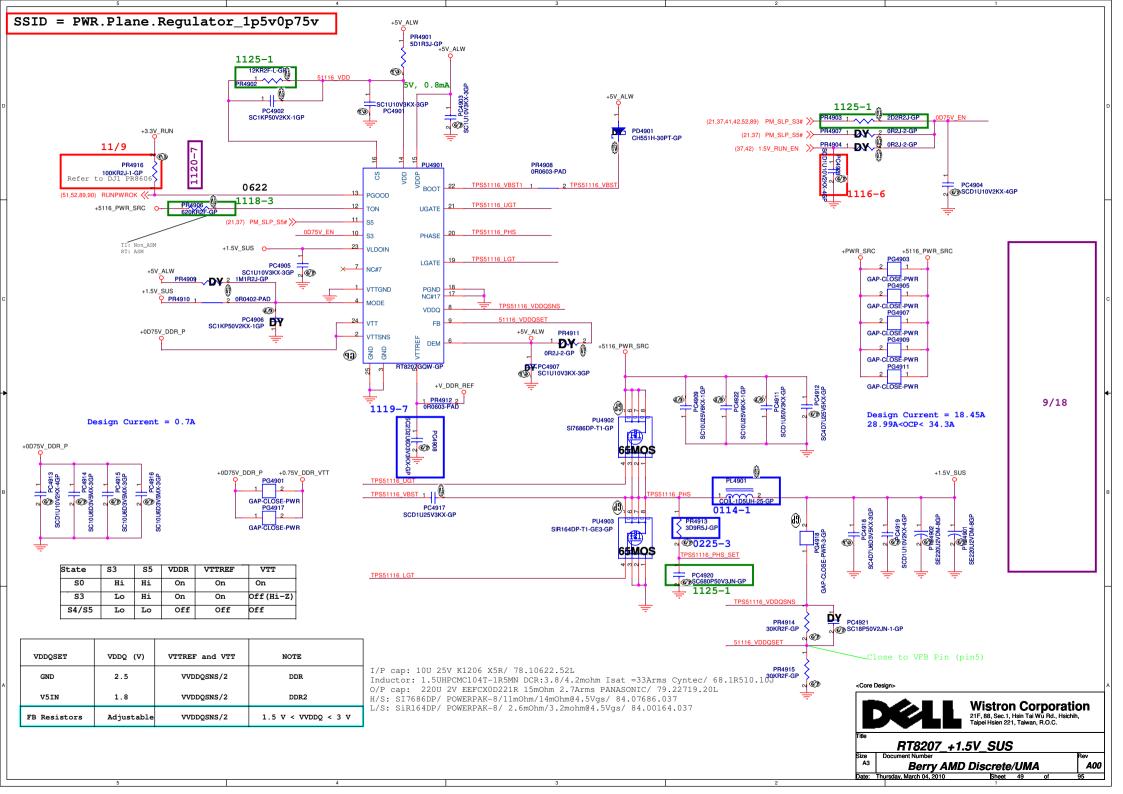






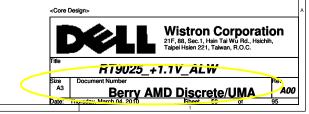


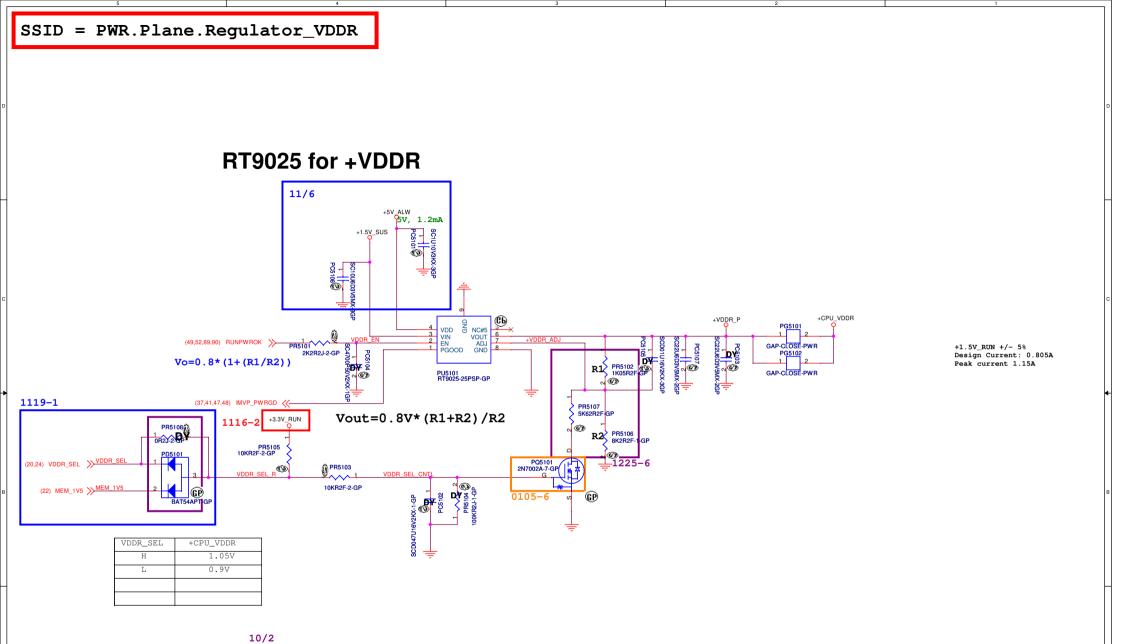


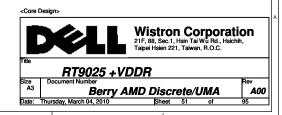


1117-2 RT9025 for +1.1V\_ALW +3.3V\_ALW 0106-1 10KR2J-3-GP +1.1V\_ALW\_P VDD & NC#5
VIN VOUT
EN ADJ
PGOOD GND 1 PR5002 2K2R2J-2-GP (37,46) 3V\_5V\_POK >> GAP-CLOSE-PWR PG5001 PC5004 (8) DD01U16VZKX GAP-CLOSE-PWR PU5001 RT9025-25PSP-GP Vo=0.8\*(1+(R1/R2)) Vout=0.8V\*(R1+R2)/R2 PR5003 2K7R2F-GP **@** 

SSID = PWR.Plane.Regulator\_+1.1V\_ALW

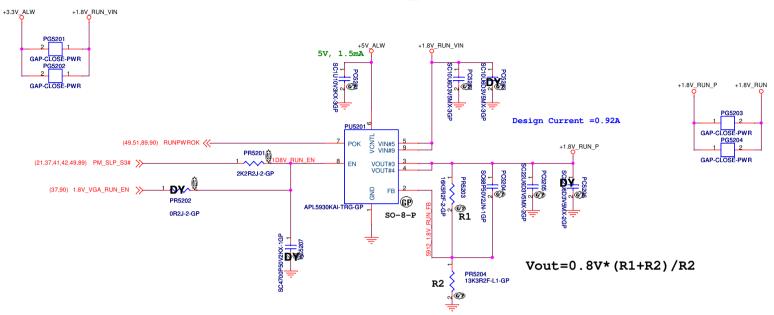




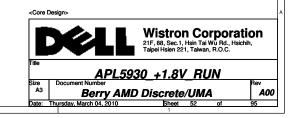


SSID = PWR.Plane.Regulator\_1p8v

# **APL5930 for +1.8V\_RUN**



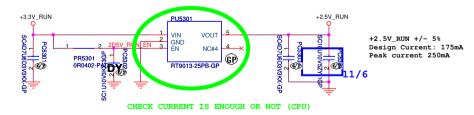
SSID = PWR.Plane.Regulator\_1p8v

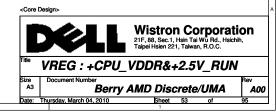


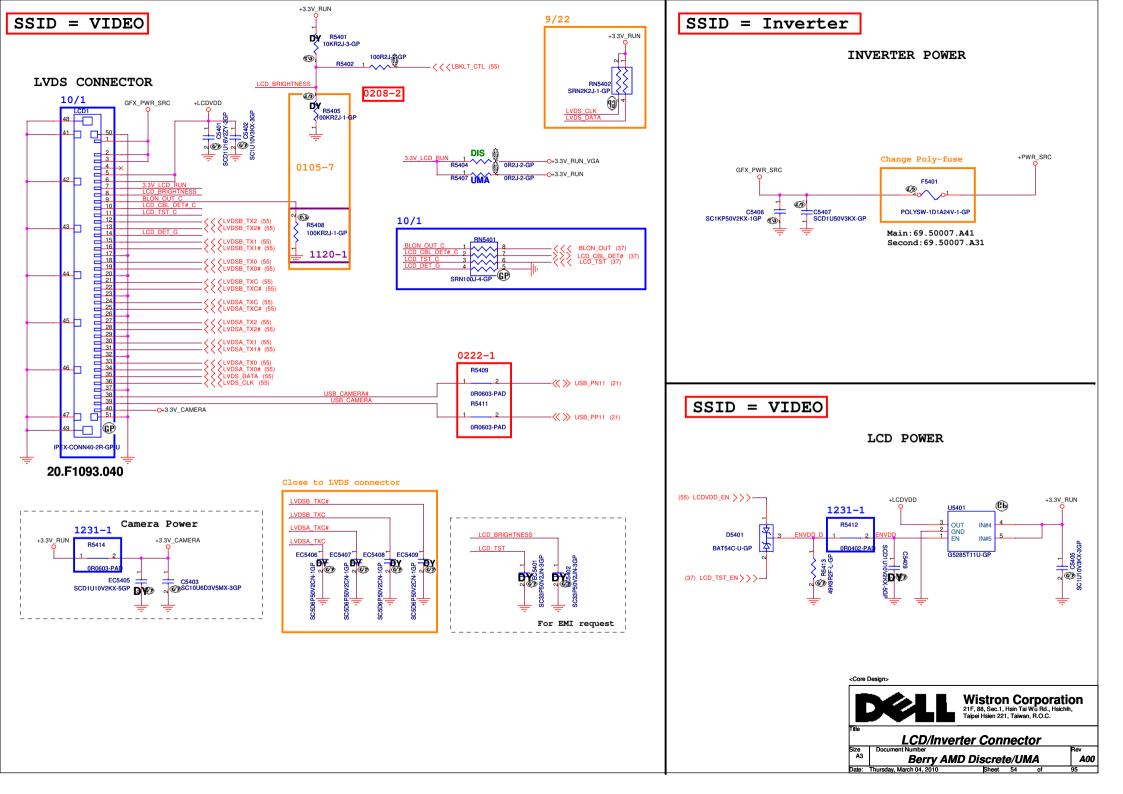
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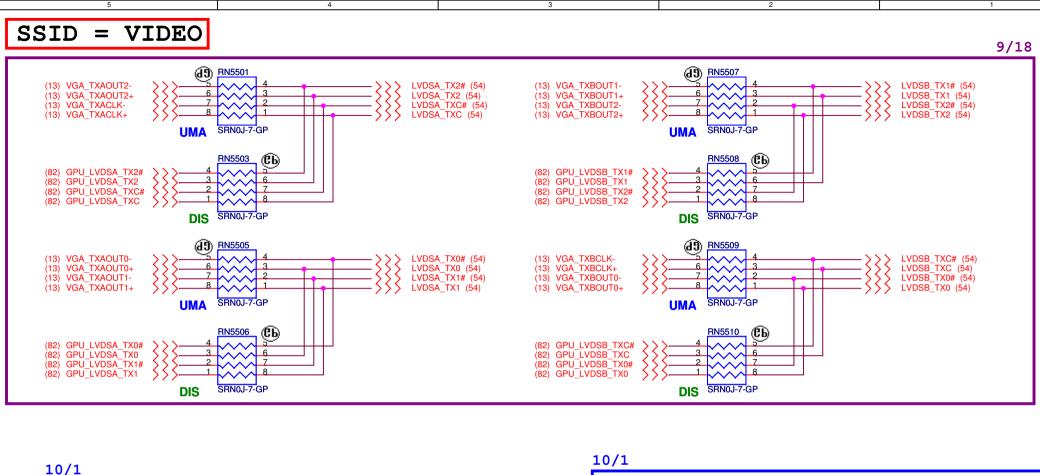
SSID = PWR.Plane.Regulator\_2p5v

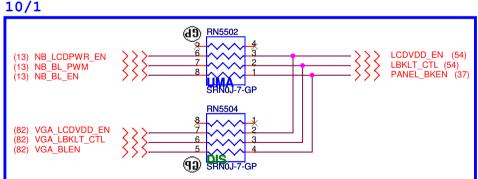
# RT9013-25PB for +2.5V\_RUN

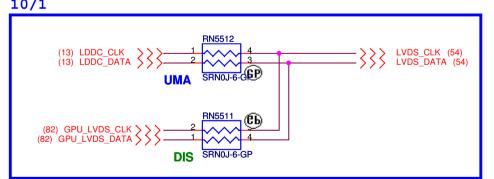




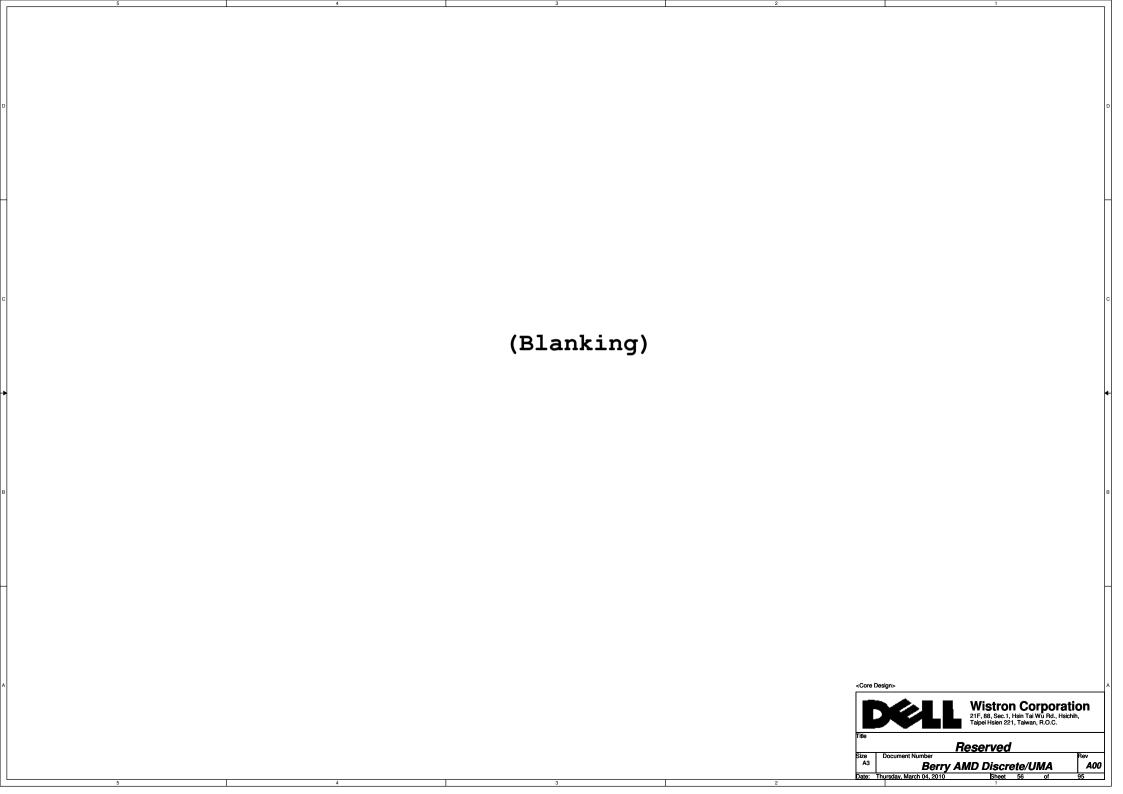


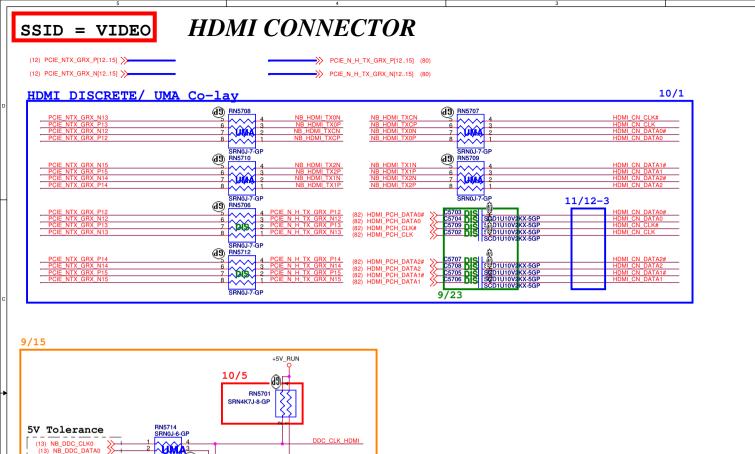












RN5713 SRN0J-6-GP

**DIS** 

+3.3V RUN

<u>=</u>

R5713 10KR2J-3-GP

Q5702

PMBS3904-1-GP

R5710

150KR2J-L1-GP

HPD HDMI CON

R5712

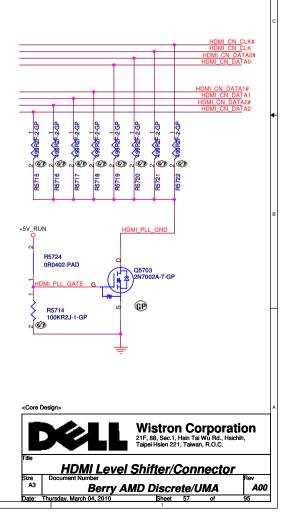
√ @®

200KR2J-L1-GP

(82) GPU\_HDMI\_CLK (82) GPU\_HDMI\_DATA

(13,82) HDMI\_HPD\_DET < < < -

9/22



HDMI CONN

O 20

0 6

0 10

0 11 0 12 13

0 16

SKT-HDMI1

0

0 7

22.10296.211

AFTP5703

TP5702

AFTP5708

AFTP5712

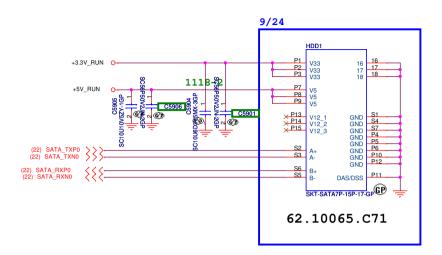
C5701 (B)

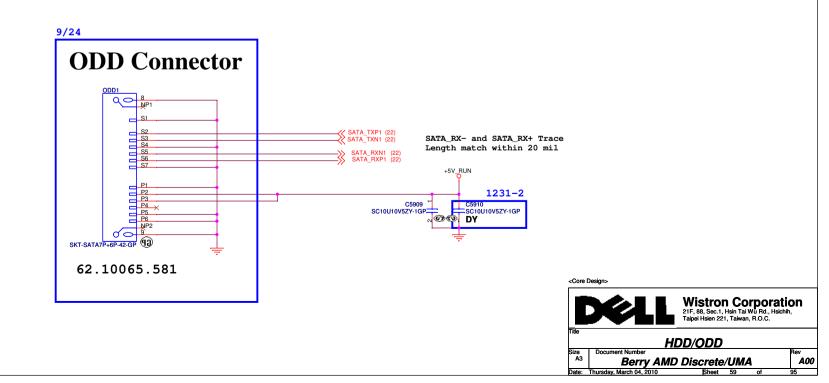
HDMI CN DATAO# PF5711
HDMI CN CLK 1 TP5710

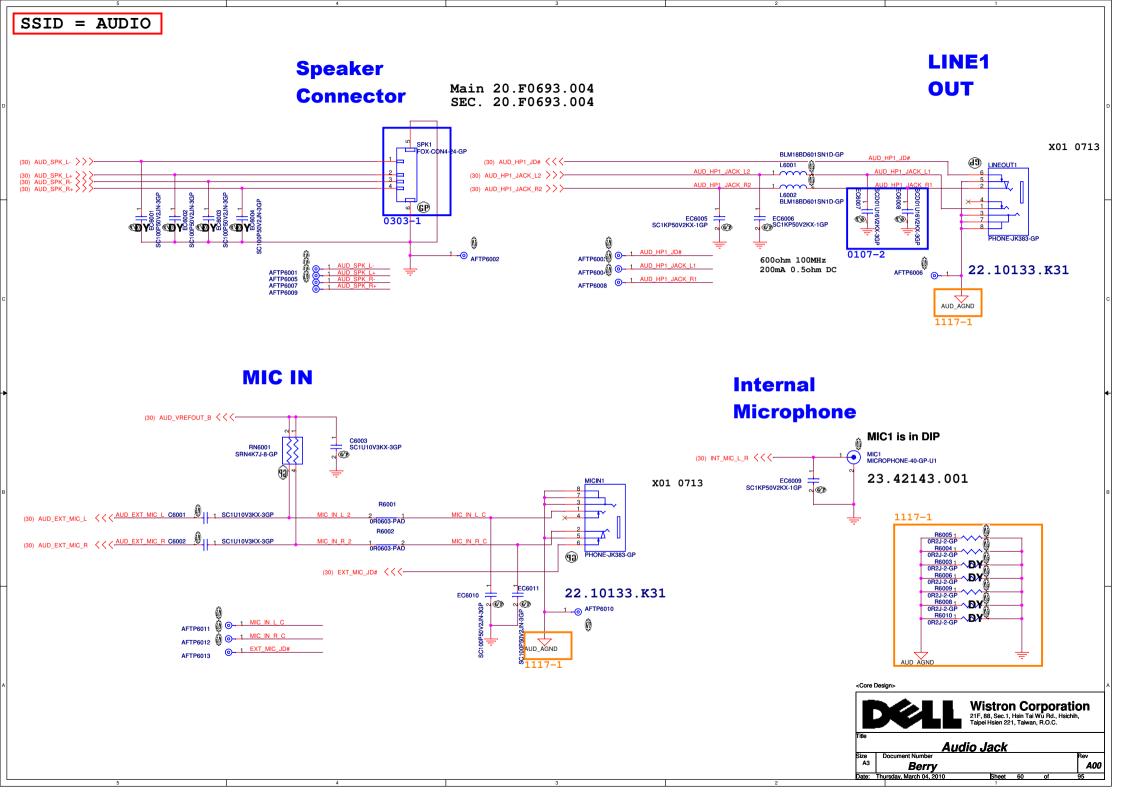
HDMI CN CLK# 1

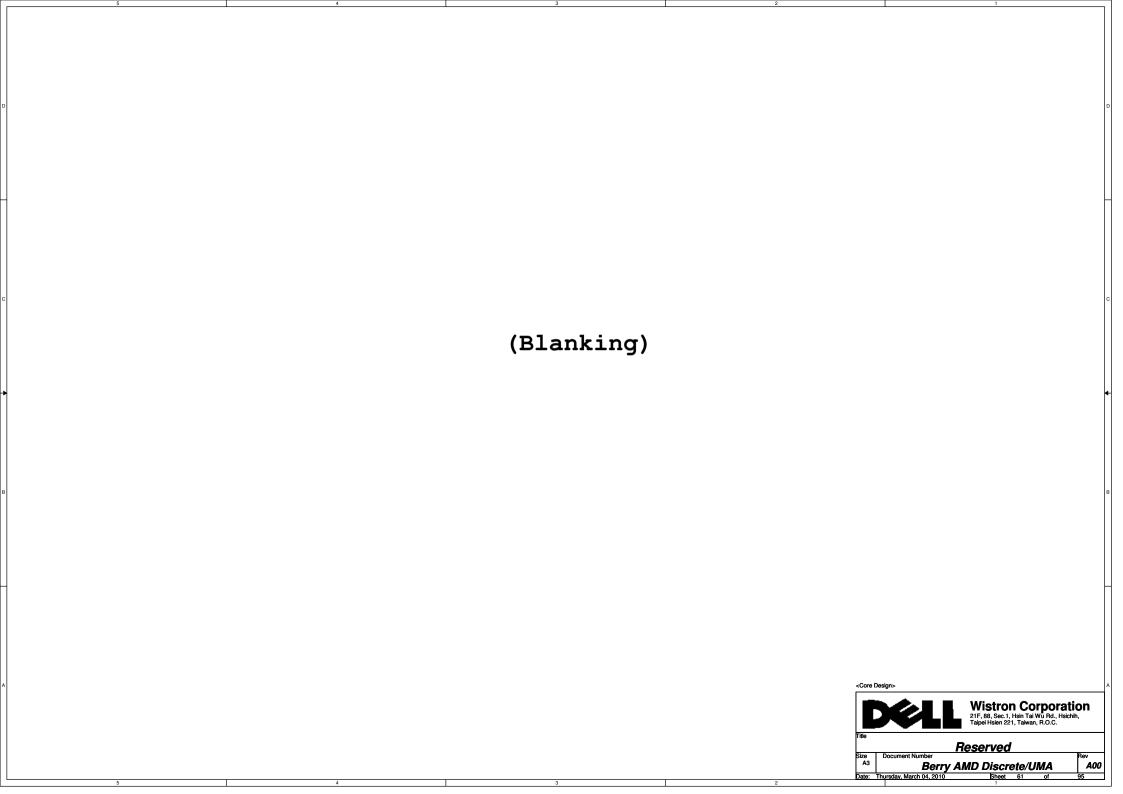
SSID = User.Interface SSID = Thermal **Fan Connector** \*Layout\* 15 mil (39) EMC2102\_FAN\_DRIVE >>> EMC2102\_FAN\_DRIVE O 1 EMC2102\_FAN\_TACH FOX-CON3-6-GP-U AFTP5803 (1) O 1 EMC2102 FAN\_DRIVE 20.D0210.103 20.F1293.003 D5801 CH551H-30PT-GP C5801 SC10U10V5ZY-1GP Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. ITP/Fan Connector Berry AMD Discrete/UMA A00 SSID = SATA

# **SATA HDD Connector**



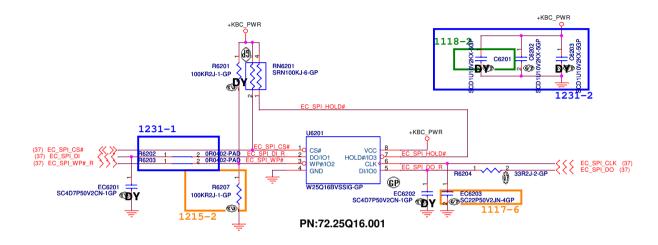


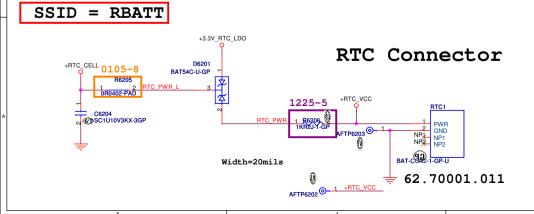


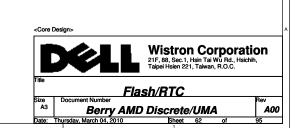


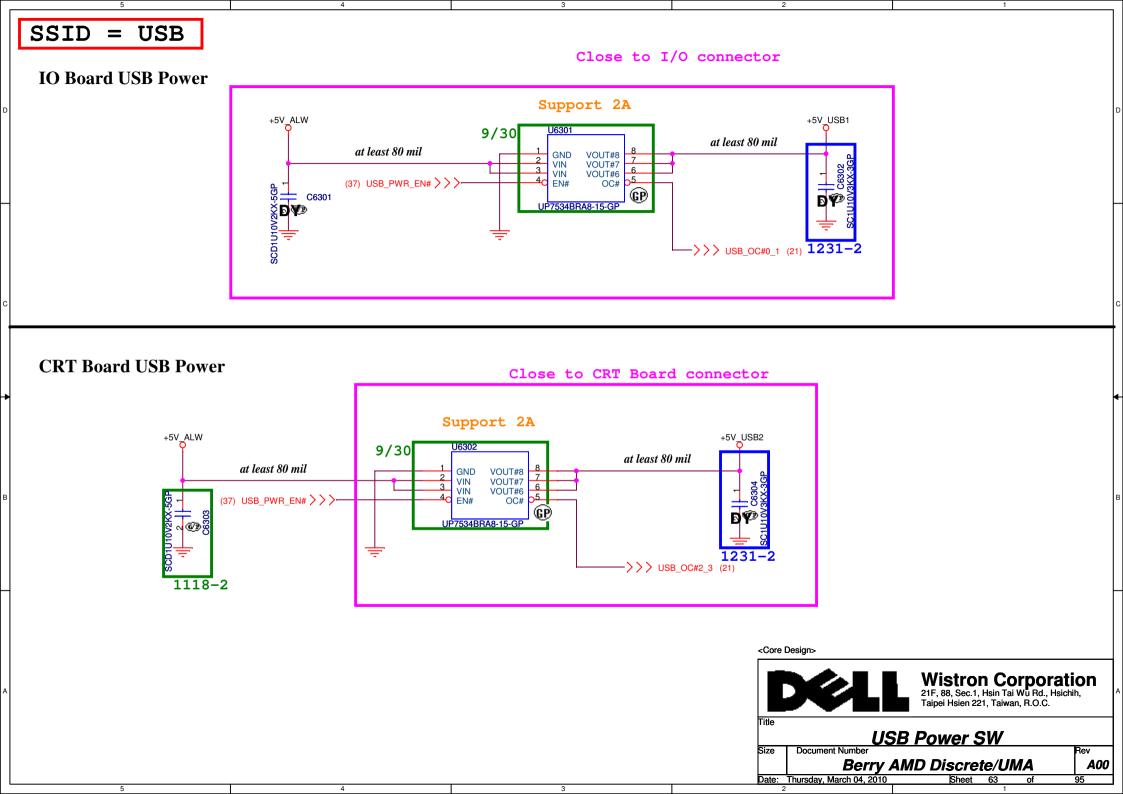
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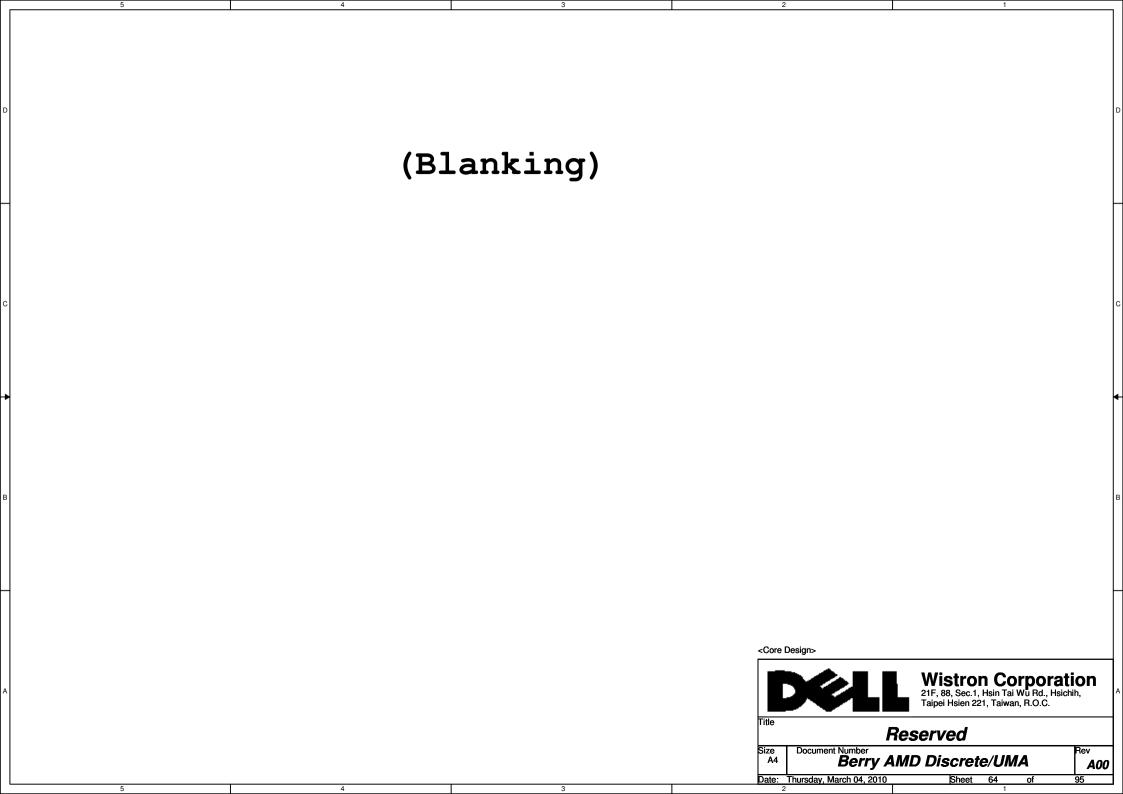
## SPI FLASH ROM (16M bits) for KBC

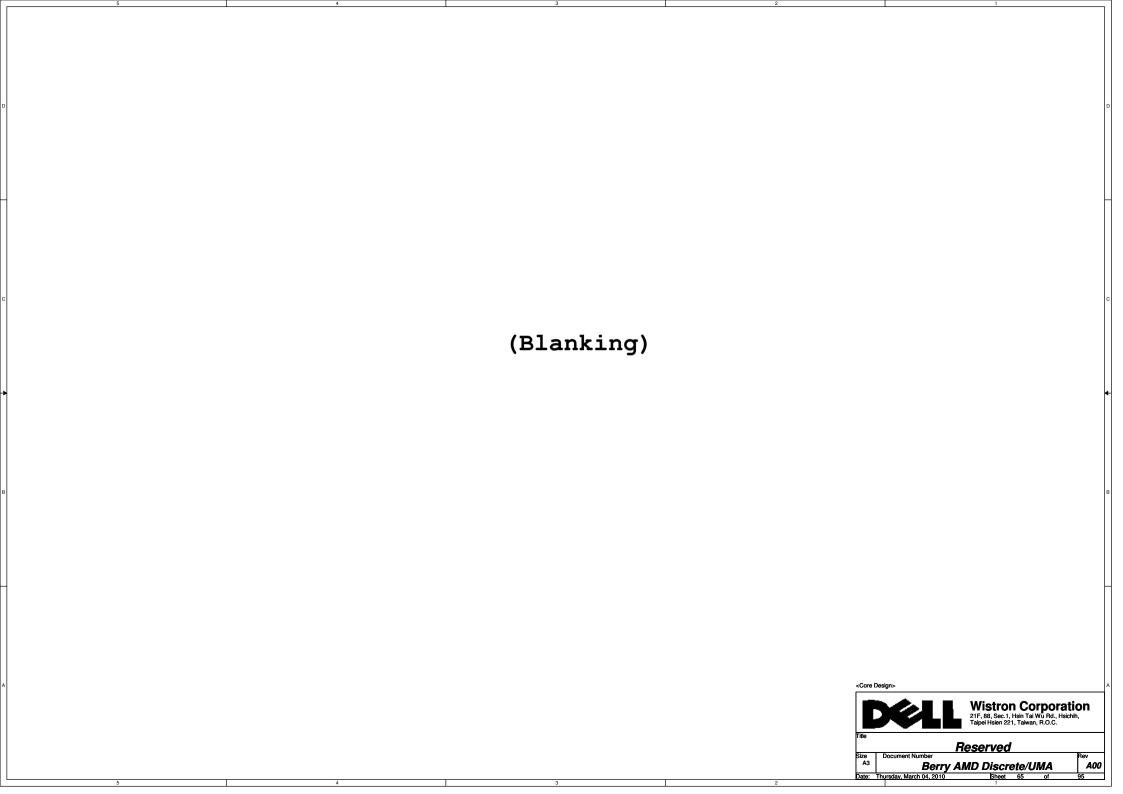


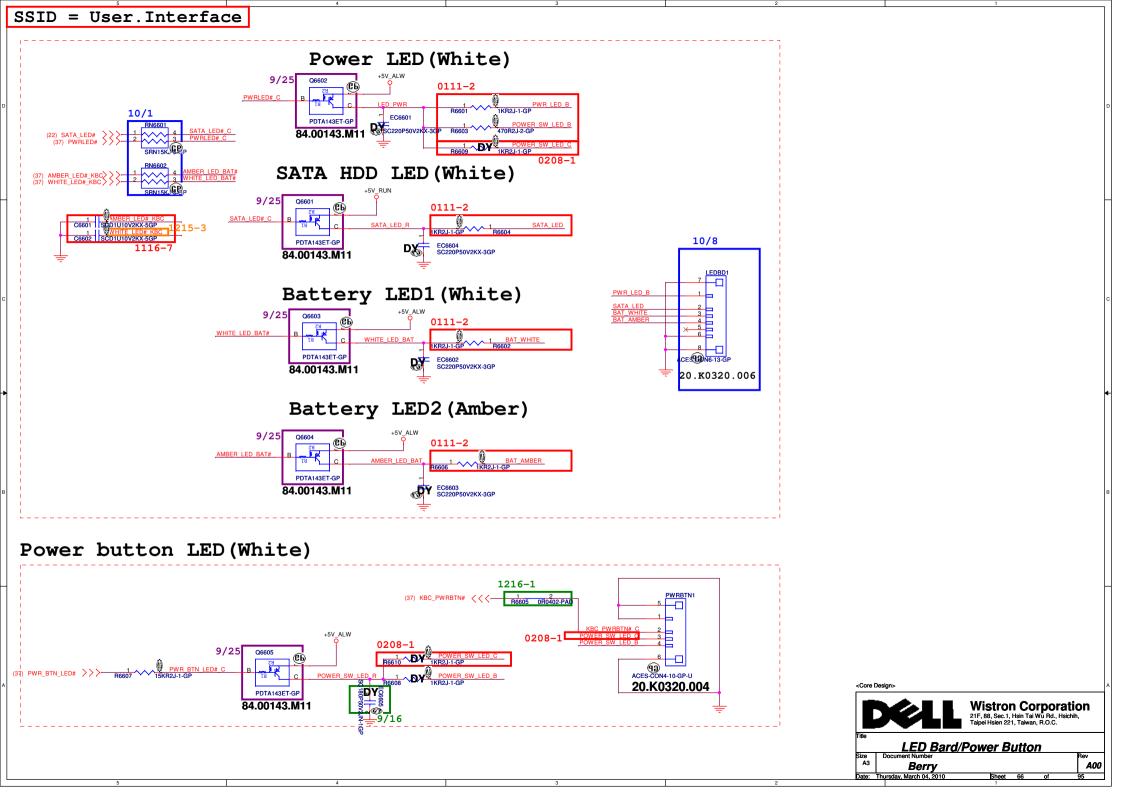


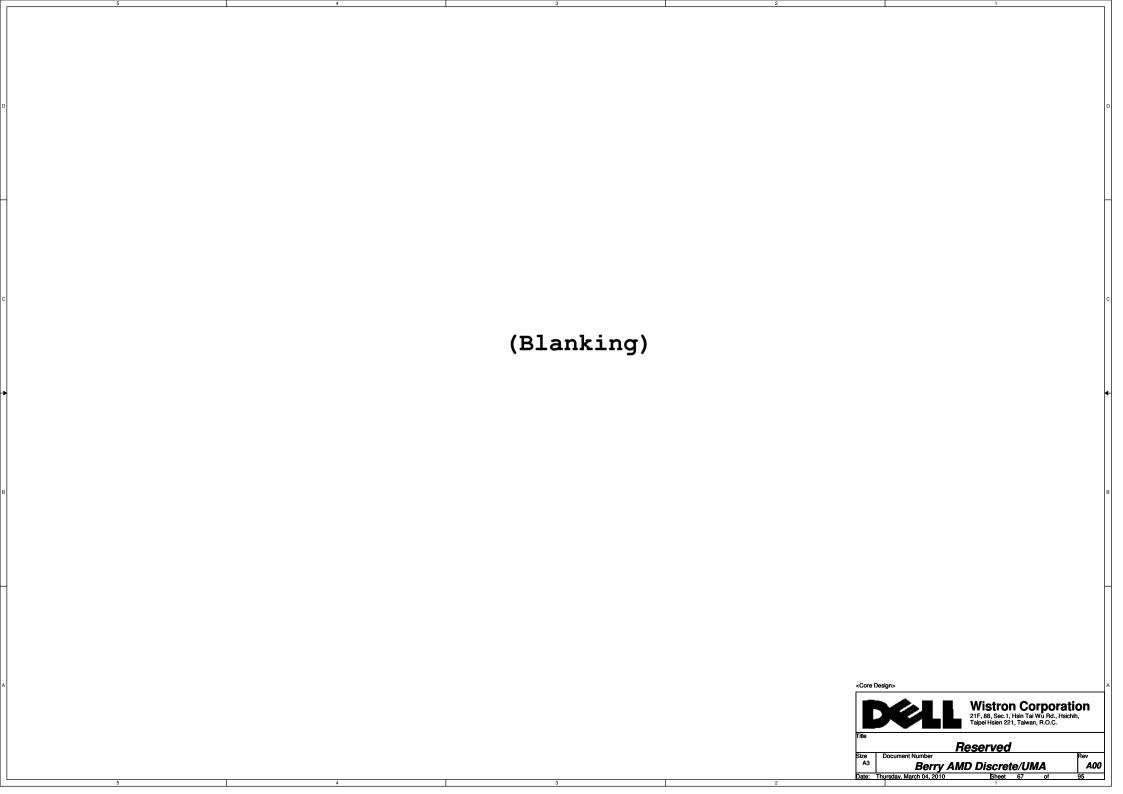






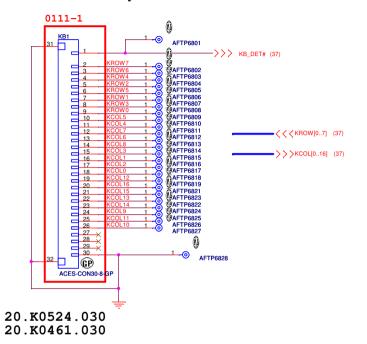






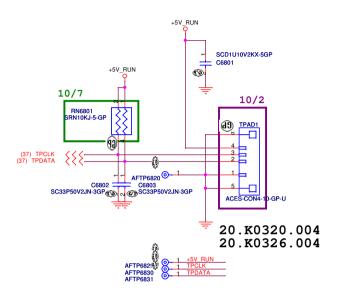


## **Internal KeyBoard Connector**

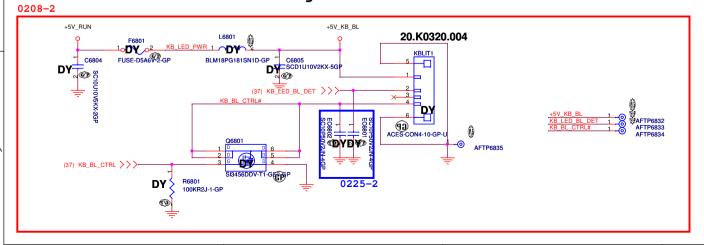


## SSID = Touch.Pad

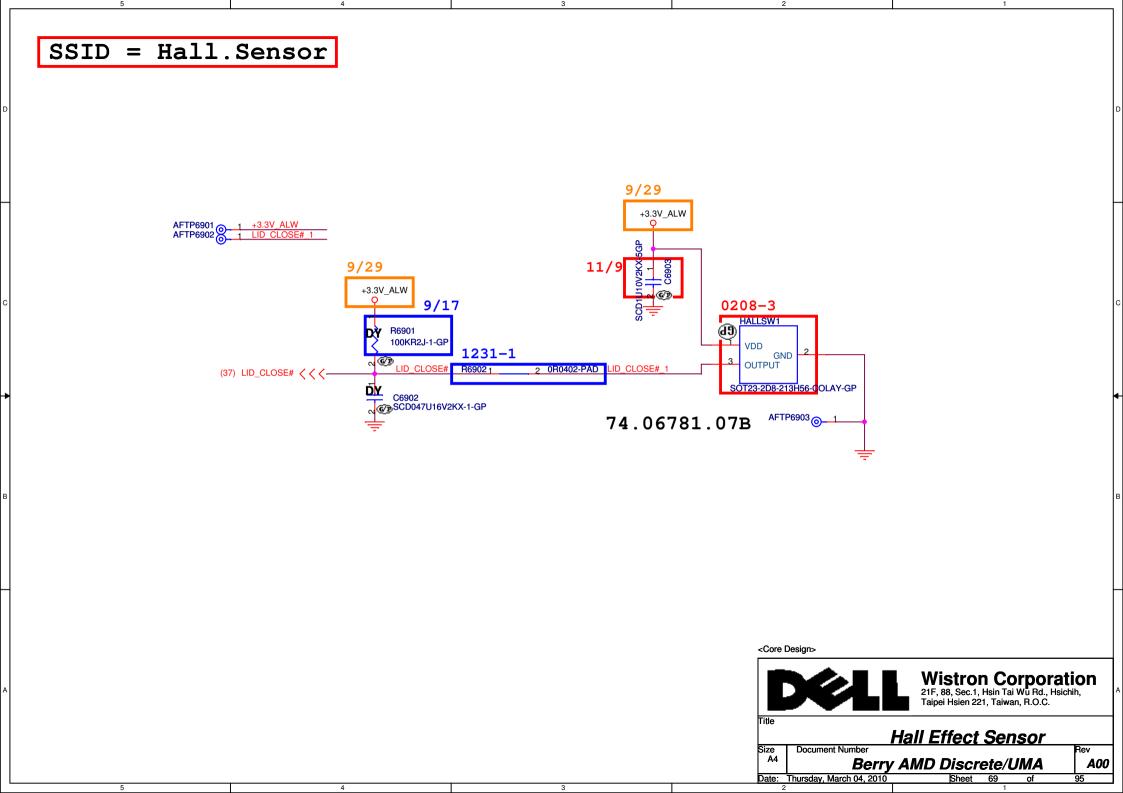
#### **TouchPad Connector**

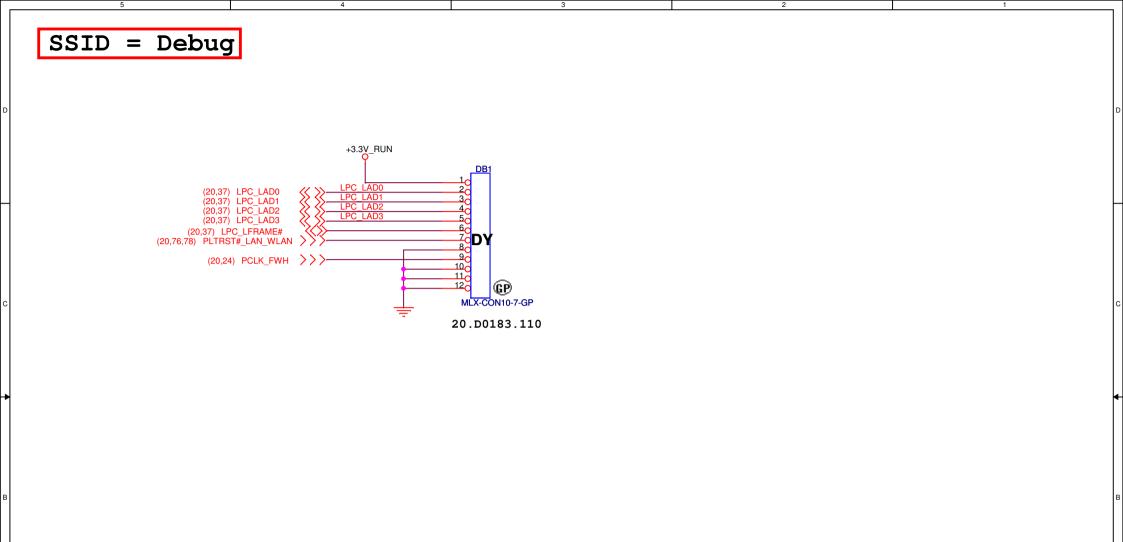


## KB Backlight Connector













# Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

**Dubug connector** 

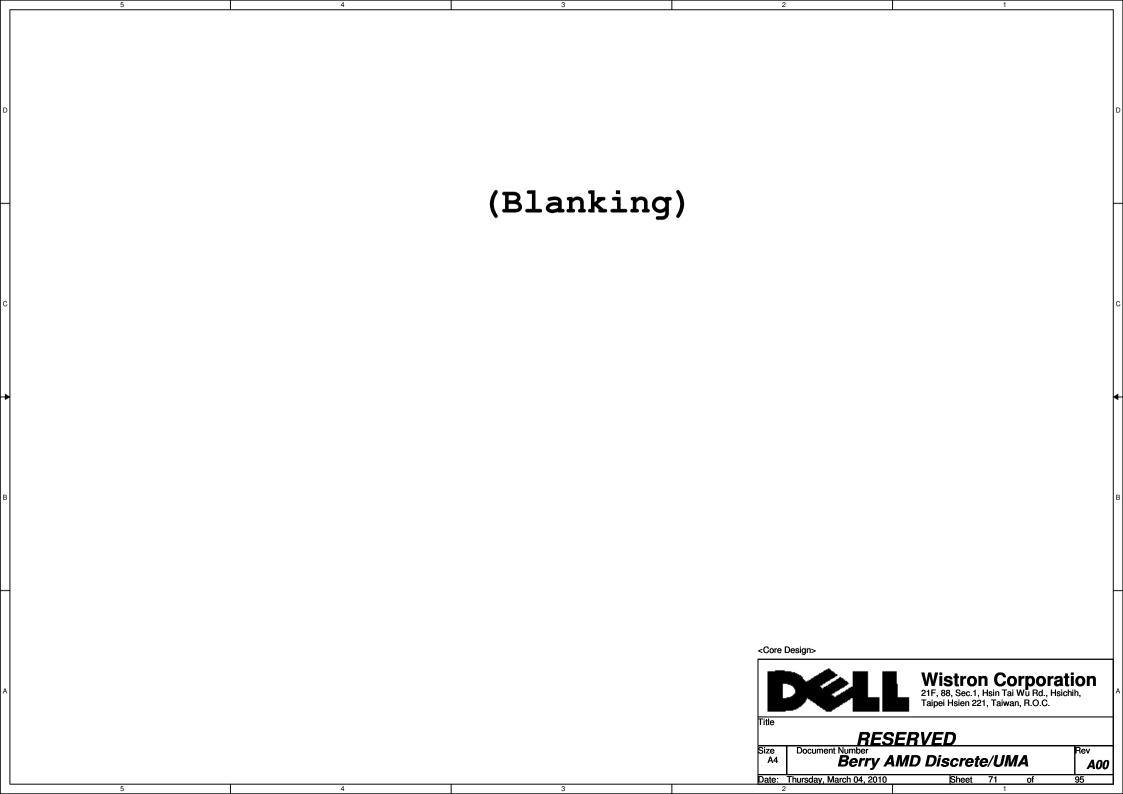
Document Number **Berry AMD Discrete/UMA** 

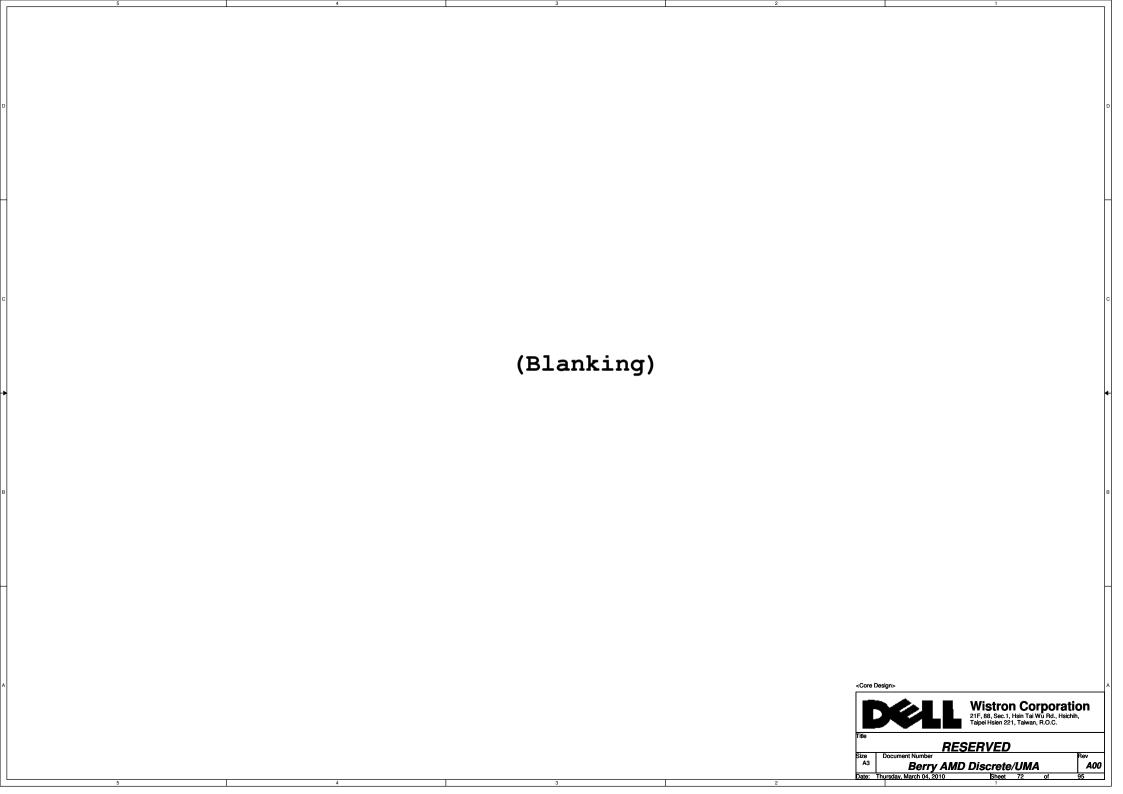
Date: Thursday, March 04, 2010

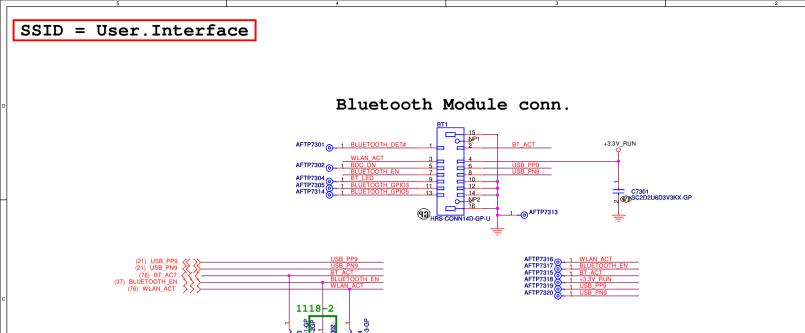
Sheet 70

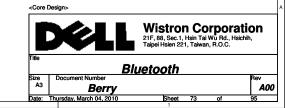
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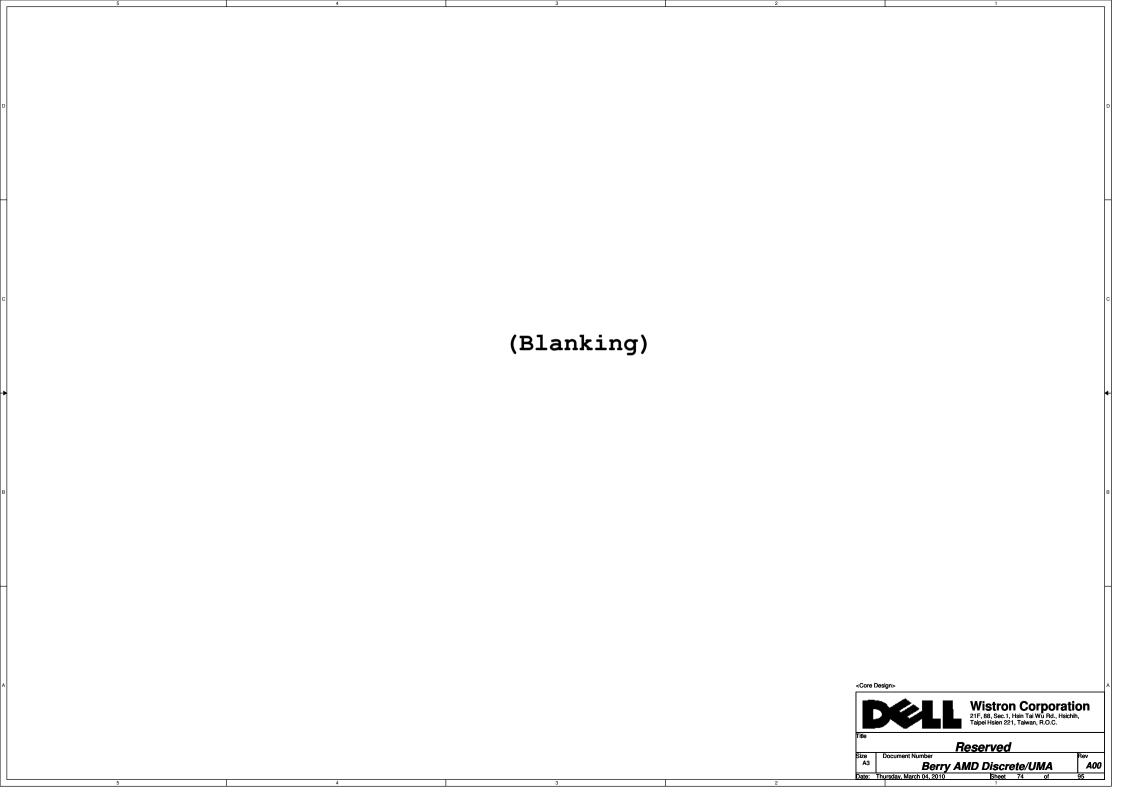
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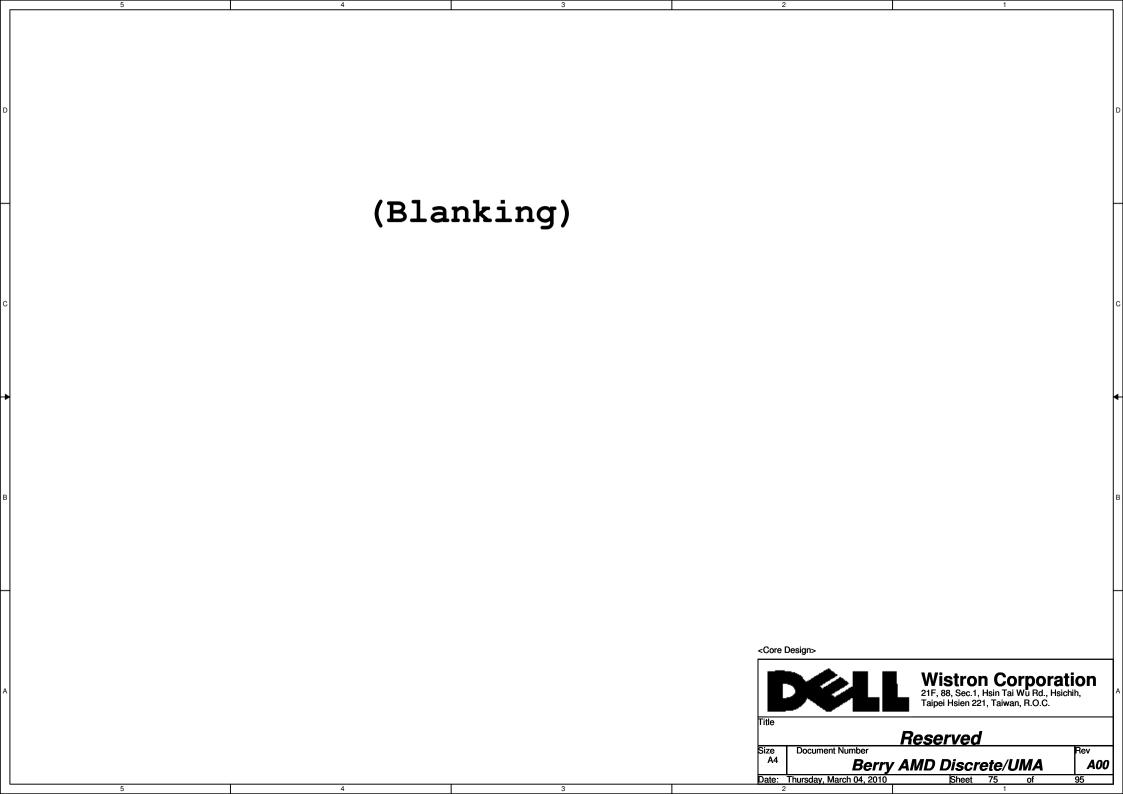


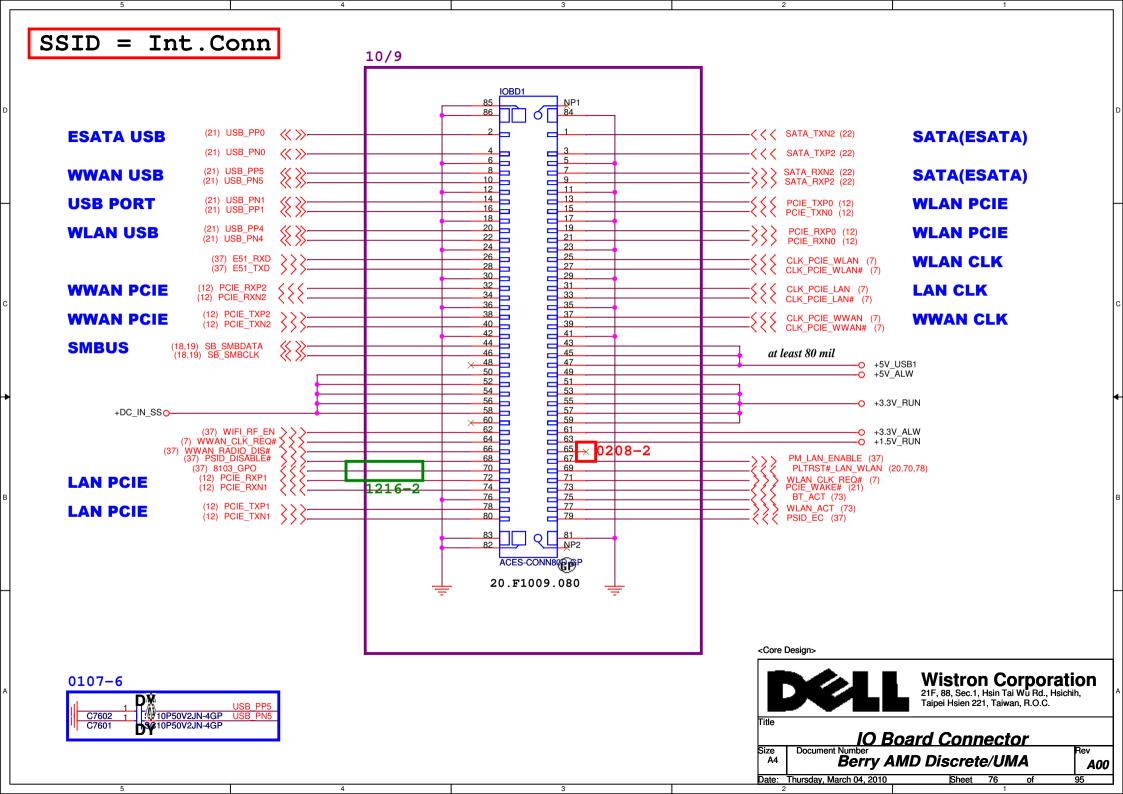


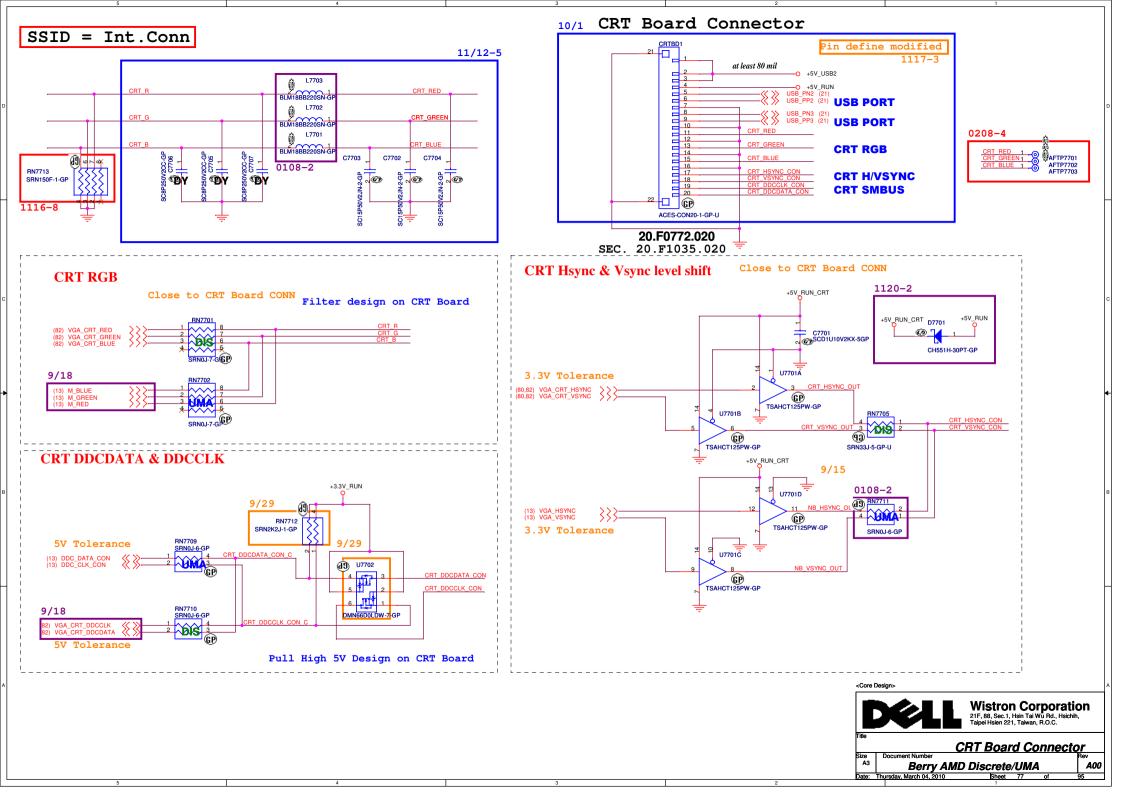






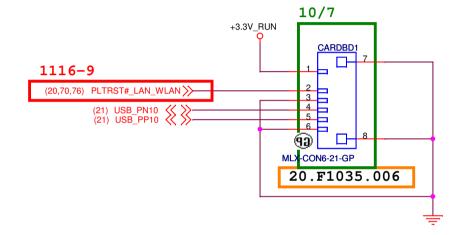






SSID = SDIO

## Card Reader connector



<Core Design>



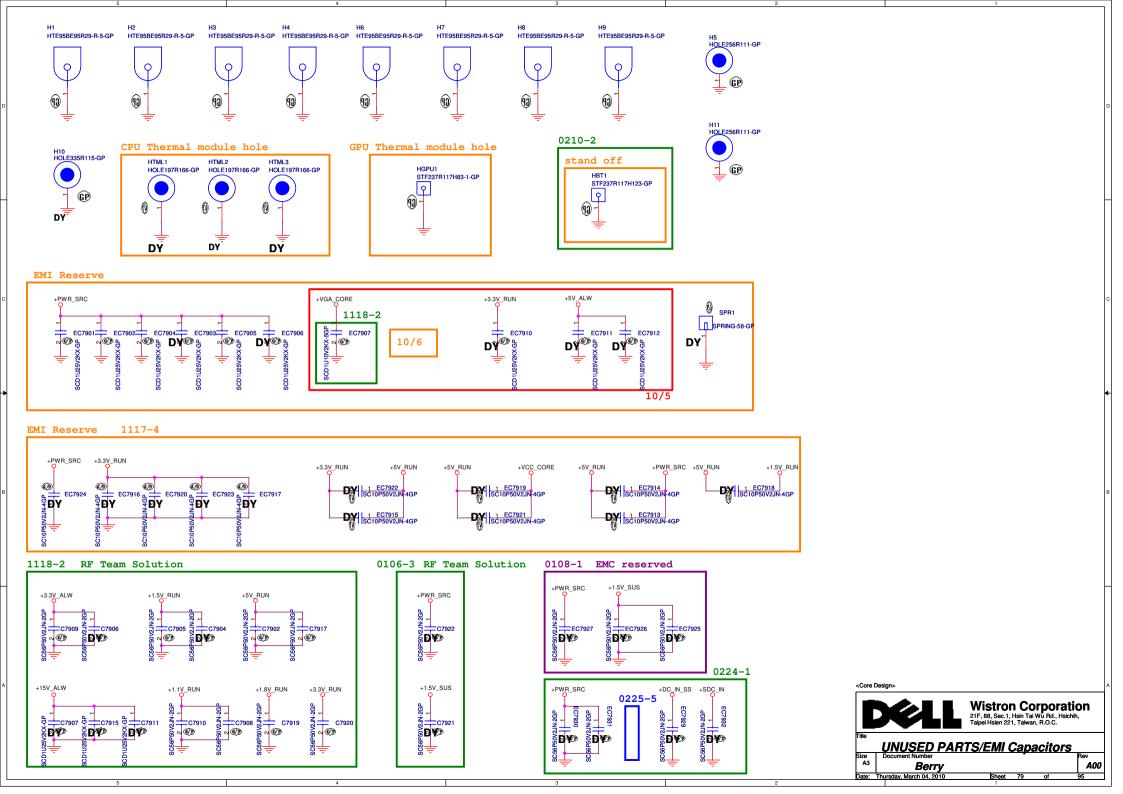
# Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wü Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

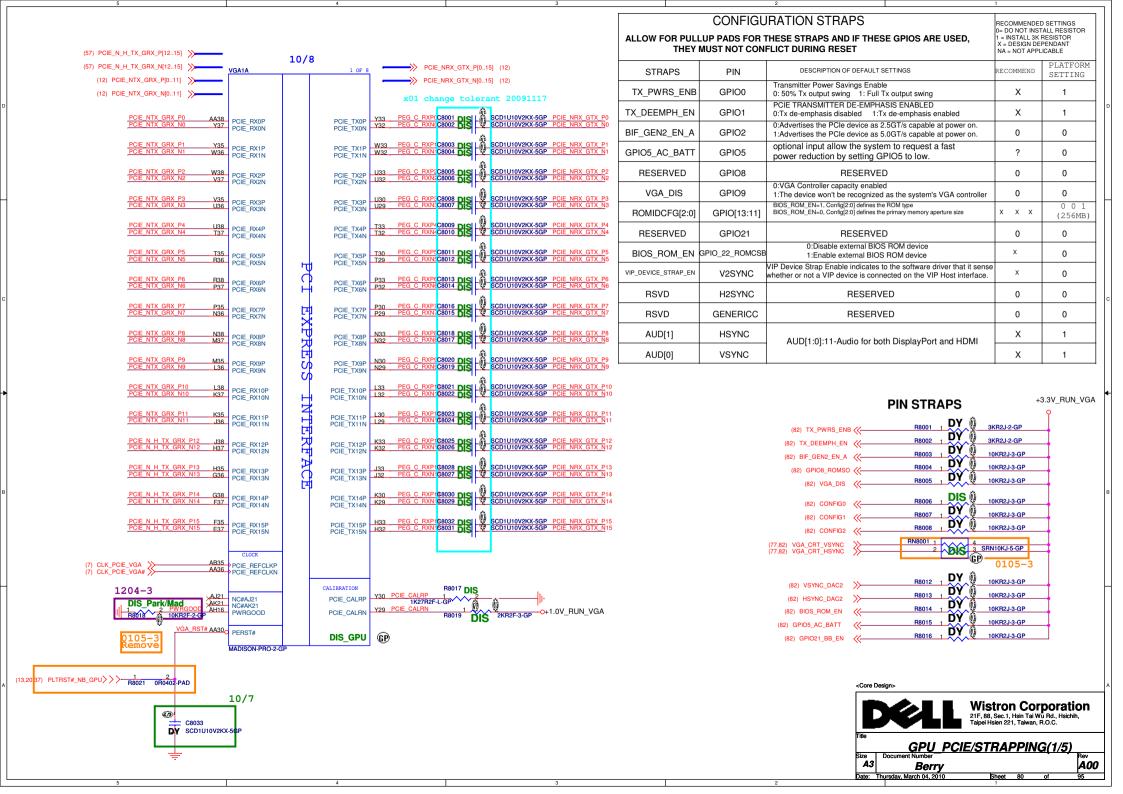
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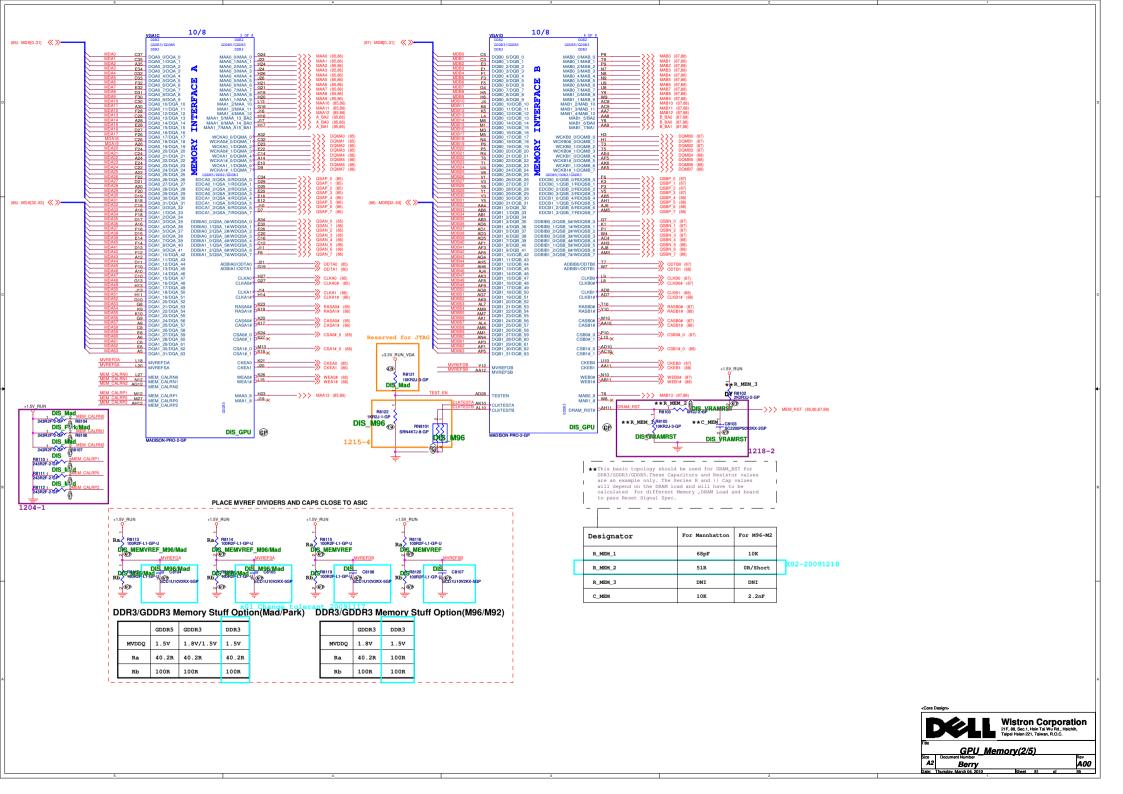
CARD Reader CONN
Document Number

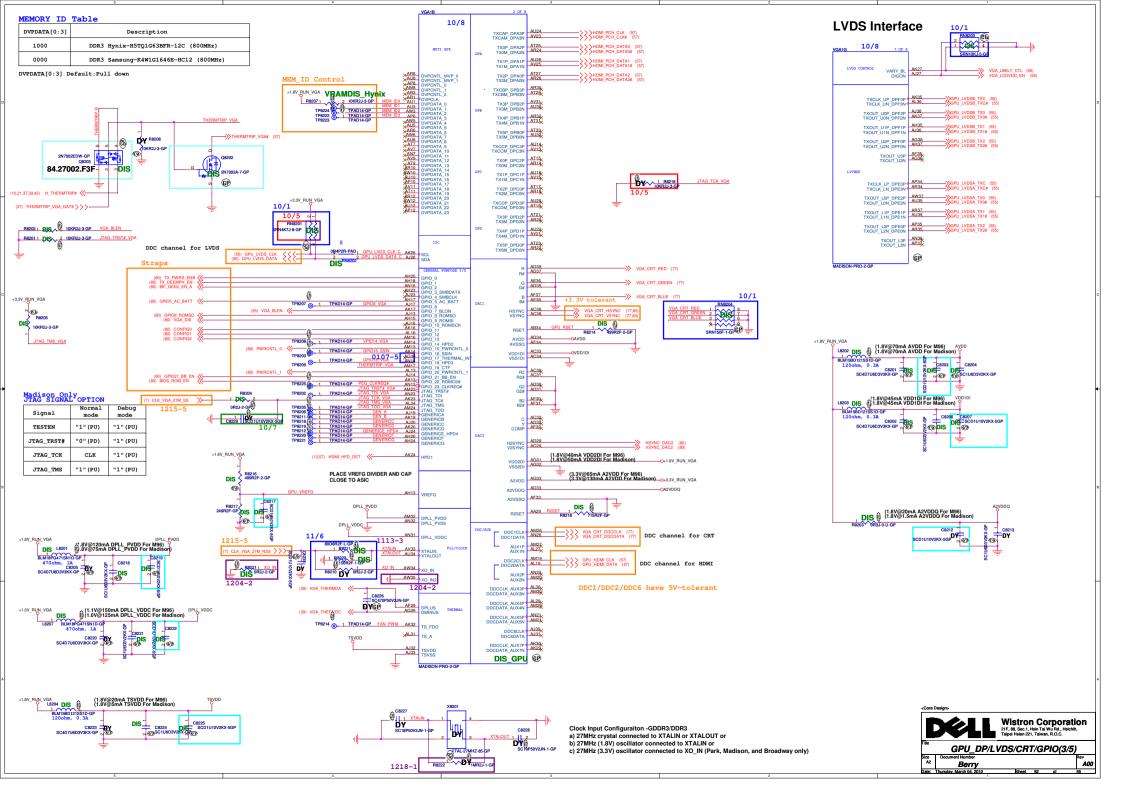
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 Berry AMD Discrete/UMA

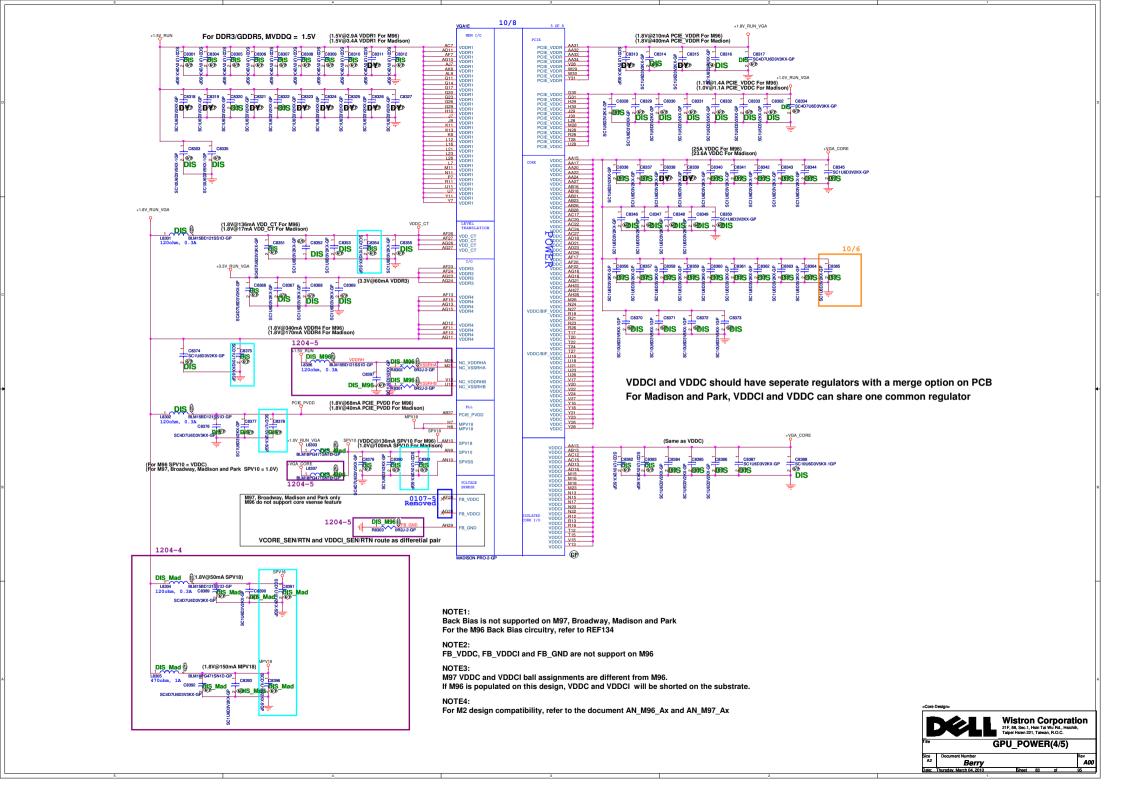
 Date: Thursday, March 04, 2010
 Sheet 78

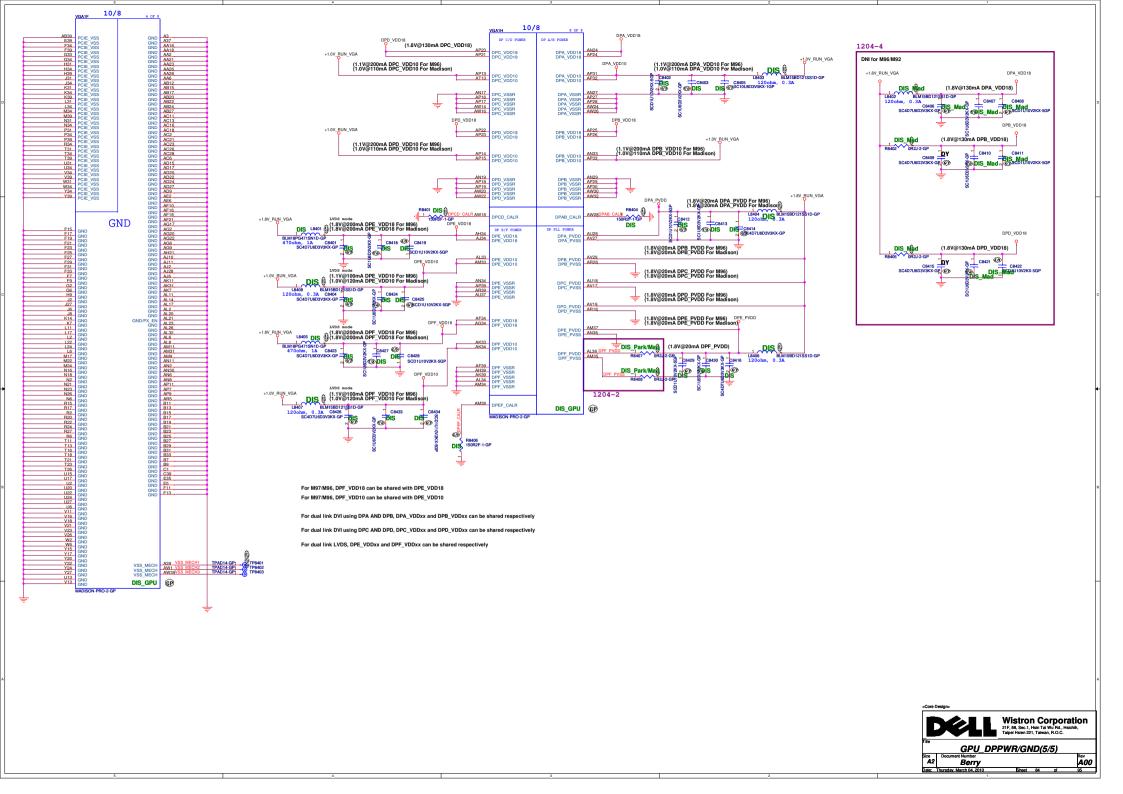


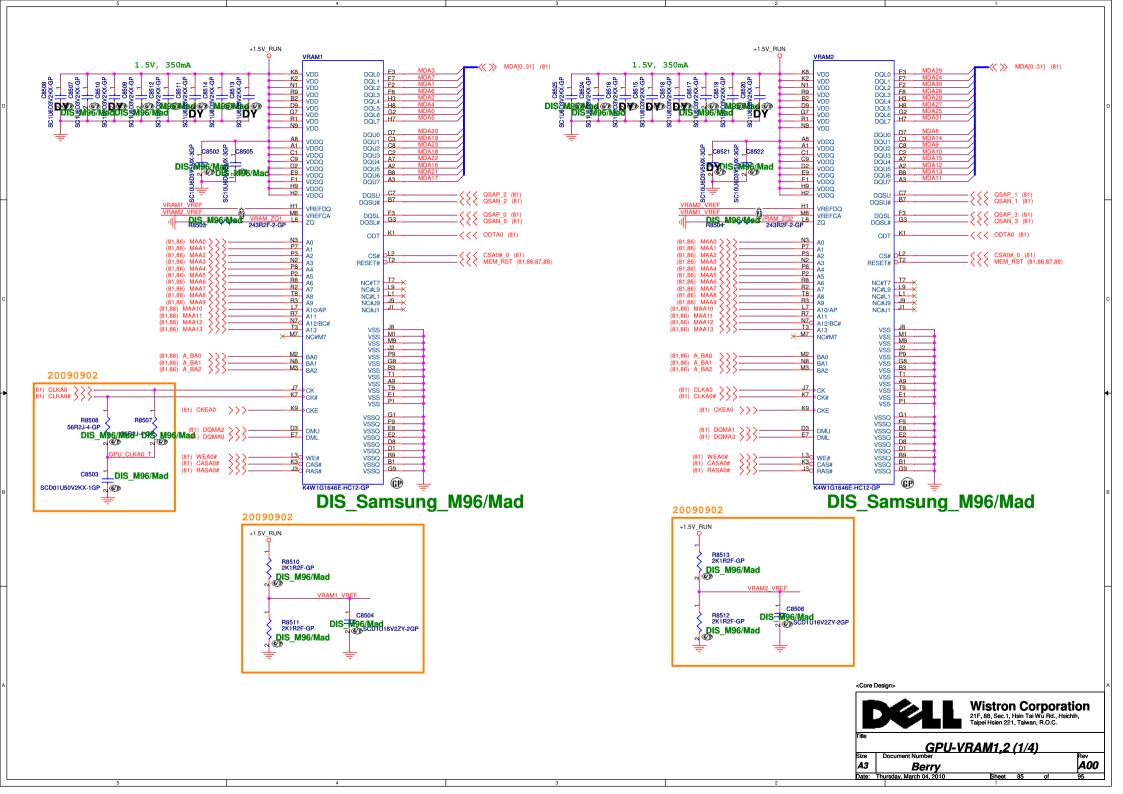


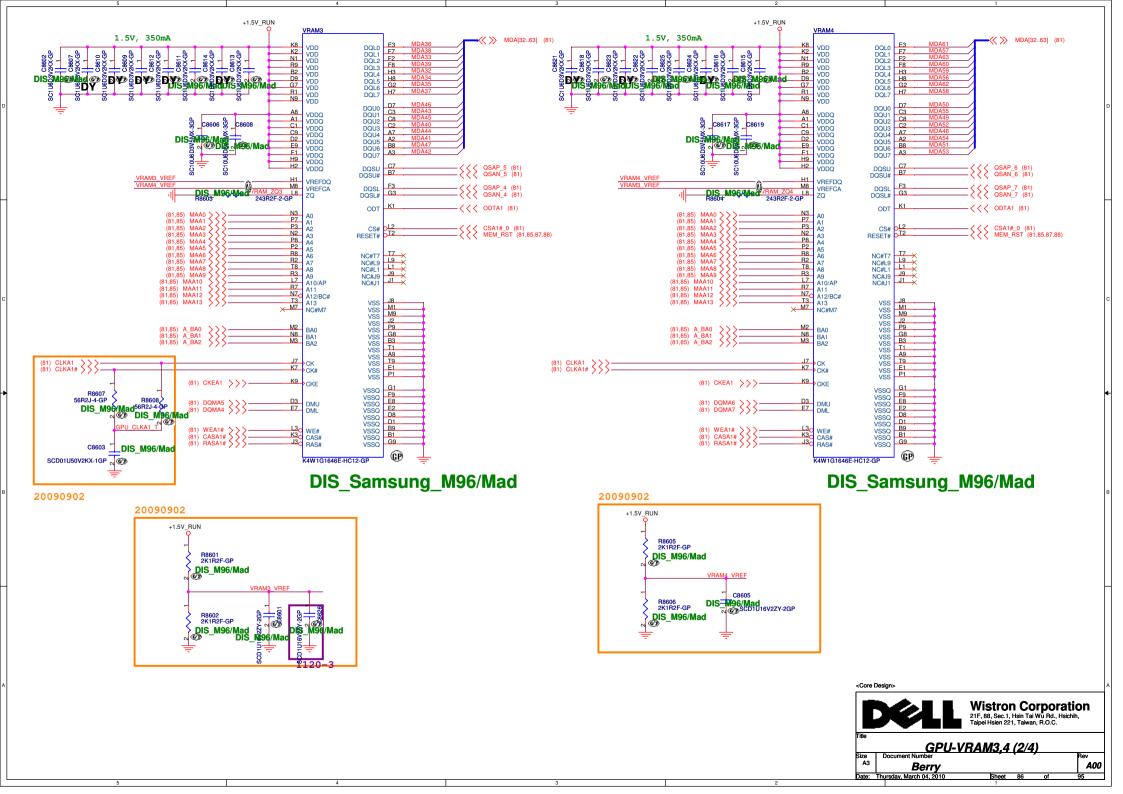


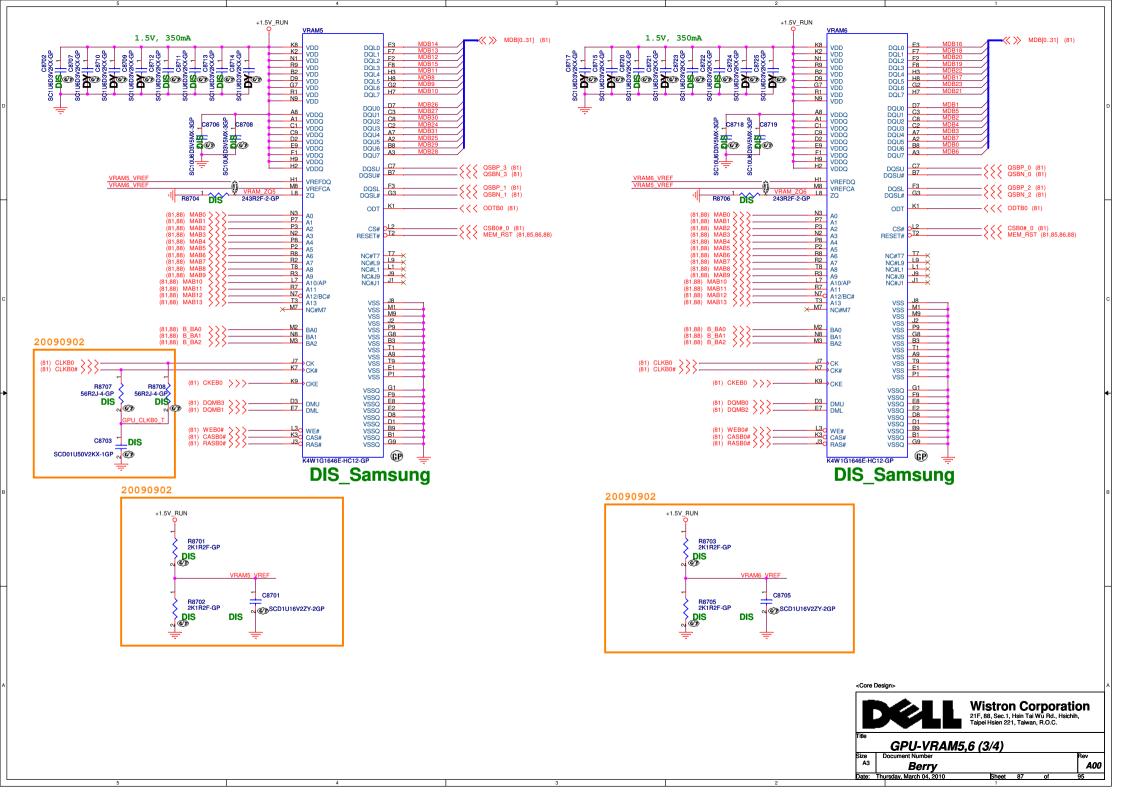


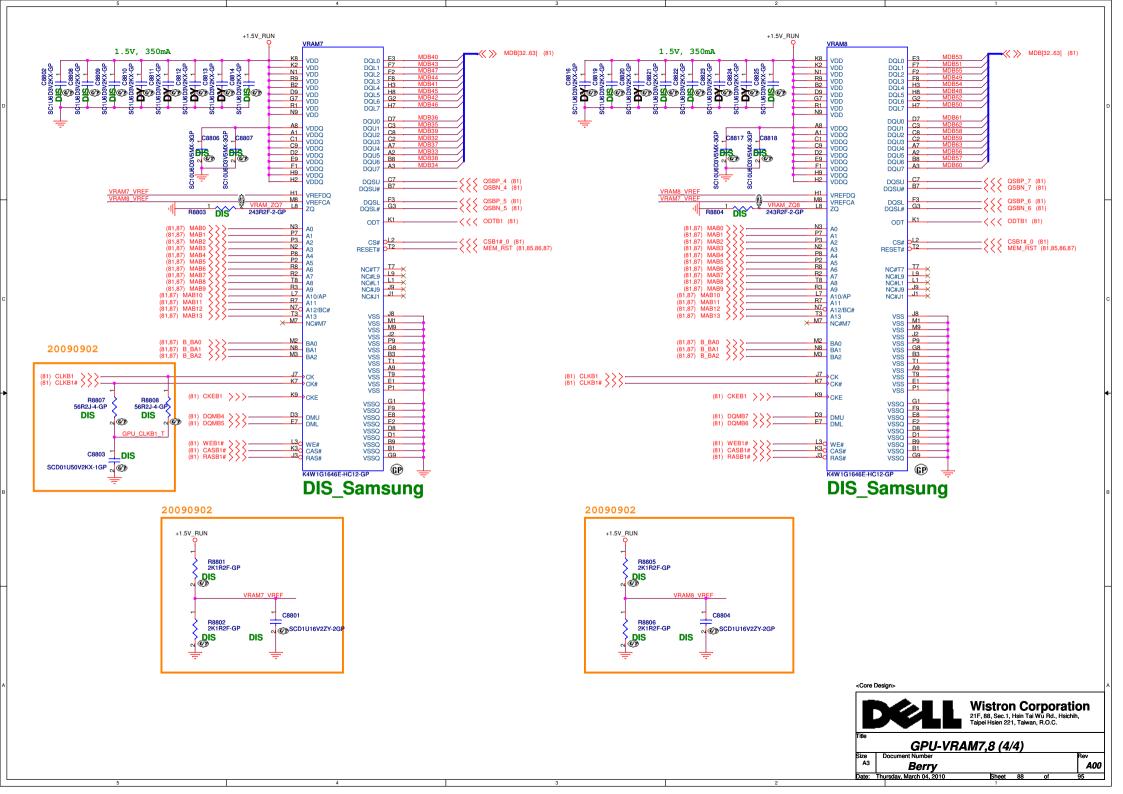












#### RT8208AGQW for +VCC\_GFX\_CORE SSID = Video.PWR.Regulator +PWR SRC +5V ALW Vout=0.75V\*(R1+R2)/R25V, 1.25mA PI 18902 SI7686DP-T1-GP ...910 • **S**IO Design Current = 21.94A 24.14A<OCP< 28.53A SC1U10V2KX-1GP 49KR2F-GP 0114-1 PC8906 PC8906 PC8906 PC8906 PC8906 PC8906 PC8906 PC8906 +VGA CORE 16 TON VDDP BOOT UGATE VDD COIL-D56UH-2-GI PHASE POSS15 (%) CDIU/OVZKA4GP CDIU/OVZKA4GP CDIU/OVZKA4GP (49,51,52,90) RUNPWROK PR8906 2D2R5F-2-GP DΥ DIS DIS GND VOUT PDIS 65MOS DIS 65MOS Change to RT8208B(Pin to Pin) PR8908 PC8910 DIS 0210-1 (37) GFX\_CORE\_EN >> PR8921 1 DX 0R2J-2-GP № 10KR2J-3-GP (21,37,41,42,49,52) PM\_SLP\_S3# >>PR8920 1 +GFX CORE EN R SCD1U10V2KX-4GP PR8909 PR8911 49K9R2F-L-GP PR8912 49K9R2F-L-GP DIS DIS **DIS PowerPlay @** Park Power Table M96 Power Table PWRCNTL\_0 PWRCNTL\_ +VCC\_GFX\_CORE PWRCNTL\_0 PWRCNTL\_ +VCC\_GFX\_CORE 0.9V 0.9V 0.95V 0.95V L Н 1.05V 1.05V 1.12V PR8912=49.9KR PR8912=49.9KR 64.49925.6DL 64.44225.6DL I/P cap: 10U 25V K1206 X5R/ 78.10622.52L Inductor: 0.56uH PCMC104T-R56MN Cyntec DCR:1.6mohm/1.8mohm Isat=25Arms 68.R5610.10D O/P cap: 330U 2.5V EEFSX0D331ER 9mOhm 3Arms Panasonic/ 79.33719.L01 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. H/S: SI7686DP/ POWERPAK-8/11mOhm/14mOhm@4.5Vgs/ 84.07686.037 L/S: SiR460DP/ POWERPAK-8/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037

Vistron Corporation
21F, 88, Sec. 1, Hsin Tai Wü Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

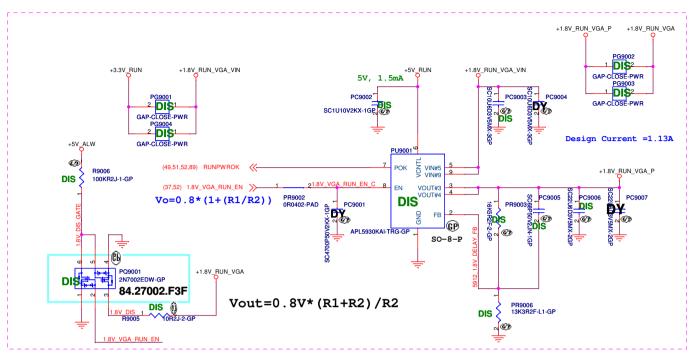
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RT8208B + VCC GFXCORE

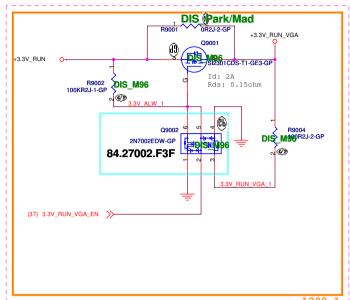
Size
A3

Document Number
Berry AMD Discrete/UMA
Date: Thursday, March 04, 2010
Sheet 89 of 95

### APL5930 for +1.8V\_RUN\_VGA

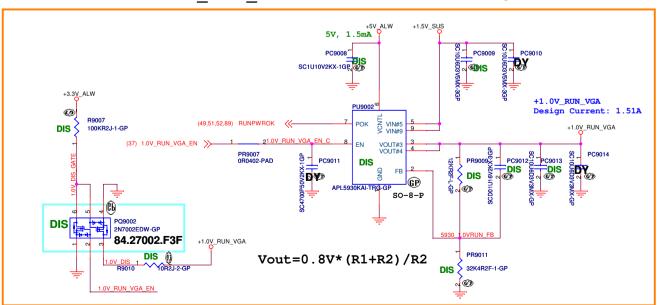


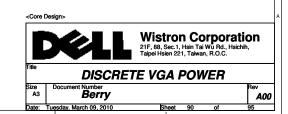
#### +3.3V\_RUN\_VGA

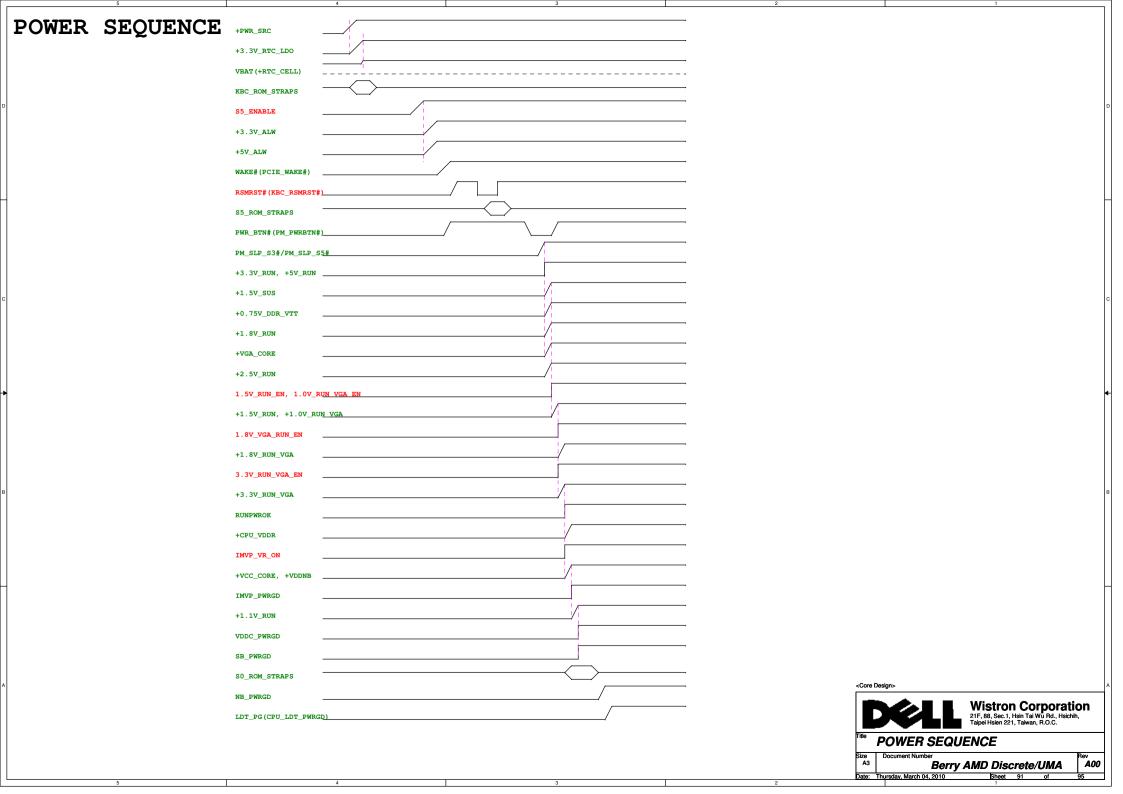


#### APL5930KAI for +1.0V RUN VGA

Will be Change to +1.0V\_RUN\_VGA







Change notes - Page 1 VERSON DATE ITEM PAGE OWNER Modify List Issue Description X01 11/6 10 Add C1002 10uF, C1007, EC1001 0.1uF, C1008 10pF. EE 1 Insure signal quality. EE 13 Change R1314 to 4.7K. Meet CRB. 51 Swap PU5101 pin3, pin4. Correct input voltage level. EE 82 Add R8210 OR. EE Reserve GPU clock input source. 11/9 30 Change C3014 to 2.2uF. Reduce package size. EE EE 2 69 Change C6903 to 0.1uF. Reduce package size. 3 49 Add PR4916 100KR. To prevent leakage in S3 status. EE 11/10 ME 1 18,19 Change DIMM socket Part Number. Request by ME. 2 37 Add R3754 100KR To detect leakage current. EE 11/11 10 Modify R1028 pull-up to +1.5V\_RUN. Solve leakage in S3 status. EE 11/12 EE 20 Change C2011 to 18pF, C2012 to 15pF. Set accurate clock frequency. EE 37 Add C3717 10pF. Stable singal level. 57 Delete RN5711, RN5705. Redundant parts. EE EE 13 Delete R1331, R1332, R1308 Redundant parts. 77 Add Pi-filter. Cure EMI. EMC 11/13 1 20 Change X2001 P/N. Request by Sourcer. Sourcer 2 7 Change R713 to 47R. Fine tune damping. EE 3 82 Add R8211 80.6R, R8220 150R. Set a voltage divider to 1.8V level swing. EE 21 Add R2133 1KR. For UMA VRAM vendor selection. EE 11/16 1 22 Delete RN2203 pin 4, pin 5 connection. Solve S5 leakage. EE Change PR5105 pull-up to +3.3V\_RUN. EE 51 Prevent leakage EE 3 21 Add C2103, C2104 0.1uF. For signal stability. 37 Add C3718 0.1uF. For signal stability. EE 41 Add C4101, C4102 0.1uF. For signal stability. EE EE 49 Add PC4923 0.1uF. For signal stability. 66 Add C6601, C6602 0.1uF. For signal stability. EE 77 Add RN7713 150R. Move impedance matching resistor from CRT/B to M/B. **EMC** EMC 78 Change CARDBD1 pin 2 link to PLTRST#\_LAN\_WAN. Change card reader chip to RTS5159 to solve EMI. 11/17 Add R3014, R3017, R3020 OR to link AGND and GND. EE Issue for pop noise when system boot. Merge 1.1V power solution on main board. 42,48,50 Save components. EE, Power 3 77 Modify CRTBD1 pin define. Relief EMI. EMC 79 Add some decoupled capacitors. Request by EMC. EMC Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. 37 Change R3737 to 33R, stuff C3715 10pF. Request by EMC. EMC Request by EMC. EMC 62,89 Sutff EC6203 22pF, PC8911, PC8907 0.1uF. Change notes 45, 46, 47 Stuff EC4502 0.1uF, PC4605, PC4609, PC4738 0.1uF. Request by EMC. **EMC Berry AMD Discrete/UMA** A00 Change notes - Page 2 VERSON ITEM PAGE OWNER DATE Modify List Issue Description X01 11/17 EE 9 Delete R904. Remove redundant layout trace. EE 11/18 81 Swap R8105, C8103 location. Meet CRB. 2 79 Add some decoupled capacitor. By RF team request. RF 3 49 Change PR4903 to 620KR. Change to common part. Power 11/19 A11 Synchronize with DJ schematic. Schematic standardlize. EE 2 48 Change P/N for PU4802, PU4803, PU4804, PU4805. Rquest by Power team Power All Review all capacitors tolerance. EE 3 Total review for deratig. EE 21 Add RN2105 OR. Reserve to fine tune signal quality. 21 Change RN2101 to 4.7KR. EΑ Fine tuned value for signal. 37 Add RN3705, R3755 OR. To isolate layout trace to DB1 connector. EΑ EΑ 49 Change PC4908 to 2.2uF. Changed by EA report. 11/20 EE 1 54 Modify R5408 connection. To synchronize with DJ. 57 Add D7701. To prevent leakage from RGB monitor. EE Add C8626 0.1uF. EΑ 86 By EA report. 37 Add R3756 10KR, C3720 0.1uF. Synchronize with DJ. EE 37 Delete RN3705, R3755. For more layout space. EE 13 Delete TP1303, TP1304. For more layout space. EE 49 Delete PR4905. For more layout space. EE 89 Add PC8918 0.1uF. Stable signal quality. EE Change PU4601, PU4901 Power components. 11/24 1 46,49 Power Request by Power team. 11/25 46,47,49,8 Change power components. Request by Power team Power EE 11/29 1 10 Change C1008 to 10pF. Fine tuned signal slew rate to meet specification. 2 30 Change R3007 to 2.2KR. EE By FAE suggestion. X02 12/04 81 Set BOM mark R8104, R8106, R8107, R8110, R8111, R8112. Implement co-layout Madison and M96. EE 82,84 Add R8407, R8408 OR. Implement co-layout Madison and M96. EE Add R8016 10KR. Implement co-layout Madison and M96. EE EE 83,84 Set BOM mark. Implement co-layout Madison and M96. EE 5 83 Add L8306, L8307, C8397, R8301, R8302, R8303. Implement co-layout Madison and M96. 12/05 37 Change R3756, C3720 connection. EE Correct soft-start for EC power. 12/08 1 EE 90 Set BOM mark Implement co-layout Madison and M96. 12/15 1 15 Delete RN1501, Add G1501~G1504. Synchronize with DJ and supply sufficient power rail. EE 62 Add R6207 100KR. Insure SPI Write-Protect pin signal level. EE Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. EE 66 Change C6602 net name. Correct signal name. EE 81 Add R8122 1KR, RN8101 4.7KR. Meet M96 schematic check list. Change notes EE 82 Swap CLK\_VGA\_27M\_NSS and CLK\_VGA\_27M\_SS connection. Solve external RGB display tremble issue. A00 **Berry AMD Discrete/UMA** 

hange	notes -	Pag	ge 3				
ERSON	DATE	ITEM	PAGE	Modify List	Issue Description	OWNER	
X02	12/16	1	66	Change R6605 to OR.	Assure power button level set to low.	EE	
		2	37,76	Add net "8103_GPO".	Implement LAN DSM hardware function.	EE	
	12/17	1	37	Add U3703.	To solve SPI WP signal malfunction on EC.	EE	
	12/18	1	82	Add R8222 1MR.	Assure crystal resonant clock stable.	EE	
		2	81	Set VRAM reset circuit.	Follow M96 reset circuit and reseve BOM option.	EE	
	12/25	1	18	Change TC1801 to 330uF, 2V tolerance.	Implement common part for 1.5V power rail.	EE	
		2	46	Change PR4603 to 127KR.	Set 5V current limitation.	Power	
		3	46	Empty PR4618 and stuff PR4619.	Set Ultra-sonic mode to keep +15V_ALW voltage level.	Power	
		4	10	Set RN1006 PU to +1.5V_SUS.	Follow AMD check list and cure +1.5V_RUN leakage.	EE	
		5	62	Change R6206 to 1KR.	According to Safety request, verified OK.	Safety	
		6	51	Change PR5102 1KR, PR5106 8.2KR, PR5107 5.62KR.	Set VDDR low voltage level to 0.9V.	EE	
	12/29	1	10,37	Add Q1005, R1039, R1040.	Request by AMD to set CPU into HTC mode in DOS.	EE	
		2	47	Change PR4720 93.1KR, PR4721 24KR.	Set power OCP value.	Power	
	12/31	1	ALL	Change some resistors as short-pad or resistor array.	Save component counts.	EE	
		2	ALL	Change some capacitors with smaller value or empty.	Save component counts.	EE	
	01/04	1	15	Change R1507,R1508,R1509,R1510,R1511 to bead.	Filter power noise.	EMC	
	01/05	1	7	Combine R707,R721 as RN711.	For more layout space.	EE	
		2	81	Delete TP8101,TP8102.	Remove useless test point for more layout space.	EE	0108
		3	7,80	Delete R716,R8020, combine R8009,R8010 as RN8001.	Redundant part.	EE	
		4	37,39,41	R3747,R4104 short pad, delete R3722,R3904.	Redundant part.	EE	
		5	46	Change PR4620 as short pad.	Redundant part.	EE	
		6	51	Change PQ5101 with ESD protector.	Change to common part.	Power	
		7	54	Empty R5405 and Stuff R5408.	Avoid LCD white panel.	EE	
		8	62	Change R6205 to OR.	Already have one 1KR ahead.	EE	
	01/06	1	50	Add PR5004 10KR and empty PR5002.	Avoid +1.1V_ALW leakage in South Bridge.	EE	
		2	13	Change R1342 to size 0603.	Synchronous schematic w/DJ.	EE	
		3	79	Add R7921 and R7922.	Reserved RF team solution.	RF	
	01/07	1	7	Add RN712,C722,C723	Reserve for SMBus signal quality tuning.	EE	
		2	60	Change EC6007, EC6008 to 0.01uF.	According FAE Request.	IDT FAE	
		3	39	Add Q3904.	According thermal team request.	Thermal	
		4	21,18	Change location RN2105 to RN1801, add C1823,C1824.	For SMBus signal quality fine tune.	EE	
		5	39,82,83	Remove C3912, TP8301, TP8302, TP8213.	Remove dummy part for more layout space.	EE <0	ore Design>
		6	76	Reserve C7601, C7602.	Fine tune USB signal quality.	EE	Wistron Corporatio 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
	01/08	1	79	Reserve EC7925,EC7926,EC7927.	Reserve by EMC team.	EMC Tit	Taipei Hsien 221, Taiwan, R.O.C.
		2	77	Change RN7711 to OR, L7701,L7702,L7703 to bead 22R.	According EMC measurement result.	EMC Siz	Change notes  Berry AMD Discrete/IMA

Change notes - Page 4 VERSON DATE PAGE Modify List Issue Description OWNER X02 01/08 18,19 Add C1825, C1922 EE 3 Reduce V\_REF ripple by EA team result. EE 37 Reserve C3721, C3722. Prevent signal cross talk. 5 ALL Change capacitors value and add C3723. EE Ensure signal quality. 01/11 ME 1 68 Change KB1 P/N. According ME request. 2 EE 66 Change R6601, R6602, R6604, R6606 to 1KR, R6603 to 470R. Decrease LED brightness. 01/12 1 37 Add C3724, R3757. To set accurate current detection in EC. EE 2 EE 10 Add R1041 OR. Add OR for level shift off. 01/13 1 21,37 Add C3725, C2105. Reserve for singal quality. EE 01/14 1 Power Modify power team componets. Request by Power Team. Power 2 7 Change RN712 to 22R. EE Fine tuned damping resistor value. A00 02/08 1 66 Reserve R6609, R6610 1KR. Add for future LED brightness balance. EE 2 68 Add keyboard back light circuit, remove R5403. Add for keyboard with back light module. EE 3 69 Change HALLSW1 footprint for co-layout. Change for co-layout different kind of HALLSW1. EE EE 77 Add AFTP7701, AFTP7702, AFTP7703. Add AFTP test point for factory test. 02/10 1 Power Update Obsolete parts. Update obsolete parts due to policy. Power 2 79 Change HBT1 part number to match ME EMN file. ME Change HBT1 part number. 47 Add PTC4710. EE Add to solve board accoustic issue. 02/22 1 54 Remove co-layout pad. EE As factory requst. 0308-1 2 42 Add C4217, C4401, C4402. Ensure signal quality. EE 48 Delete Power Gap. Request by Power Team. Power 02/23 EE 1 ALL Change to short pad. Change most of 0-ohm resistors to short pad. 02/24 7,68,79 Reserve C724, C725, C6806, C6807, EC7928-EC7932. EMC As EMC team request. 1 Add TP1309. 02/25 13 As factory requset to add. Factory 7,68 Rename EMC capacitor to EC704, EC705, EC6801, EC6802. Meet schematic standardization. EE 49,89 Change PR4913 to 3.9R, PR8905 to 6.98KR. PR4913 for snubber, PR8905 for OCP. Power 4 21 Change R2133 to OR. Set GPIO input level from 0.5V to 0V. EE 5 79 Remove EC7928. Layout space limitation. EE 02/26 1 39,42 Empty R3906 and Change R4202 from OR to 1KR. It is for solving T8 shutdown issue. EE ME 1 60 03/03 Change SPK1 part number. Request by ME. 20,24,37 EE 03/05 1 Empty R2029, R2404, R3751. Saving unused components. 03/08 48 Stuff PU4803 and empty PU4804. Place the H/S and L/S MOS at the same surface. Power Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C. Rev A00